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Design and Implementation of a Digital Standard Cell Library for 28 nm Technology

Master's thesis in Electronic System Design

Supervisor: Trond Ytterdal, Snorre Aunet

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ABSTRACT

A digital standard cell library has been designed and implemented for a 28 nm technology. The library has been designed and optimized for a supply voltage of 300 mV, to be compatible with a standard design flow. Each cell has been characterized with extracted parasitic components. Combinatorial logic gates, including compound logic gates, and sequential cells were implemented with SLVT (Super Low VT) transistors. The library has been used to synthesize a functional RISC-V architecture (PicoRV32). The motivation was to verify the functionality of the standard cell library and obtain quantitative results of the performance of the library. The minimum energy point (at room temperature in the TT-corner) for the CPU was found to be with a supply voltage of 500 mV and a frequency of 20 MHz. By increasing the supply voltage to 600 mV, the CPU supports a 50 MHz clock. The highest simulated frequency was 250 MHz at 1 V

PREFACE

This report is written as an assignment for TFE4930, the master thesis in the Electronic Systems Design and Innovation program at NTNU Trondheim. The goal of the project is to design and characterize a digital standard cell library in a 28 nm technology, with a supply voltage of 300 mV. All work presented in this report is a continuation of a previous project (presented in [1]) which is assumed to be known to the reader. In cases where it is deemed necessary, some information may be revisited for clarification purposes. Despite the similarity of the content, the implementation of some of the cells has been changed.

I want to acknowledge and thank my supervisors:

Prof. Trond Ytterdal for always being available for questions, and being an astounding resource for insight to the tools related to design of CMOS circuits.

Prof. Snorre Aunet for the uttermost insight in digital design, and providing vital guidance on solutions and results that are beneficial to pursue.

I would also like to thank Fredrik Feyling. By allowing me to contribute on developing PADE¹, I had the possibility to develop testbenches in a much simpler manner than before. PADE was used to simulate some simple synthesized designs (presented in Section IV-C), and without it I would require much more time on setting everything up.

Asbjørn Djupdal has helped me to set up the top module for the PicoRV32 CPU, as presented in Section IV-D, and the testbench of the CPU, presented in IV-D2. I would not have the time to implement and simulate on a circuit of this size without his help, for which I am very appreciative.

¹PADE is available on [github](#).

The version used in the implementation is the following commit: 37c8cfedbf4f09642ae71d8d4ca8a19c13f1f9ce. The repository is not open to the public at the time of publication, as confidentiality of some information must be protected. This is prone to change.

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GLOSSARY

FF	Fast-Fast, where both PMOS and NMOS are in the fast process corner
library characterization	The process of characterizing the behavior of each cell in a standard cell library
main netlist	The netlist synthesized for 300 mV and 3.2 MHz, with parasitic components extracted
PADE	Python aided Analog Design Environment
PicoRV32	An open-source, size-optimized RISC-V CPU implementation
poly	Short name for polysilicon, which is made of small crystalline regions of silicon
PVT	Process-Voltage-Temperature variations. Inaccuracies across variations due to process corners, voltage and/or temperature
RISC-V	Open source standard instruction set architecture based on Reduced Instruction Set Computer (RISC) principles

SS	Slow-Slow, where both PMOS and NMOS are in the slow process corner
standard cell library	A library containing pre-designed and pre-verified technology-dependent digital cells, available when synthesizing a technology-independent RTL-design
synthesis	Gate level synthesis, the process of mapping technology-independent RTL description to technology-dependant CMOS logic using a library of pre-characterized standard cells
SystemVerilog	A Hardware Descriptive Language (HDL) language (and Hardware Verification Language), based on Verilog and some extensions
TT	Typical-Typical, where both PMOS and NMOS are in the typical process corner
Verilog	A Hardware Descriptive Language (HDL) used to model digital electronic systems

ACRONYMS

AOI	And-Or-Invert
ASIC	Application-Specific Integrated Circuit
CMOS	Complementary Metal-Oxide Semiconductor
CPU	Central Processing Unit
DRC	Design Rule Check
HDL	Hardware Descriptive Language
lef	Library Exchange Format
LVS	Layout Versus Schematic
NMOS	Negative-channel Metal-Oxide Semiconductor
OAI	Or-And-Invert
P&R	Place And Route
PDK	Process Design Kit
PMOS	Positive-channel Metal-Oxide Semiconductor
POS	Product-Of-Sums
RISC	Reduced Instruction Set Computer
RTL	Register-Transfer-Level
SLVT	Super Low VT
SOP	Sum-Of-Products
VT	Threshold voltage (V_t)

I. INTRODUCTION

The implementation of modern digital designs requires an increasingly amount of complexity, and requirements for computer performance still increases. Although full-custom ASIC design allows more control of the optimization, there are major drawbacks regarding design-time and requirements in skill for designers. A major factor in the rapid growth of integrated circuits is the use of standard cell libraries [2]. By using pre-designed and pre-verified standard cells to perform various system functions, time can be spent on working on the Register-Transfer-Level (RTL). A tool may then use the technology-independent RTL description and map it to technology-dependent CMOS logic using a library of pre-characterized standard cells. This process is called gate-level synthesis.

In recent years, as the complexity increases and the size of transistors decreases, there has been an increased focus on the energy efficiency of integrated circuits. Patrick P. Gelsinger predicted in 2001 that the development of integrated circuits meant that the power consumption would become higher than what is practically possible [3]. His predictions imply that the power density would reach the power density of a nuclear reactor by 2005, a rocket nozzle by 2010, and the surface of the sun in 2015. As this is practically impossible, power consumption needs to be addressed. Often this can be achieved by decreasing the supply voltage, decreasing the clock frequency, or by various implementations to reduce power consumption in Hardware Descriptive Language (HDL). Decreasing the supply voltage to sub-threshold or near-threshold values can often be necessary to realize self-powered systems.

This report will present an implementation of a standard cell library, which consists of digital cells that perform a sequential or combinatorial function, and can then be used by a synthesis tool to generate a digital design. An implementation of a RISC-V CPU in HDL has been used to test the library. As the main focus is the library itself, there have not been any efforts made to optimize or improve the RTL design. The chosen processor is a PicoRV32, which is a size-optimized RISC-V CPU, presented in Section IV-D.

The technology is a commercially available 28 nm CMOS technology. All transistors were designed with the minimum length allowed by the Process Design Kit (PDK) and width of 200 nm [1]. The size of the transistors were equal in every cell in the standard cell library to simplify the design process. SLVT transistors were used to maximize the speed.

Because of the importance of energy efficiency, the library has been designed to use a supply voltage of 300 mV, which is a near-threshold voltage. Some analysis has been done to see how varying the supply voltage affects the overall speed and energy-efficiency of the CPU.

There were no requirements for the frequency, as supported frequency can vary based on which RTL design is implemented. However, the following were desired to find to characterize the potential of the library:

- The maximum possible frequency for operation with a supply voltage of 300 mV.
- The minimum possible supply voltage for operation with a frequency of 50 MHz, for applications that require higher speed.
- The minimum energy point to perform a set of instructions, with a pair of frequencies and supply voltages.

The standard cell library has been implemented with various combinatorial and sequential cells. Both two-input logic gates and compound logic gates of And-Or-Invert (AOI)- and Or-And-Invert (OAI)-type are present in the library. A D-type flip-flop has been implemented to allow clocked digital designs to be synthesized.

Additionally, a D-type latch and a tri-state buffer have been implemented. Although not required or utilized in any synthesized designs presented in this report, some digital designs may require these cells for the RTL-code to be synthesizable.

The work presented in this report is based on previous work presented in [1].

There were some problems with the previous implementation that have since been resolved. The biggest problem was due to compatibility issues in Place And Route (P&R) related to the Library Exchange Format

(lef) file. The routing grid was previously chosen to be suitable for the design. However, to resolve issues that surfaced under P&R, the routing grid has been changed to comply with the restrictions of the PDK.

The library was functional for the synthesized designs. Generated reports after library characterization and results of simulations provided correct functionality. Synthesized designs passed Design Rule Check (DRC) and Layout Versus Schematic (LVS) checks, which implies that the standard cells are compatible with the standard design flow.

The PicoRV32 CPU was verified to function with a clock frequency of 2.1 MHz at 300 mV. When the supply voltage was increased to 600 mV, the CPU supported a clock frequency of 50 MHz. The maximum supported frequency tested by simulation was 250 MHz, with a supply voltage of 1 V.

The lowest amount of energy consumed for executing the testbench was found to be approximately 32.3 pJ at 500 mV and 20 MHz.

A. *Outline*

The report contains the following chapters, and is meant to be read in the following way:

- **Background** (Section II) - Background theory, written in a generalized manner, necessary to be familiar with to better understand the implementation and results
- **Methodology** (Section III) - The tools and methods used in the implementation, and how results were obtained
- **Implementation** (Section IV) - How the standard cell library and the synthesized designs were implemented
- **Results** (Section V) - Results obtained by library characterization, synthesis, P&R and simulation of synthesized design
- **Discussion** (Section VI) - The results are discussed and evaluated
- **Conclusion** (Section VII) - The conclusion of the discussion

II. BACKGROUND

This section will describe some theory that is necessary to be familiar with to understand the implementation of the standard cell library. The design flow used for the implementation is presented in Section II-A. Tools that are used in the design flow are presented in Section III-A.

A. Design flow

An overview of the design flow is given in Fig. 1.

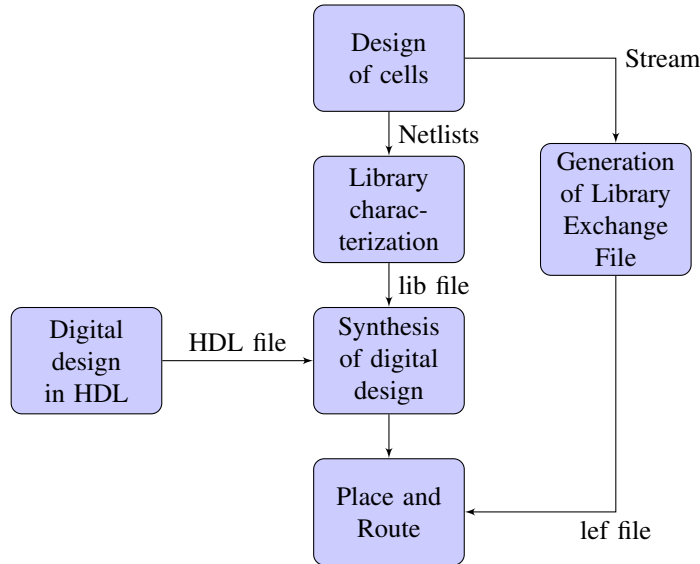


Fig. 1: Overview of standard cell library design [1, Fig. 4]

The initial step is designing the cells themselves. This step is explained in further detail in Section II-A1.

A library characterization tool simulates each cell to characterize the power consumption and timing information. The tool imports the netlists (containing parasitic capacitances) for each cell and generates a *lib* file containing all information about the cells. Information about area may be included (optional) to allow the synthesis tool to optimize for area. As the netlists do not contain geometrical information, this is not included automatically. Included in the *lib* file is also the logic functionality of the cells.

The synthesis tool is responsible for reading an HDL file and generating a netlist containing the cells that are available in the library. As the *lib* file contains the truth tables, power consumption, and timing for each cell, the synthesis tool has the necessary information to synthesize with correct functionality and meet the timing requirements (if possible). The netlist generated by the synthesis tool can be used by the Place And Route (P&R) tool to create the floorplan with the cells placed and connected as stated in the netlist.

For the P&R tool to be able to place the cells and route between them without creating shorts, it needs to be provided information about the layout of the cells. However, not all the information from the layout is needed. This can be done by using a Library Exchange Format (*lef*) file. The file contains the following information [4]:

- Technology: layer, design rules, via definitions, metal capacitance
- Site: Site extension
- Macros: cell descriptions, cell dimensions, layout of pins and blockages, capacitances

An important part of the design flow is to include the *lef* file for the given technology in use. By using a tool, one can generate another *lef* file containing the *macros*. These macros contain the necessary information about the cells, which allows the P&R tool to use the cells without any information about the internal netlist. Not shown in Fig. 1, is that the *lef* files may be included in the synthesis tool.

Including this file implies that information about the area is known, which allows the tool to minimize the area and produce more accurate reports. Additionally, the lib file can be included in the P&R tool to analyze necessary setup and hold times in the design.

When the P&R tool has finished placing all cells and routing the design, the layout and Verilog netlist can be exported for further use. The layout is streamed out to a binary *.gds* file, which is the file used to fabricate the integrated circuit. The Verilog netlist contains all the digital cells (from the standard cell library) that are placed and routed by the P&R tool. It is also necessary to ensure that the design passes the DRC and LVS checks. They will be explained in further detail in Section II-A1.

Additional steps for finalizing the design for tape-out are regarded as out of the scope of this report. However, the exported layout after P&R can be used for further simulation with parasitic components extracted (extraction is explained in Section II-A1).

1) *Cell design*: Fig. 2 shows an overview of the design flow for a single digital cell. The initial stage is to design the cell on the schematic level. The cell can then be verified and analyzed in simulation and redesigned if necessary.

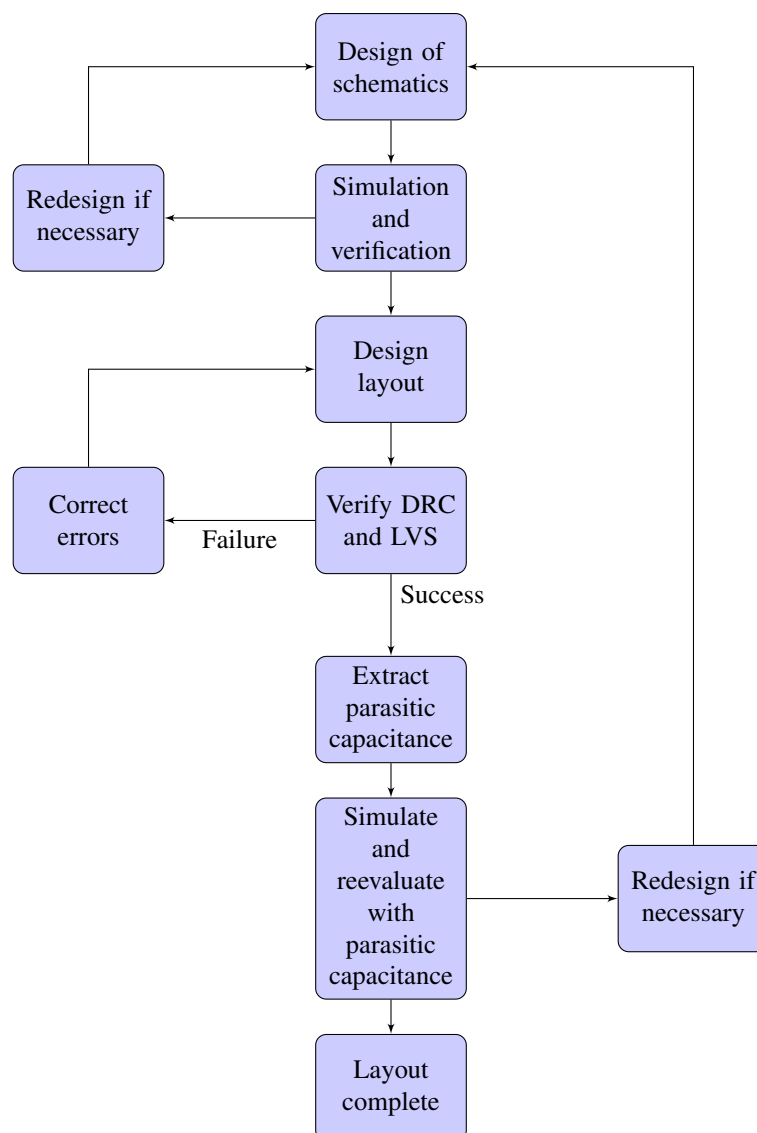


Fig. 2: Design flow of digital cells [1, Fig. 5]

When the cell works as intended with satisfying results, the next step is to design the layout. The layout is related to the physical design and contains the geometrical information of the layers that are intended to be in the integrated circuit. When drawing the layout, the design must obey the *design rules* that are given

by the Process Design Kit (PDK). To ensure that these are followed, the layout must pass the Design Rule Check (DRC) to achieve an overall high yield and reliability [5]. In addition to DRC, the design must pass Layout Versus Schematic (LVS). This tool verifies that the layout is the same representation of the circuit as the schematic (same number of transistors, nets connected correctly, etc.).

When both DRC and LVS pass, there is one more step that is necessary to complete the layout step. Transistors contain *parasitic capacitors* [6], which impacts the behavior of the cells. In addition, adding metal wires in the cell adds parasitic capacitance. The parasitic components can be extracted by using a tool that generates a netlist containing the parasitic components in addition to the circuit. By including the extracted components, the simulation models become more accurate when accounting for these parasitic components.

The final step is to reevaluate the behavior of the cell. If the simulation results are not satisfactory after parasitic components are accounted for, the cell must be redesigned.

B. Digital cells and logic gates

The Boolean functionality of the most common logic gates, flip-flops, and latches is assumed to be known by the reader. The following cells must be known, and are not explained in detail in this report:

- Inverters
- Tri-state buffers
- NAND, NOR, AND and OR
- XOR and XNOR
- D type flip-flops
- D type latches
- Multiplexers

Additionally, a basic understanding of CMOS transistors and how PMOS and NMOS constructs the pull-up and pull-down circuitry of a logic cell is assumed.

1) Compound gates: One can achieve any combinatorial function by only using NAND-gates and inverters. By connecting one input of a NAND-gate to VDD, one can even use only NAND-gates, assuming the synthesis tool supports it. However, this has multiple drawbacks. By creating more logic gates (f. ex. NOR, XOR, and XNOR), one can reduce the number of total required transistors. This increases overall speed and reduces both area and power consumption of the synthesized result.

Expanding on this, it is possible to create cells that perform more complex logic functions in a single stage of logic by using a combination of parallel and serial connections of PMOS and NMOS transistors [6]. Examples of this are AOI (And-Or-Invert) and OAI (Or-And-Invert) cells. How they can be derived is described in the following paragraphs. Note that the approach can be used to analyze simple NAND- and NOR-gates with two or more inputs. For clarity, a short description of them is provided.

a) NAND gates: The output of a NAND-gate is dependant on every input being high for the output to be low. This implies that when only one (or none) of the inputs is low, the output must be high. The PMOS circuitry is responsible for pulling the output to the value of the VDD rail (PMOS circuitry may be referred to as the pull-up network). As the NAND-gate produces a high output even when a single input is low, the PMOS transistors must be connected in parallel. When the gate voltage is low on one of the inputs, the transistors connects ² the output to VDD. Similarly, for the NMOS circuitry, a single low input must disconnect ³ the output from VSS. Only when all inputs are high must the output be connected to VSS. This implies that the NMOS transistors are connected in series.

b) NOR gates: The output of a NOR gate requires both inputs to be low for the output to be high. Following the same approach as for the NAND gate, one can see that both PMOS transistors must conduct for the output to be driven high. This implies that the PMOS transistors must be connected in series. The NMOS transistors should connect the output to VSS when at least one transistor has a high gate voltage, which implies that the NMOS transistors are connected in parallel.

²By providing a low-impedance path

³By having a high impedance path

c) *AOI cells*: AOI cells perform Sum-Of-Products (SOP) expressions. This means that the output depends on the sum of two or more products. An example is shown in eq. (1). Note that the output is inverted.

$$Y = \overline{AB + CD} \quad (1)$$

The equation in the example can naturally be made by using two AND-gates (connected to A and B, and C and D respectively), which feeds a two-input NOR-gate. However, this can be simplified.

If we first regard the pull-down network consisting NMOS transistors, one can see that for the (inverted) output to be pulled low, either AB or CD must be true. For each product, both inputs must be high to conduct between output and VSS. This implies that the NMOS transistors must be connected in series for the given product. The output only depends on one of the products to be true, which implies conducting serial connection. From this follows that each serial connection is connected in parallel.

The pull-up network consists of PMOS transistors, which conducts when the gate voltage is low. Pulling the output voltage high requires both products to be false (given the output is inverted). This implies that A or B must be low, for the product to be evaluated as false. The same applies to C and D . As both products must be evaluated to false for the output to be driven high, the transistors for AB and CD must be connected in series, while the transistors for each product are in parallel.

The resulting schematic and symbol that evaluates the function in eq. (1) is given in Fig. 3. The name for this specific cell is AOI22.

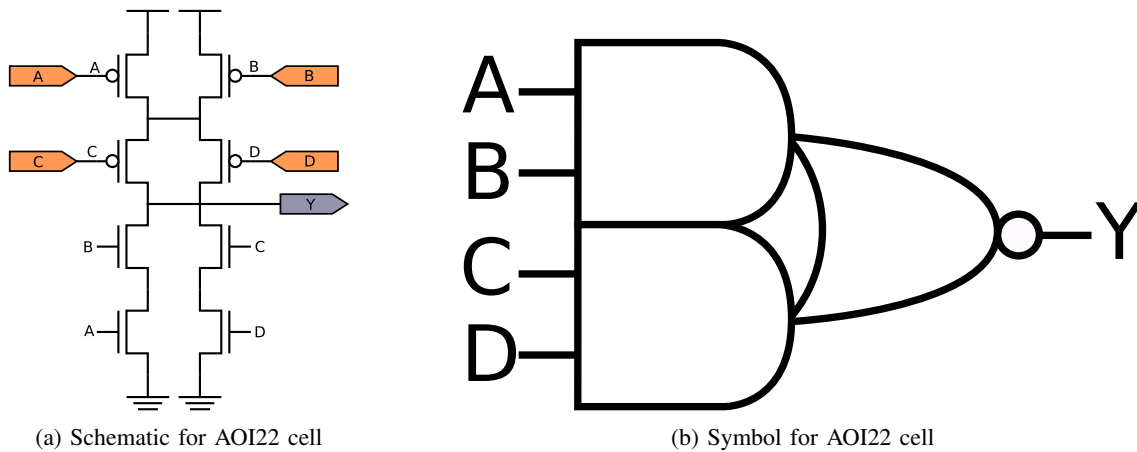


Fig. 3: AOI22, an example of logic gate of type And-Or-Invert

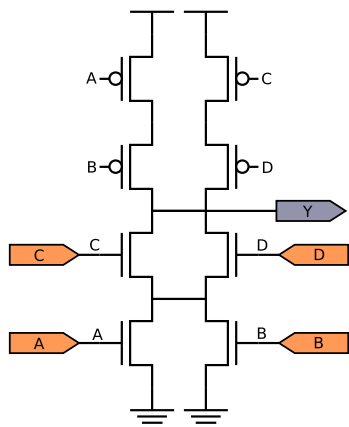
Using the same approach for different Boolean functions, one can create schematics for logic gates to evaluate other Boolean functions, with more or fewer inputs.

d) *OAI cells*: OAI cells are similar to AOI cells. However, OAI cells are used to calculate a Product-Of-Sums (POS) expression instead of a SOP expression. Fig. 4 shows the schematic and symbol for the logic gate that represents the equation shown in eq. (2).

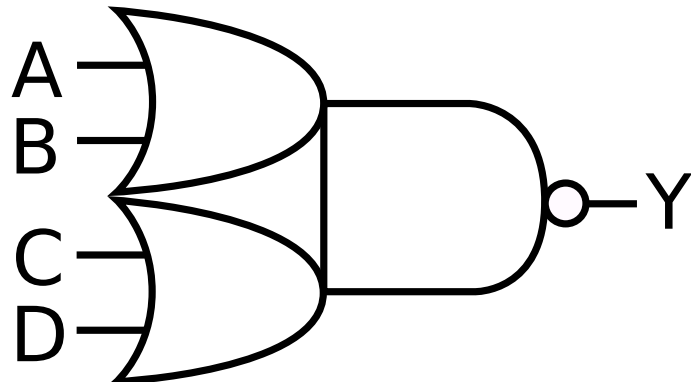
$$Y = \overline{(A + B)(C + D)} \quad (2)$$

Using the same approach as for the AOI cell, one can create the schematic by using a combination of parallel and serial connections of the transistors. However, the first step is to identify each sum instead of each product. As inputs A and B are ORed together, the NMOS transistors must be connected in parallel and PMOS transistors in series. As the sums are ANDed together, the NMOS circuitry for each sum must be connected in series, and the PMOS circuitry must be connected in parallel. From this follows that the OAI cells can easily be created by switching the parallel and serial connections from the complementary AOI cells.

An important thing to notice with AOI- and OAI-cells is that for each input, one NMOS and one PMOS transistors are required. This implies that the total number of transistors is twice the amount of inputs.



(a) Schematic for OAI22 cell



(b) Symbol for OAI22 cell

Fig. 4: OAI22, an example of logic gate of type Or-And-Invert

III. METHODOLOGY

A. Tools

Table I presents the tools and descriptions for what they were used.

TABLE I: Tools used in the design flow of the standard cell library

Tool	version	Description
Virtuoso	6.1.7-64b	Design of schematic and layout.
calibre	v2020.3_24.16	Design Rule Check (DRC) and Layout Versus Schematic (LVS)
Quantus Extraction	20.1.1-s233	Extraction of parasitic capacitance
Liberate	19.21.472	Library characterization of cells (lib-file)
Genus	19.15.000	Gate level synthesis
Abstract	6.1.7-64b	Abstract view generation, to generate Library Exchange Format (lef)
Innovus	v19.16-s053_1	Place And Route (P&R)
irun	15.20-s084	Simulation of processor with Verilog testbench

1) *Design of standard cells*: The Schematic Suite XL and Layout Suite XL in Virtuoso were used to design the schematic and layout of cells. Some simulations were done with ADE Explorer to verify the functionality of the cells.

2) *Library characterization*: The characterization of the library was done by use of Liberate from Cadence. All cells were characterized for a nominal temperature of 25 °C in the TT process corner. To accurately characterize the behavior of the digital cells, the input slews and load capacitance must be defined. The characterization was done for the following input slews and load capacitances:

- Input slew: 0.5 ns, 1 ns, 3 ns, 7 ns, 10 ns
- Load capacitance: 0.5 fF, 1 fF, 2 fF, 3 fF, 5 fF

The library contains results for all combinations of input slews and load capacitances. Values were chosen based on initial simulation results and measurements of capacitance of various cells.

3) *Synthesis*: The gate-level synthesis was performed with Genus from Cadence. To allow more accurate area optimization and reporting, lef files for the technology, and the generated lef files for the library, were included in the script run by Genus. The synthesis was performed with a high effort on redundancy removal and optimization for timing, area, and power.

The power estimations were performed with default settings. The leakage power is calculated from values given by the lib files, and the dynamic power is calculated as following: If a pin is associated with a clock, the default toggle rate is 10% of the frequency. If a pin is *not* associated with a clock, the default toggle rate is 1% of the frequency.

B. Testbench

The implementation of the testbench is presented in Section IV-D2. In order to find the most energy-efficient supply voltages, some metrics should be defined.

The average power consumption, P_{avg} , is found by measuring the current delivered by the power supply, and multiply the average current, I_{avg} , with the supply voltage, V_{VDD} , as shown in eq. 3. From this, the total energy consumed when simulating the testbench can be calculated by multiplying the average power consumption with the time, T , as shown in eq. 4. As the number of clock cycles is known, the total time required can be substituted with a function given by the frequency f , as shown in eq. 5.

$$P_{avg} = I_{avg} \cdot V_{VDD} \quad (3)$$

$$E = P_{avg} \cdot T \quad (4)$$

$$E = P_{avg} \cdot \frac{\text{cycles}}{f} \quad (5)$$

IV. IMPLEMENTATION

In this chapter, the implementation of the standard cell library will be presented. All digital cells were implemented using Super Low VT (SLVT) transistors to maximize speed. A consequence of this is a trade-off with higher current leakage through the transistors. Each transistor was implemented with a width of 200 nm, and minimum gate length. The width was chosen by initial experimentation to achieve a balanced rise and fall time for the output of the inverter. Every transistor was implemented with equal width to simplify the design process. As will be explained in Section IV-A1, higher drive strengths were obtained by using multiple transistors in parallel.

PicoRV32, a RISC-V CPU architecture presented in Section IV-D, was synthesized with a supply voltage of 300 mV and frequency of 3.2 MHz. The synthesized design was used in Place And Route (P&R), to generate a netlist where parasitic components were extracted. The resulting netlist will be referred to as the main netlist in this report. All simulation results are based on simulation of the main netlist.

A. Digital Cells in standard cell library

All digital cells have been designed to function optimally with a supply voltage of 300 mV. The cells that have been implemented are presented in Table II. The schematics and layouts for all cells are presented in Appendix A.

Each cell has a fixed height of 1.3 μm . The width is a multiple of 130 nm for compatibility with the Process Design Kit (PDK).

TABLE II: Digital cells implemented in the standard cell library

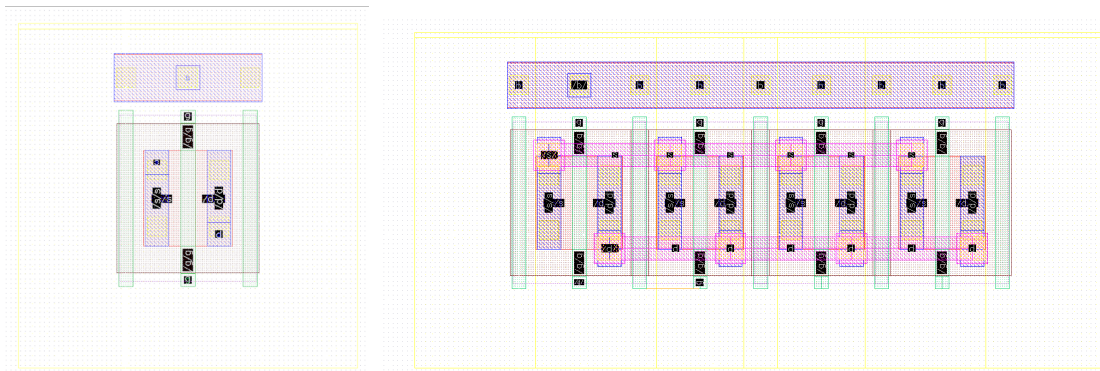
Name	Drive strength	Description
INV1	X1 (Fig. 16), X4 (Fig. 17)	Single-input inverter
BUFF1	X1 (Fig. 18)	Tri-state buffer
NAND2	X1 (Fig. 19)	Two-input NAND
AND2	X1 (Fig. 20)	Two-input AND
NOR2	X1 (Fig. 21)	Two-input NOR
OR2	X1 (Fig. 22)	Two-input OR
XNOR2	X1 (Fig. 23)	Two-input XNOR
XOR2	X1 (Fig. 24)	Two-input XOR
AOI12	X1 (Fig. 25)	Two-input AND to two-input NOR
AOI22	X1 (Fig. 26)	Double two-input AND to two-input NOR
AOI112	X1 (Fig. 27)	Two-input AND to three-input NOR
AOI212	X1 (Fig. 28)	Double two-input AND to three-input NOR
AOI222	X1 (Fig. 29)	Triple two-input AND to three-input NOR
OAI12	X1 (Fig. 30)	Two-input OR to two-input NAND
OAI22	X1 (Fig. 31)	Double two-input OR to two-input NAND
OAI211	X1 (Fig. 32)	Two-input OR to three-input NAND
OAI222	X1 (Fig. 33)	Triple two-input OR to three-input NAND
MUX2	X1 (Fig. 34)	2:1 multiplexer
DFF	X1 (Fig. 35), X4 (Fig. 36)	D-type flip-flop
DL	X1 (Fig. 37)	D-type latch
FA	X1 (Fig. 38)	Full adder

The area for the layout of each cell is presented in Table III.

1) *Transistors*: As shown in Table II, there are two available drive strengths in the library. The width of all transistors are 200 nm (for both NMOS and PMOS). As the height of the cells should be equal for every cell in the library [1], this is the case for both X1- and X4-versions of the cells. The higher drive strength is realized by having multiple transistors in parallel. The given technology requires the bulk connection to be connected to the VDD/VSS rails, so they are in themselves a part of the rails. Fig. 5 presents the layout for PMOSX1 and PMOSX4. NMOSX1 and NMOSX4 layouts are presented in Fig. 6

TABLE III: Area of the implemented cells

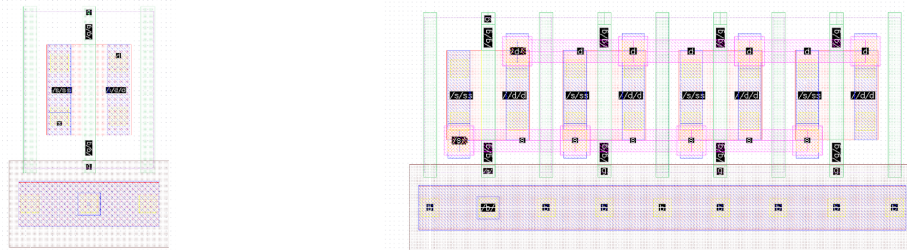
Cell	Area
INV1X1	0.507 μm^2
INV1X4	1.690 μm^2
BUFF1X1	1.521 μm^2
NAND2X1	0.676 μm^2
AND2X1	1.014 μm^2
NOR2X1	0.676 μm^2
OR2X1	1.014 μm^2
XNOR2X1	2.366 μm^2
XOR2X1	2.366 μm^2
AOI12X1	1.183 μm^2
AOI22X1	1.183 μm^2
AOI112X1	1.014 μm^2
AOI212X1	1.352 μm^2
AOI222X1	1.690 μm^2
OAI12X1	1.183 μm^2
OAI22X1	1.352 μm^2
OAI211X1	1.183 μm^2
OAI222X1	1.859 μm^2
MUX2X1	3.549 μm^2
DFFX1	2.535 μm^2
DFFX4	9.126 μm^2
DLX1	2.535 μm^2
FAX1	7.943 μm^2
FILLER	0.169 μm^2



(a) Layout for PMOSX1

(b) Layout for PMOSX4

Fig. 5: Layout for the PMOS transistors



(a) Layout for NMOSX1

(b) Layout for NMOSX4

Fig. 6: Layout for the NMOS transistors

The main difference that must be accounted for is that the transistors are connected on another metal layer when dealing with multiple transistors in parallel. As mentioned, the bulk connections are all connected

to the rails that are over the PMOS transistors and under the NMOS transistors. The rails are designed to be easy to stack side by side. In addition, the symmetrical rails allow similar transistors to be mirrored over/under the rails. To be compliant with the restrictions of the PDK and reduce mismatch and PVT-variations, the gates have a fixed pitch of 130 nm. Non-active poly is included for the reasons presented in [1].

2) *Simple logic gates:* Implementation of the most basic inverting logic cells (INV1, NAND2, NOR2) is very intuitive. Section II-B presents some information about how NAND2 and NOR2 can be implemented. Only two-input versions of the cells are included in this standard cell library.

AND2 and OR2 have been designed by simply using NAND2/NOR2 and an inverter in series. The area has been slightly minimized by having an overlap between the cells, reducing the area from what would be possible by the synthesis tool.

XNOR2 and XOR2 have been designed using an 8 transistors in a static CMOS configuration [6]. Inverters are included in the cells to provide the inverted complements of the signals within the cells. Note that, in difference with the other logic gates presented in this section, one can achieve the inverting functionality without including an inverter on the output of the complementing cell.

INV1 is one of the few gates that has both an X1- and an X4-version. As this is one of the most used gates, the overall synthesized design can benefit by having more than one available drive strength.

3) *Compound logic gates:* How to draw the schematic for compound logic gates is presented in Section II-B1. All implemented compound cells are of And-Or-Invert (AOI) and Or-And-Invert (OAI)-type. The non-inverting complements of the cells can be realized using an inverter on the output, which can be done by the synthesis tool, and has therefore not been implemented in the current cell library. The following cells, with the given Boolean functions have been implemented:

- AOI12X1: $Y = \overline{AB + C}$ (Presented in Fig. 25)
- AOI22X1: $Y = \overline{AB + CD}$ (Presented in Fig. 26)
- AOI112X1: $Y = \overline{AB + C + D}$ (Presented in Fig. 27)
- AOI212X1: $Y = \overline{AB + CD + E}$ (Presented in Fig. 28)
- AOI222X1: $Y = \overline{AB + CD + EF}$ (Presented in Fig. 29)
- OAI12X1: $Y = \overline{(A + B)C}$ (Presented in Fig. 30)
- OAI22X1: $Y = \overline{(A + B)(C + D)}$ (Presented in Fig. 31)
- OAI211X1: $Y = \overline{(A + B)CD}$ (Presented in Fig. 32)
- OAI222X1: $Y = \overline{(A + B)(C + D)(E + F)}$ (Presented in Fig. 33)

By inspecting the schematics of one of the larger compound logic gates, the maximum amount of transistors between the output and the VDD/VSS rails can be more than what is required by using multiple two-input logic gates (for example up to three transistors in AOI222X1, Fig. 29b, or OAI222X1, Fig. 33b).

4) *Buffers:* For the synthesis tool to be able to amplify signals or delay signals (given timing constraints), there should be at least one buffer in the cell library [7]. For several buffers to be attached to a databus or similar, it should be a tri-state buffer. This allows several buffers to avoid outputting to the bus all at once. In the current library, a tri-state buffer with an enable signal E has been implemented. When E is high, the output Y is equal to the input A . When E is low, the output is Z (high-impedance), disregarding the value of the input is.

Due to time restrictions for the project, a digital buffer (without an enable signal), or an inverting tri-state buffer, has not been implemented.

5) *Multiplexer:* The 2:1 multiplexer that has been implemented is presented in Fig. 34. The multiplexer passes either the value of input A , or the value of input B to the output, depending of the value of the select signal, SEL . This is realized by ANDing the inputs with the select signal (inverted in the case of A). By the use of the AND-gates, only one signal can be passed to the OR-gate at the time.

6) *D-type flip-flop:* For the D-type flip-flop, two drive strengths have been implemented (X1 and X4). As one of the most timing-critical parts of the library, it's beneficial to have the possibility to have cells with higher speed. The implemented design is based on the Pass Gate DFF presented in [8]. This design was chosen as it scored the best overall score for low-voltage implementations.

The DFFX1 is presented in Fig. 35, and DFFX4 is presented in Fig. 36. Note that flip-flops are necessary to synthesize sequential digital designs.

7) *D-type latches*: Some designs written in HDL may require a latch. Various HDL designs were synthesized for testing purposes, but some designs required latches to be synthesizable. Although the D-type latch is not required for work presented in this report, the latch was implemented to allow the library to be used whenever a design should be synthesizable.

As the D-type latch is not a high priority for this project, only a single drive strength has been implemented. The DLX1, presented in Fig. 37, is an Active High Transparent Latch, with a non-inverted output.

8) *Full Adder*: A full adder may be implemented by the synthesis tool. However, by implementing a full-custom cell, one can exploit known optimizations, which may improve the overall performance of the synthesized design. The full adder (FAX1) that is implemented in this library is inspired by a FA implementation, using XNOR gates and a multiplexer, presented in [9]. A comparative study of multiple full adders was done in [10], where the XNOR based implementation obtained good results for both energy-efficiency and speed with a sub-threshold implementation. The full adder is presented in Fig. 38.

9) *Filler*: Although not an active part of the digital library, filler cells need to be implemented to ensure that the P&R tool is able to fill void. There are a couple of things to keep in mind when designing the filler cell. It is used to ensure that the layout after P&R does not contain any DRC errors because of empty space between cells. Similar to other cells, the filler cells should contain rails that are symmetrical. This ensures that the rails have similar symmetry, reducing mismatch- and PVT-variations. Dummy-poly are implemented as well for the same reasons. As the cell does not contain any components, designing a schematic is not required. The layout for the filler cell, named FILLER, is presented in Fig. 7. Some overlapping layers (N-well regions etc.) are included to remove any possible DRC errors due to arbitrary distances between the layers.

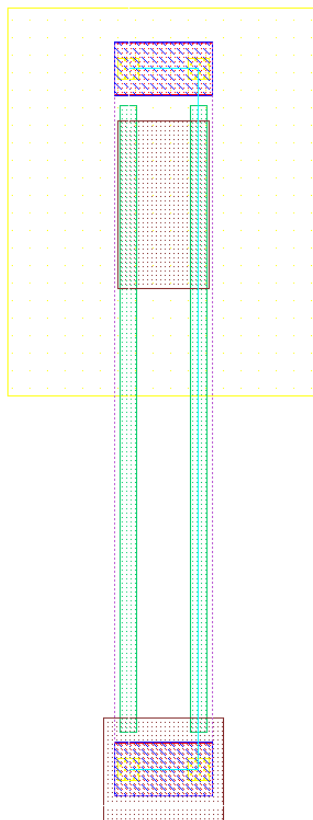


Fig. 7: Layout for FILLER

B. Library characterization

The method used for the library characterization process is described in Section III-A2. As mentioned, the characterization was done for nominal temperature in the TT corner. Presented results do therefore not take PVT-variations.

However, it can be beneficial to analyze the robustness of the various cells. To achieve this, the different process corners were characterized over three temperatures: 25 °C, −20 °C and 85 °C.

The most interesting operating conditions were found to be the following:

- 25 °C, TT-corner, Nominal conditions
- 85 °C, FF-corner, Highest speed and highest power consumption
- −20 °C, SS-corner, Lowest speed and lowest power consumption

The results from comparisons of the different operating conditions are presented in Section V-A.

C. Synthesis of digital designs

Before synthesizing a larger digital design, some smaller designs were used for some intermediate verification of the standard cell library. As the motivation was to verify the functionality of the standard cell library, the frequency was kept fairly low. Both designs were synthesized for 300 mV and 1 MHz.

These two designs were synthesized:

- A full adder, synthesized with the FAX1 cell excluded.
- An 8-bit counter with support for enable and loading data.

After synthesis, the designs went through P&R and extraction of parasitic components. Simulations were performed, by using PADE, on the netlists with parasitic components extracted.

1) *Full adder*: The full adder is a simple clocked adder, with carry-in and carry-out signals. The RTL-code, written in SystemVerilog, is presented in Listing 1. At every positive clock edge, the carry-out, *CO*, and sum, *S*, is calculated as the sum of the input values (*A*, *B* and *CI*).

```
module adder (  
    input logic A,  
    input logic B,  
    input logic CI,  
    input logic clk,  
    output logic CO,  
    output logic S  
);  
  
    always_ff @(posedge clk) begin  
        {CO, S} <= A + B + CI;  
    end  
  
endmodule
```

Listing 1: Implementation of the full adder

The synthesis was performed by excluding the full adder cell, FAX1. If synthesis would produce all combinatorial logic with a single cell, it could be more difficult to verify that the standard cell library is compatible with the whole design flow.

The simulation looped through the possible combinations of the inputs, and the output values were measured and inspected visually. For the simulation, the supply voltage was 300 mV and the frequency was 1 MHz. The results are presented in Section V-B.

2) *Counter*: The 8-bit counter is written in Verilog, as presented in Listing 2.

The counter can be reset with the *reset* signal. If the *enable* signal is high, *out* is incremented every clock cycle. The *load* signal can be used to load a value from *data* to the counter.

```

module top( out, data, load, enable, clk, reset);

output [7:0] out;
input [7:0] data;
input load, enable, clk, reset;

reg [7:0] out;

always @(posedge clk)
    if (reset) begin
        out <= 8'b0;
    end else if (load) begin
        out <= data;
    end else if (enable) begin
        out <= out + 1;
    end
end
endmodule

```

Listing 2: Implementation of the Counter

The testbench works by resetting the counter for 1 clock cycle, and enables it immediately after the reset. The *enable* signal goes low at 8 μ s for one clock cycle before going high again. At the same time, and the *load* signal goes high for a single clock cycle, while *0x55* is written to *data*. Then the counter should resume operation, counting up from *0x55*.

D. PicoRV32

PicoRV32⁴ is an open-source RISC-V CPU implementation written in Verilog. The CPU may be configured as a RV32E, RV32I, RV32IC, RV32IM or RV32IMC core. To simplify the design, the CPU was implemented as shown in Listing 3 (A. Djupdal, personal communication, May 12, 2021). This configuration reduces the number of registers, disables interrupts and 64-bit counters. Additionally, it allows instructions for comparisons and arithmetic operations to use two clock cycles, which relaxes timing requirements.

The motivation for implementing a RISC-V processor was to verify the functionality of the standard cell library, and obtain quantitative results of the performance of the library. The CPU was synthesized for 300 mV, over a range of frequencies. The maximum frequency that met timing restrictions after synthesis was found to be 3.2 MHz. Using the synthesized netlist for 300 mV and 3.2 MHz, the layout of the CPU was obtained after P&R. The layout was verified to pass DRC and LVS, and parasitic components were extracted for the layout of the whole CPU. Extraction of the parasitic components was done similar to the process for extraction for each standard cell, explained in Section II-A1. All simulations were done on the main netlist obtained after the parasitic extraction. This implies that the CPU is optimized for 300 mV and 3.2 MHz by the synthesis tool.

1) *P&R*: Power rings were added around the CPU to allow the P&R tool to route the power rails. This was necessary to pass LVS and ensure that the netlist had consistent VDD/VSS rails. P&R was done with a core utilization of 70%. As the main focus was to verify that the standard cell library worked correctly, no efforts were made to increase the core utilization from the default value. Because of this, necessary filler cells were added to ensure that no DRC errors occurred.

2) *Testbench*: The testbench that has been used to simulate the CPU is shown in Listing 4 (A. Djupdal, personal communication, May 18, 2021). It works by executing multiple instructions that are given in *memimage.hex*.

Initially, the CPU resets for eight clock cycles before processing the instructions. The simulation of the testbench is finished when the execution of the instructions in the memory is completed. Alternatively, on a timeout, if the CPU behaves incorrectly (ie when the frequency is higher than possible).

The content of *memimage.hex* executes the program presented in Listing 5 (A. Djupdal, personal communication, May 18, 2021). With eight clock cycles for resetting the CPU, the whole execution

⁴The full Verilog code for the CPU can be found on [github](#). The version used in the implementation is the following commit: f9b1beb4cfd6b382157b54bc8f38c61d5ae7d785.

A version that was forked on May 27, 2021 is available [here](#)

```

module top (
    input          clk,
    input          resetn,
    output wire    mem_valid,
    output wire    mem_instr,
    input         mem_ready,
    output wire [31:2] mem_addr,
    output wire [31:0] mem_wdata,
    output wire [ 3:0] mem_wstrb,
    input         [31:0] mem_rdata
);
    wire [31:0] mem_addr_i;

    parameter [31:0] STACKADDR = 32'h 0000_0400;
    parameter [31:0] PROGADDR_RESET = 32'h 0000_0000;

    assign mem_addr = mem_addr_i[31:2];

    picorv32 #(
        .ENABLE_COUNTERS64      (0),
        .ENABLE_REGS_16_31      (0),
        .ENABLE_REGS_DUALPORT    (0),
        .LATCHED_MEM_RDATA      (1),
        .CATCH_MISALIGN          (0),
        .CATCH_ILLINSN           (0),
        .TWO_STAGE_SHIFT         (0),
        .TWO_CYCLE_COMPARE       (1),
        .TWO_CYCLE_ALU           (1),
        .STACKADDR                (STACKADDR),
        .PROGADDR_RESET           (PROGADDR_RESET),
        .ENABLE_IRQ               (0)
    ) cpu (
        .clk          (clk),
        .resetn       (resetn),
        .mem_valid    (mem_valid),
        .mem_instr    (mem_instr),
        .mem_ready    (mem_ready),
        .mem_addr     (mem_addr_i),
        .mem_wdata    (mem_wdata),
        .mem_wstrb    (mem_wstrb),
        .mem_rdata    (mem_rdata)
    );
endmodule

```

Listing 3: Top implementation of PicoRV32 (A. Djupdal, personal communication, May 12, 2021)

takes 82 clock cycles.

The CPU was synthesized for various values of supply voltages and clock frequency to obtain an estimate for the maximum possible frequency for each supply voltage. However, the testbench was simulated only on the netlist that was synthesized for 300 mV.

```

`timescale 1 ns / 1 ps

module tb_picorv32;
    reg clk;
    reg resetn;
    wire mem_valid;
    wire mem_instr;
    wire [31:2] mem_addr;
    wire [31:0] mem_wdata;
    wire [ 3:0] mem_wstrb;
    reg [31:0] mem_rdata;

    reg [31:0] mem [0:255];

    integer cyclecounter;

    initial begin
        $readmemh("memimage.hex", mem);
        cyclecounter = 0;
        clk = 0;
        resetn = 0;
        #8000 resetn = 1;
    end

    always #500 clk=~clk;

    // stop if timeout
    always @(posedge clk) begin
        cyclecounter = cyclecounter + 1;
        if(cyclecounter >= 100) begin
            $display("Error, timeout");
            $stop;
        end
    end

    // memory
    always @(*) begin
        if (mem_valid) begin
            mem_rdata <= mem[mem_addr];
            if (mem_wstrb[0]) mem[mem_addr][ 7: 0] <= mem_wdata[ 7: 0];
            if (mem_wstrb[1]) mem[mem_addr][15: 8] <= mem_wdata[15: 8];
            if (mem_wstrb[2]) mem[mem_addr][23:16] <= mem_wdata[23:16];
            if (mem_wstrb[3]) mem[mem_addr][31:24] <= mem_wdata[31:24];
        end
    end

    // exit when firmware exits
    always @(*) begin
        if( (mem_valid) &&
            (mem_addr == 30'h0000_080) &&
            (mem_wstrb == 4'hf) &&
            (mem_wdata == 32'h0000_00ad)
        ) begin
            $display("Test program ended correctly");
            $stop;
        end
    end

    top chip (
        .clk          (clk),
        .resetn       (resetn),
        .mem_valid    (mem_valid),
        .mem_instr    (mem_instr),
        .mem_ready    (1),
        .mem_addr     (mem_addr),
        .mem_wdata    (mem_wdata),
        .mem_wstrb    (mem_wstrb),
        .mem_rdata    (mem_rdata)
    );
endmodule

```

Listing 4: Testbench for simulation of PicoRV32 (A. Djupdal, personal communication, May 18, 2021)

```
#define MEM_RESULT 512

int main(int argc, char *argv[]) {
    int volatile *res = (int*)MEM_RESULT;
    *res = 0xad;
    return 0;
}
```

Listing 5: Program executed when running the instructions in *memimage.hex* (A. Djupdal, personal communication, May 18, 2021)

V. RESULTS

The library characterization produces datasheets for each cell, presented in Appendix B. Additional results and further elaboration of the results regarding the library characterization are presented in Section V-A.

The simulation of the 8-bit counter and full adder were intended to verify the functionality of the library. The results are presented in Section V-B and V-C.

Synthesis results of the PicoRV32 CPU is presented in Section V-D1. These results are based on reports generated by the synthesis tool.

Section V-D2 presents the results that are obtained by simulating the testbench of the PicoRv32 processor (presented in Section IV-D2). All simulations were done on the same netlist, synthesized for 300 mV and 3.2 MHz, after P&R and extraction of parasitic capacitance. As mentioned, this netlist will be referred to as the main netlist.

A. Library characterization

The library characterization produced a library file and a Verilog file containing Verilog descriptions of the cells. Additionally, the characterization produced datasheets of each cell. All datasheets characterized for 300 mV are presented in Appendix B. As mentioned in Section IV-B, the characterization was performed for nominal circumstances, which is 25 °C in the TT-corner. These are the results exactly as extracted from the library characterization, only edited for formatting. Notice that area and process corners are absent from the datasheets. The correct area of the cells is presented in Table III

The cells were also characterized with other operating conditions, as mentioned in Section IV-B. Some key results are presented in Table IV. The Δdelay and Δpower columns is the difference in the maximum delay and leakage power from the nominal conditions (25 °C, TT-corner). They are calculated as shown in eq. (6), where Delay is the maximum delay as shown in the table, and Leakage is the leakage power. Delay_{nom} and Leakage_{nom} are the values from the nominal operating conditions (25 °C, TT-corner).

$$\Delta \text{delay} = \frac{\text{Delay}}{\text{Delay}_{nom}}, \quad \Delta \text{power} = \frac{\text{Leakage}}{\text{Leakage}_{nom}} \quad (6)$$

As there are plentiful cells in the library, only a selection has been presented. However, the characterization results for all cells are presented in Appendix C.

TABLE IV: Library characterization results for different operating conditions

Operating conditions	Cell	Maximum delay	Δ delay	Leakage power	Δ power
25 °C, TT-corner	INV1X1	10.89 ns	1.0	0.14 nW	1.0
	INV1X4	7.28 ns	1.0	0.57 nW	1.0
	NAND2X1	16.64 ns	1.0	0.29 nW	1.0
	AND2X1	16.03 ns	1.0	0.35 nW	1.0
	XNOR2X1	25.9 ns	1.0	0.46 nW	1.0
	AOI12X1	21.53 ns	1.0	0.29 nW	1.0
	AOI112X1	32.35 ns	1.0	0.29 nW	1.0
	AOI222X1	36.83 ns	1.0	0.29 nW	1.0
OAI222X1	28.02 ns	1.0	0.43 nW	1.0	
-20 °C, SS-corner	INV1X1	48.8 ns	4.48	0.01 nW	0.06
	INV1X4	20.83 ns	2.86	0.03 nW	0.06
	NAND2X1	89.9 ns	5.4	0.02 nW	0.06
	AND2X1	89.7 ns	5.6	0.02 nW	0.06
	XNOR2X1	175.43 ns	6.77	0.03 nW	0.06
	AOI12X1	145.14 ns	6.74	0.02 nW	0.06
	AOI112X1	241.41 ns	7.46	0.02 nW	0.06
	AOI222X1	280.24 ns	7.61	0.02 nW	0.06
OAI222X1	176.2 ns	6.29	0.02 nW	0.06	
85 °C, FF-corner	INV1X1	4.05 ns	0.37	2.89 nW	20.27
	INV1X4	2.17 ns	0.3	11.56 nW	20.27
	NAND2X1	4.5 ns	0.27	5.45 nW	18.67
	AND2X1	3.73 ns	0.23	8.44 nW	23.89
	XNOR2X1	5.84 ns	0.23	11.14 nW	24.17
	AOI12X1	5.92 ns	0.27	6.03 nW	20.58
	AOI112X1	7.08 ns	0.22	9.07 nW	31.22
	AOI222X1	7.54 ns	0.2	8.72 nW	30.21
OAI222X1	6.23 ns	0.22	8.0 nW	18.42	

B. Full Adder

The synthesis and P&R for the full adder completed without any errors. Both DRC and LVS checks passed. The simulation results for the full adder are presented in Fig. 8. By visually inspecting the graph, it is clear that the clock period is 1 μ s.

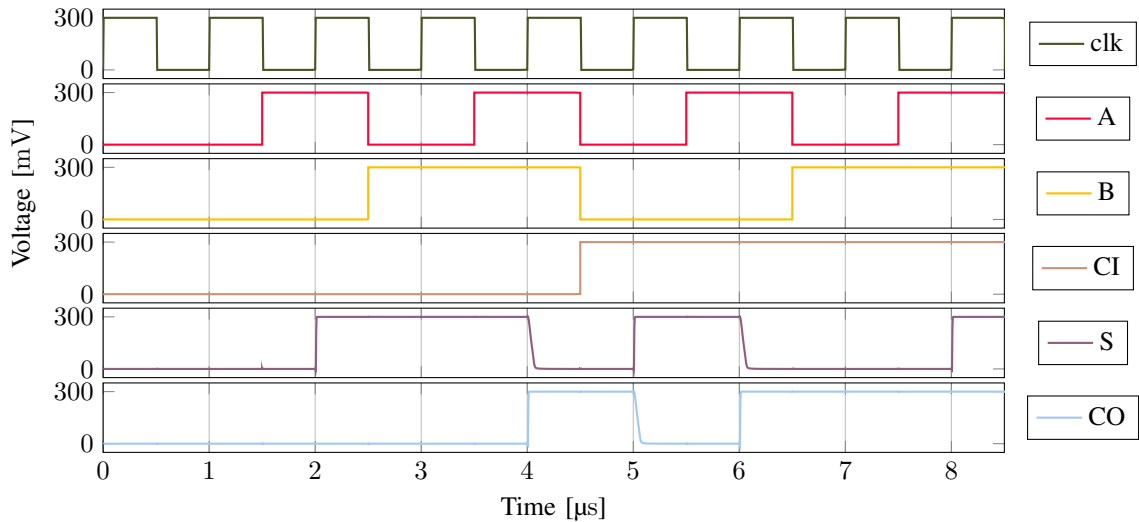


Fig. 8: Simulation results of full adder

C. Counter

The 8-bit counter was synthesized, placed, and routed without any reported errors. DRC and LVS did not report errors.

The simulation results of the counter are presented in Fig. 9. Note that the *data* signal has not been excluded in the graph to simplify the figure.

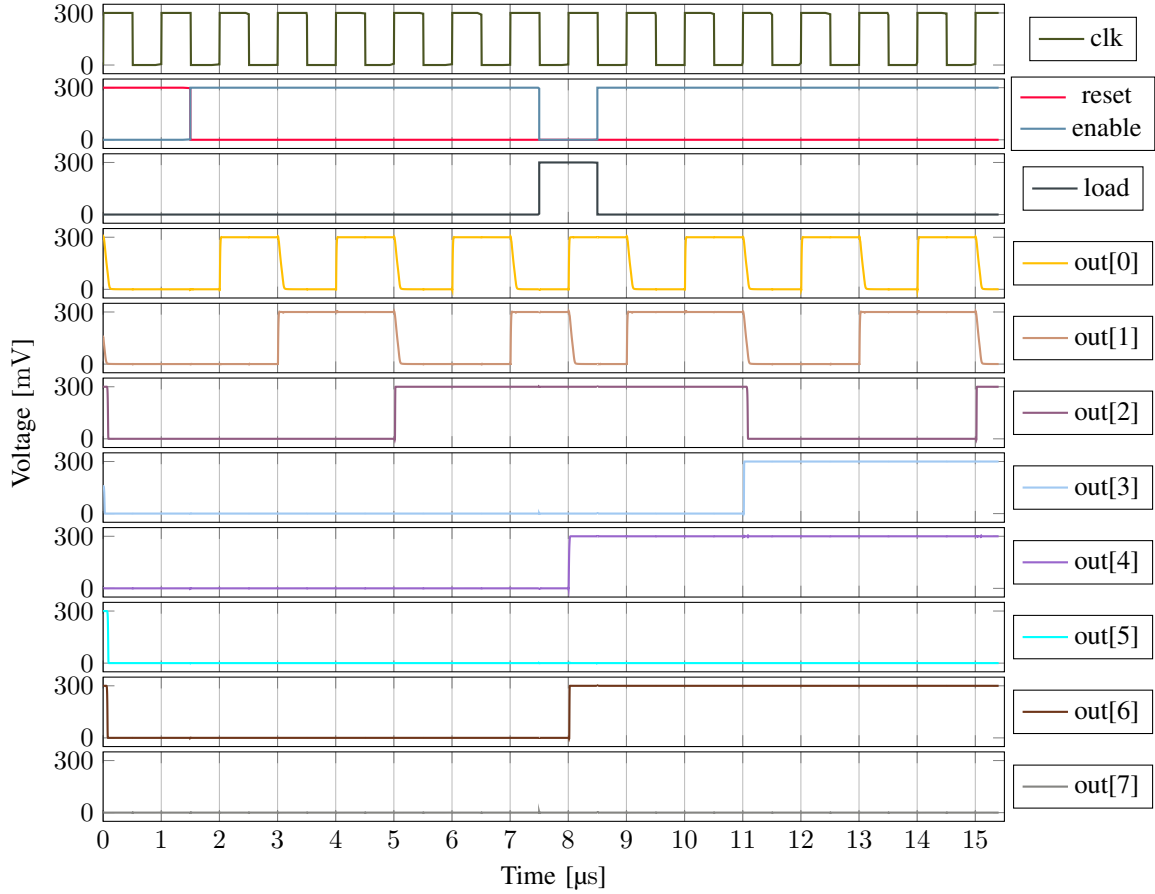


Fig. 9: Simulation results of 8-bit counter

D. PicoRV32

1) *Synthesis and P&R*: The synthesis of the main netlist produced the following results:

- Supply voltage: 300 mV
- Frequency: 3.2 MHz
- Area: 30 219 μm^2
- Number of gates: 17555
- Total power consumption: 8.82 μW
- Dynamic power consumption: 4.26 μW
- Leakage power consumption: 4.56 μW
- Timing slack: 11 ps

After P&R, the measured area was 32 604 μm^2 , which is an increase of approximately 7.9%.

The layout is shown in Fig. 10. By inspecting the layout, one can see that the digital logic does not fill the entire layout. However, the area that does not contain digital logic is not empty but has been filled by the filler cells.

On the left and right sides of the design, horizontal wires can be seen between the power rings and the core. These are the results of routing the power nets.

The pair of frequencies and voltages presented in Table V were synthesizable with a positive timing slack. All simulation results presented in Section V-D2 were done for the main netlist, but the synthesis results were used to determine frequencies to use in simulation.



Fig. 10: Layout of PicoRV32 after P&R

TABLE V: Supported pairs of frequency and voltages after synthesis

Supply voltage	Frequency	Timing slack
250 mV	1.25 MHz	421 ps
300 mV	3.2 MHz	11 ps
350 mV	5 MHz	2644 ps
400 mV	10 MHz	3425 ps
450 mV	20 MHz	37 ps
500 mV	50 MHz	0 ps
550 mV	100 MHz	1 ps
1 V	250 MHz	4 ps

a) *Effect by implementing compound gates:* Section IV-A3 presents the implementation of compound logic gates of AOI- and OAI-type. By excluding the compound gates from synthesis, different results were obtained. The CPU was synthesized for 300 mV and 2 MHz with the compound gates included, and excluded. The difference in results are presented in Table VI. Note that the frequency is different than for the main netlist, which implies that the resulting netlists are therefore different.

TABLE VI: Comparison of synthesis results with compound gates included or excluded

Compound gates	Area	Power Consumption	Leakage Power	Dynamic Power	Timing slack
Included	31 709 μm^2	8.23 μW	4.84 μW	3.40 μW	389 ps
Excluded	33 229 μm^2	8.39 μW	5.13 μW	3.26 μW	629 ps

b) *Area:* The area reported for the main netlist is approximately 30 219 μm^2 . However, the area varies with the frequency and supply voltage, as shown in Fig. 11.

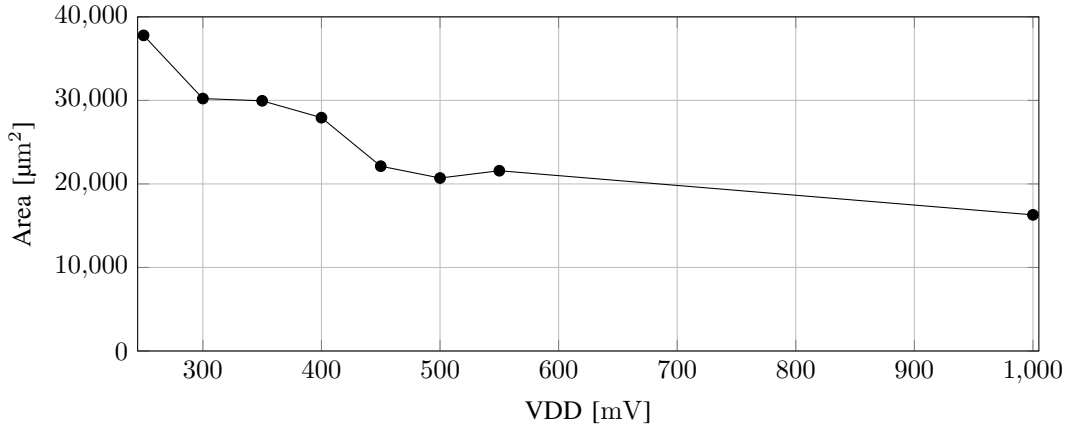


Fig. 11: Area as a function of supply voltage and frequency

The various synthesized results utilized different gates and drive strengths to produce the results. Fig. 12 presents how many INV1X1, INV1X4, DFFX1 and DFFX4 gates were included in the synthesized netlist for the following pairs of frequency and voltage:

- $VDD = 300\text{ mV}$, $f = 2.1\text{ MHz}$ (main netlist)
- $VDD = 500\text{ mV}$, $f = 50\text{ MHz}$
- $VDD = 1\text{ V}$, $f = 250\text{ MHz}$

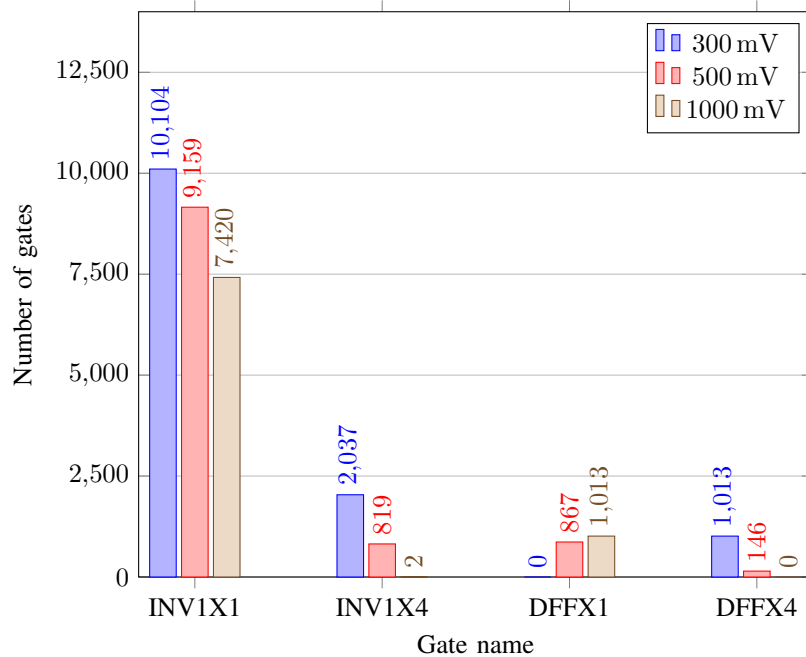


Fig. 12: Logic gates included in the synthesized results

2) *Simulation*: The pairs of frequencies and supply voltages presented in Section IV-D2 were results after synthesis and had to be adjusted when simulating the main netlist. In most cases, the supply voltages had to be increased to support the given frequencies. Table VII presents the pairs of supply voltages and frequencies that were functional, with the average power consumption through the testbench. Additionally, the maximum frequency that was supported for the supply voltage of 300 mV was found to be 2.1 MHz.

The supported frequencies and the power consumption are presented as functions of supply voltage in Fig. 13 and Fig. 14, plotted on a logarithmic axis.

The energy consumed by the testbench as a function of supply voltage is shown in Fig. 15. Note that the frequency is not constant, but varies with the supply voltage as listed in Table VII. The total energy consumption is calculated as explained in Section III-B.

TABLE VII: Simulation results

Supply voltage	Frequency	Average Power Consumption
270 mV	1.25 MHz	1.2 μ W
300 mV	2.1 MHz	1.5 μ W
350 mV	3.2 MHz	2.2 μ W
400 mV	5 MHz	3.0 μ W
450 mV	10 MHz	4.7 μ W
500 mV	20 MHz	7.9 μ W
600 mV	50 MHz	19.9 μ W
650 mV	100 MHz	45.9 μ W
1 V	250 MHz	255.9 μ W

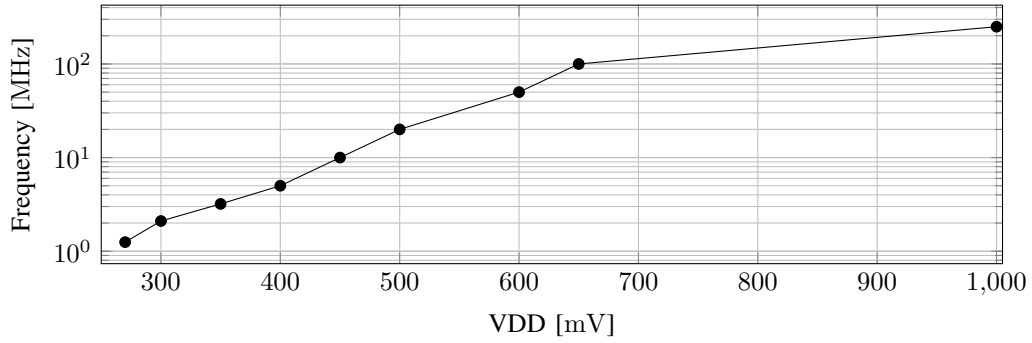


Fig. 13: Supported frequencies

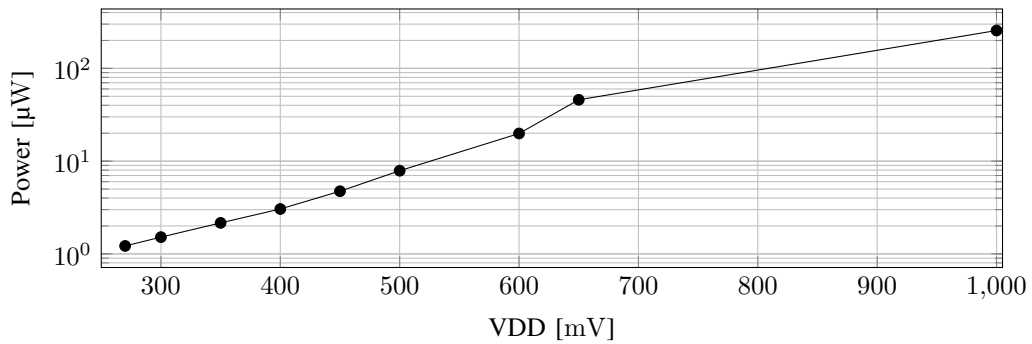


Fig. 14: Power consumption

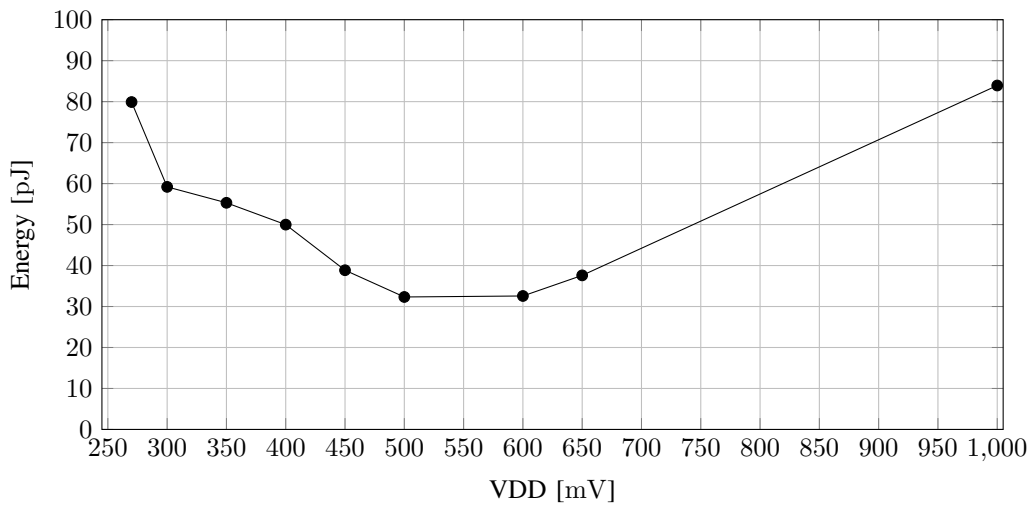


Fig. 15: Energy consumption

VI. DISCUSSION

The implemented standard cell library has been tested through various steps.

The first step was to verify that the library characterization worked as intended. By inspecting the truth tables given in the datasheets generated by Liberate, all cells perform the desired function.

The next step was to verify the functionality of synthesized designs. Before working with the PicoRV32, two smaller designs were tested: A full adder and an 8-bit counter. By verifying and fixing issues with these smaller designs, finding bugs in the standard cell library was an easier process. These designs are discussed in Section VI-B1 and VI-B2.

When the adder and the counter were functional, the PicoRV32 CPU was synthesized. The implementation and results are discussed in Section VI-B3.

A. Library characterization

As mentioned, the datasheets presented in Appendix B contains logical functions and truth tables for each cell. Some of the cells can have unusual functions that are not necessarily the intuitive interpretation of the cell. For example, the function for NAND2X1 is given as $(!A) + (!B)$. What one might expect would be $!(A * B)$. In these cases, one can identify that the logic functionality is equivalent by using *DeMorgan's Theorems* [11]. However, for more complex logical functions (for example, AOI222X1, OAI222X1, or FAX1), it might be simpler to verify the functionality by inspecting the truth tables in the datasheets.

As the logic cells are functional, the next topic to discuss is the behavior of the cells.

All cells were implemented with Super Low VT (SLVT) transistors. By having the lowest possible threshold voltage, the speed of the transistors is maximized. However, this has a drawback, which is an increased leakage current. This can result in high static power consumption. As seen in the datasheets, the leakage power of the cells can range from 0.1425 nW (INV1X1) to 2.5677 nW (DFFX4).

The leakage power for the cells with multiple drive strength is shown in Table VIII. The leakage power increases in both cells with a factor of approximately 4 for the X4-versions. From this, we can assume that there is a probability that the leakage power increases linearly with the number of transistors in parallel.

TABLE VIII: Leakage power for different drive strengths

Cell	INV1X1	INV1X4	DFFX1	DFFX4
Leakage	0.1425 nW	0.5701 nW	0.6419 nW	2.5677 nW

The width of both PMOS and NMOS transistors was chosen to be 200 nm. The reason for this is that the rise time and fall time were balanced for the inverter.

By inspecting the delay in various combinatorial cells, the balance in rise time and fall time is not necessarily balanced. The maximum delay for rising and falling output for a selection of cells is presented in Table IX.

TABLE IX: Delay for rising and falling output for a selection of cells

Cell	Delay	
	Rising output	Falling output
INV1X1	10.89 ns	10.04 ns
INV1X4	7.28 ns	7.13 ns
NAND2X1	11.04 ns	16.64 ns
NOR2X1	20.62 ns	10.11 ns
AOI222X1	36.83 ns	18.89 ns
OAI222X1	23.80 ns	28.02 ns
DFFX1	14.17 ns	69.21 ns
DFFX4	10.58 ns	44.07 ns

Both inverters (X1- and X4-version) have an approximately balanced rise time and fall time, with a marginally higher rise time. NAND2X1 has a higher fall time, while NOR2X1 has a higher rise time.

The schematic in Fig. 19b shows that NAND2X1 has two NMOS transistors between the output and VSS, and one PMOS transistor between the output and VDD. Similarly, the schematic in Fig. 21b shows that NOR2X1 has only one NMOS transistor between the output and VSS, but two PMOS transistors between the output and VDD.

This can explain why there is an opposite imbalance in the rise time and fall time for the two cells. By the same reasoning, the same can be observed for AOI222X1 in Fig. 29b and OAI222X1 in Fig. 33b.

The most unbalanced cell in the library is the D-type flip flop. The rise time is over four times higher than the fall time for both X1- and X4-versions of the cell. As mentioned in Section IV-A6, the design was inspired by [8], where it is stated that the n-channel and p-channel pass gates makes the rise and fall times highly asymmetrical. In addition to the sizes of the transistors not being balanced for the cell in the given technology and implementation, this can explain the imbalance seen in these results.

1) *Library characterization for different operating conditions:* As mentioned in Section V-A, the library was characterized for 300 mV, under nominal operating conditions (25 °C in the TT-corner). To be able to get some estimations of the effect of PVT-variations, the library was also characterized for different operating conditions. The results presented in Table IV and Appendix C presents some points that are worth to note.

When comparing INV1X1 and INV1X4, the change in delay is lower for the higher drive strength in cold conditions.

The larger combinatorial cells of AOI- or OAI-cells have a higher variation in delay than most of the smaller cells. The exceptions are NOR2X1 and OR2X1, which are more comparable to the compound gates. It can be challenging to address the severity of this variation when regarding only individual cells. Section V-D1a shows that the synthesis results improved in regards of power consumption, area, and timing by including compound gates. However, the benefits acquired must be balanced with the increase in PVT-variations.

The D-type flip-flops experienced a different variation in delay in cold conditions than the inverters. DFFX1 and DFFX4 had an increase in delay by a factor of 10.81 and 10.41, respectively. In hot conditions, the delay was reduced by a factor of exactly 10. However, the flip-flops are the cells that have the highest variations due to PVT-variations regarding the delay.

B. Synthesized Designs

The synthesis and Place And Route (P&R) was performed for three digital designs, each increasingly complex. By increasing the complexity gradually, the process of discovering and understanding the root of problems in the implementation was much easier. When transitioning to work on a more complex design, there was not an overwhelming amount of bugs, as they had been fixed after working with the simple designs.

1) *Full Adder:* The first design that was synthesized was a full adder. Even if the design is quite simple, several steps had to be performed correctly to produce any significant simulation results. The first step was to ensure that the library files were readable and compatible with the synthesis tool. Secondly, the P&R had to have correct Library Exchange Format (lef) files to be able to place the cells as they were intended in the design phase. Additionally, the routing had to be performed, which also required a correct lef file. The layout and Verilog netlist had to be exported correctly, which had to pass Design Rule Check (DRC) and Layout Versus Schematic (LVS) checks. When this was finished, the parasitic components could be extracted, and simulation could be performed.

The simulation results are presented in Section V-B. A representation of the results has been prepared in Table X to make the results more readable. Notice that the time in the table is on each positive clock edge. The outputs (*S* and *CO*) are measured by the value that appears shortly after the positive clock edge.

By comparing these results to a truth table for a full adder (for example, in the datasheet for FAX1 in Appendix B, or in [6]), it is clear that the full adder is functional. This indicates that the synthesis, P&R and parasitic extraction provided a netlist that represents a functional full adder.

TABLE X: Digital results, representing the values from Fig 8

Time	A	B	CI	S	CO
1 μ s	0	0	0	0	0
2 μ s	1	0	0	1	0
3 μ s	0	1	0	1	0
4 μ s	1	1	0	0	1
5 μ s	0	0	1	1	0
6 μ s	1	0	1	0	1
7 μ s	0	1	1	0	1
8 μ s	1	1	1	1	1

When inspecting the output signals, S and CO , it is clear that the slew for a rising edge is much steeper than the falling edge. A probable cause for this is the long fall time on the output of the DFFX1 and DFFX4 cells, as discussed in Section VI-A.

2) *8-bit Counter*: The second digital design that was implemented was an 8-bit counter, presented in Section IV-C2. Still a simple design, but it utilized more cells than the full adder. Although a lot was corrected in the standard cell library when implementing the full adder, the increased complexity of the counter allowed more problems to be discovered. With an increased number of utilized cells, some edge cases had to be taken into account.

When the necessary steps had been completed correctly, the counter was simulated to produce the results presented in Section V-C. The simulation results are presented in Table XI for readability.

TABLE XI: Digital results, representing the values from Fig 9

Time	reset	enable	load	data[7:0] (HEX)	out[7:0]	out[7:0](HEX)
1 μ s	1	0	0	0x00	00000000	0x00
2 μ s	0	1	0	0x00	00000001	0x01
3 μ s	0	1	0	0x00	00000010	0x02
4 μ s	0	1	0	0x00	00000011	0x03
5 μ s	0	1	0	0x00	00000100	0x04
6 μ s	0	1	0	0x00	00000101	0x05
7 μ s	0	1	0	0x00	00000110	0x06
8 μ s	0	0	1	0x55	01010101	0x55
9 μ s	0	1	0	0x00	01010110	0x56
10 μ s	0	1	0	0x00	01010111	0x57
11 μ s	0	1	0	0x00	01011000	0x58
12 μ s	0	1	0	0x00	01011001	0x59
13 μ s	0	1	0	0x00	01011010	0x5A
14 μ s	0	1	0	0x00	01011011	0x5B
15 μ s	0	1	0	0x00	01011100	0x5C

When the counter is enabled at time 2 μ s, the counter starts incrementing the output. The incrementation is performed every clock cycle until the *enable* signal goes low at time 8 μ s. At this time, 0x55 is written to *data* and *load* is set high. This results in 0x55 on the output. When *enable* is high again, the output is incremented every clock cycle, starting from 0x55.

The output of the counter works as described by the RTL file, which further verifies that the standard cell library is functional.

The same difference in fall time and rise time can be observed for the counter as for the full adder.

3) *PicoRV32*: The layout of the CPU after P&R, shown in Fig. 10, shows three important points.

Firstly, the design utilized the filler cells correctly. The area that does not contain digital logic was filled as intended.

Secondly, the horizontal wires connect the VDD/VSS-rails through the cells to the power rings around the core as intended.

The last point requires closer attention to the layout. By inspecting the labels in the lower right corner, one can see that the inner power ring is connected to VDD, and the outer ring is connected to VSS. The horizontal wires for the power routing are connected in an alternating fashion to the power rings. Every second rail is connected to VDD, and every other to VSS. As there is no gap between the rails,

the figure shows that the cells are placed in an alternating fashion, where every second row is flipped.

This implies that the P&R tool can utilize the symmetry of the cells as intended. There were no reported errors from DRC and LVS.

It should be mentioned that the core utilization of the CPU was 70%, which is the default value. For products intended for production, this would probably be regarded as sub-optimal. As the wasted area is directly correlated to an increase in cost, the core utilization should be increased. However, it was kept fairly low as it was beneficial to verify that the filler cells worked correctly.

Table VI shows synthesis results with AOI- and OAI-cells included and excluded. By utilizing the compound logic gates, there was an improvement in speed, area, and static power consumption. The improvement was expected, as this was the motivation to implement the compound logic gates. However, the improvement was only approximately 5% regarding the area and approximately 6% regarding leakage. As the improvement is noticeable, it would be hard to argue against including the compound logic gates. Nevertheless, as mentioned in Section V-A, the compound logic gates had slightly higher PVT-variations, which should be taken into account.

Simulation results, presented in Table VII, demonstrates combinations of frequencies and supply voltages that were supported in simulation. The synthesis results, presented in Table V, presents other pairs of frequency and voltage that are supported. This difference can be correlated to the following points:

- 1) Simulation results are done on a netlist containing parasitic components
- 2) The netlists generated by the synthesis tool is different than the main netlist.

The second point is only relevant for the simulations of other supply voltages than 300 mV. However, the simulation results show that the supply voltage had to be increased to 350 mV to support a 3.2 mV. For this reason, the circuit was simulated for 300 mV to find the maximum clock frequency at the nominal supply voltage. This was found to be 2.1 MHz.

Fig. 13 and 14 shows that there is a logarithmic increase in both supported maximum frequency and power consumption with an increase in supply voltage.

The estimation for energy consumption, presented in Fig. 15, shows that the testbench consumes the least amount of energy with a supply voltage between 500 mV and 600 mV. This estimation was higher than expected, especially as the circuit is optimized for 300 mV. It is important to mention that the time required for each simulation varies with the frequency. Consequently, a high leakage power will have a higher impact on low frequencies. This means the results can allude to the library having a substantial leakage, as the minimum energy point is with a higher frequency.

C. Area

Fig. 11 shows that the area can change drastically by synthesizing for higher supply voltages. When comparing the synthesis results for 1 V and 250 mV, the decreased supply voltage results in an increase in area with a factor of approximately 2.5.

One possible reason is that by decreasing the supply voltage, more cells with higher drive strength are required. Additionally, the synthesis may add buffers to enforce that the timing requirements are met. As mentioned in Section IV-A4, only tri-state buffers were implemented in the library. Therefore, digital buffers must be constructed by the synthesis tool by using two inverters instead.

By inspecting Fig. 12, it is a clear trend for the different supply voltages.

- The total number of inverters increased for a lower supply voltage.
- For a lower supply voltage, more cells with higher drive strength were utilized.

In every case, there were a total of 1013 D-type flip-flops. However, for 300 mV, not a single DFFX1 logic gate was utilized. Similarly, for 1 V, only DFFX1 cells were used. For a supply voltage of 500 mV, a combination of the two drive strengths was utilized.

As the area seems to be correlated with the utilized drive strengths, it might be beneficial to implement more versions. For example, X2- and X3-versions could allow the synthesis tool to optimize a little further for area.

As shown in Section IV-A1, the increase in drive strength is realized by using a multiplier for the transistors, which practically simply uses multiple transistors in parallel. However, there are no overlapping nodes of the X4-versions. By inspecting the layout of INV1X4 in Fig. 17c, one can see that the input A is connected to every second strip of poly. This suggests that every second poly-strip is non-active and simply wastes area. To rectify this, connecting the non-active poly-strip to the input, would in practice act as the double amount of active transistors, sharing source and drain. This would exploit the area more efficiently. The drawbacks regarding extra leakage and possible parasitic components would have to be taken into account.

The library does not have any simple digital buffers. This results in a large amount of inverters being used to act as digital buffers. Although the standard cell library is functional, using two inverters is not optimized for size. By inspecting the layout of INV1X1 in Fig. 16c, one can see that there is unused space to the right of the transistors. When two inverters are placed by the P&R tool, this area can not be utilized.

A digital buffer could be easily be implemented more compact than the use of inverters allow, as the mentioned empty space could be utilized. Additionally, the transistors could share the source connected to VDD/VSS rails. If this was designed to be DRC clean, each buffer could be even more compact.

Especially for low voltage implementation, where a large number of extra inverters were added, could this be beneficial.

VII. CONCLUSION

The testbenches of the various synthesized designs provide positive results. All the designs function as they are supposed, which implies that the standard cell library has been implemented correctly to be compatible with a standard design flow. There are some possible areas of improvement with regard to the performance of the library.

The initial idea of using equal transistor size in each cell of the library was to simplify the design process and find the balanced timing for the inverter. However, when the cells became larger and had an imbalanced pull-up and pull-down network, the rise time and fall time became imbalanced as well. NOR2X1, AOI112X1, AOI212X1 and AOI222X1 had approximately twice the delay for rising output, compared to falling output. The DFFX1 and DFFX4 had a delay for falling output that was between four and five times the delay for rising output.

By increasing transistor widths in the pull-up network (pull-down in the case of DFFX1 and DFFX4), the speed could be improved. Subsequently, decreasing the widths in the pull-down network (pull-up for DFFX1 and DFFX4), the leakage could be reduced.

Combining these ideas would improve the balance of the rise time and fall time of the cells, without the full cost in power consumption. This could impact mismatch of transistors negatively, which would need to be taken into consideration.

A. Using SLVT transistors

The standard cell library has been implemented with Super Low VT (SLVT) transistors. The low threshold transistors results in higher speed, but also higher power consumption. Simulation of the PicoRV32 alludes to a dominant passive power consumption. For the given testbench, the results suggest that lowering the leakage of the transistors would be beneficial. The simplest approach would be to use transistors with a higher threshold voltage.

By characterizing the library with other transistors, with other threshold voltages, multiple libraries could be made available. The user could then choose the library that is most suitable for the application, with the optimal balance of speed and leakage.

B. Drive Strength

The higher drive strength for the inverter cell, INV1, has two noticeable advantages: higher speed and lower PVT-variations. This was the expected behavior. On the other hand, the DFFX4 did surprisingly not seem to have the advantage of reduced PVT-variations.

In both cases, the higher drive strength resulted in a larger area and higher power consumption. This was naturally the expected behavior.

Implementing extra possible drive strengths for all cells could benefit the flexibility for the synthesis tool to optimize for speed, area, and power consumption.

C. PicoRV32

PicoRV32 was the largest and most complex synthesized design that the standard cell library was tested with. That the standard design flow provided a functional netlist of the CPU was a good indicator that the library is functional.

The simulation results indicate that the processor is most energy-efficient with a supply voltage between 500 mV and 600 mV, which was surprisingly high. However, as SLVT transistors are used to implement all cells, a high leakage should be expected. This could explain why a higher supply voltage, and consequently a higher clock frequency, resulted in less energy consumed.

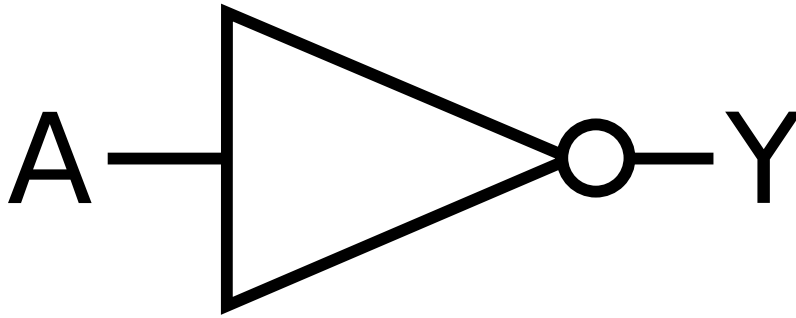
As the leakage is high, the current implementation of the standard cell library could perform well in a system that requires higher speed or with proper power gating. If the library is intended to be used in implementations with lower power consumption, addressing the leakage should be considered.

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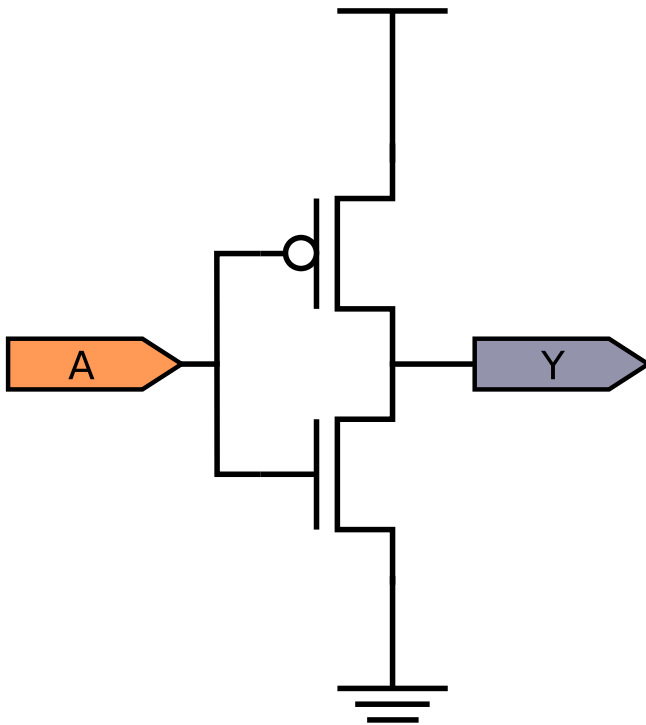
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A. Presentation of standard cells

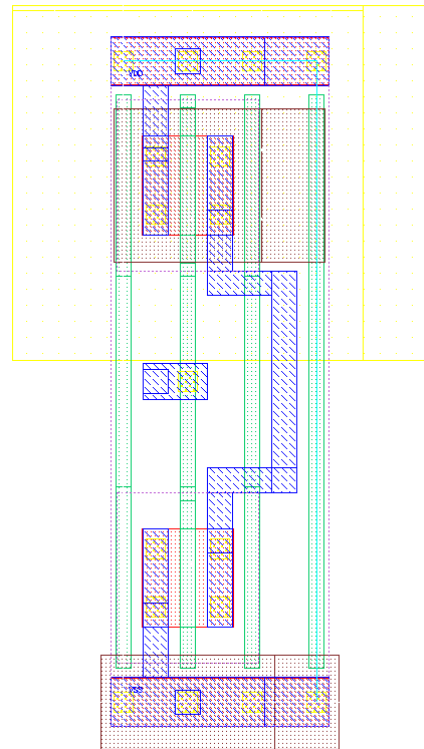
In this section all standard cells are presented with schematic, symbol and the layout.



(a) Symbol for INV1X1

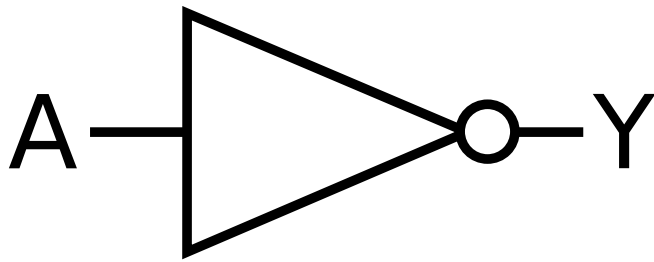


(b) Schematic of INV1X1

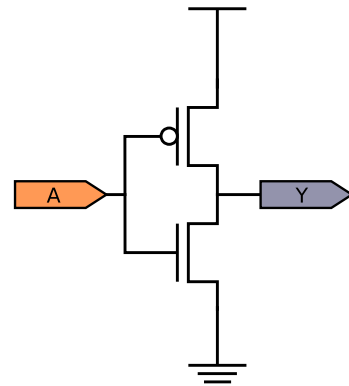


(c) Layout of INV1X1

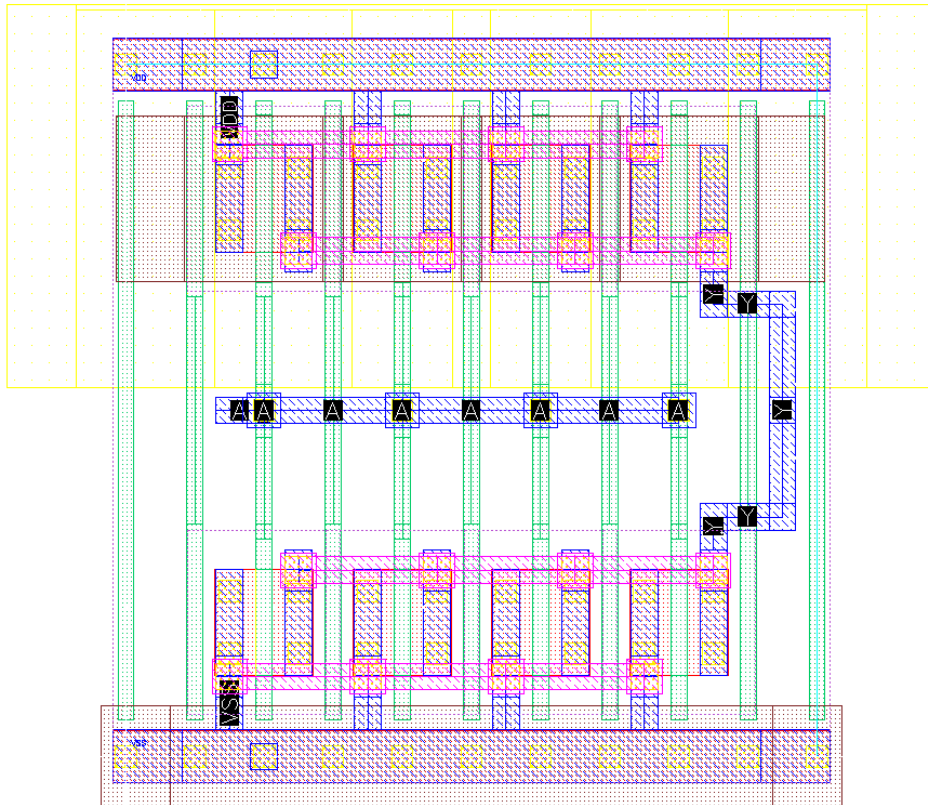
Fig. 16: Standard cell: INV1X1



(a) Symbol for INV1X4

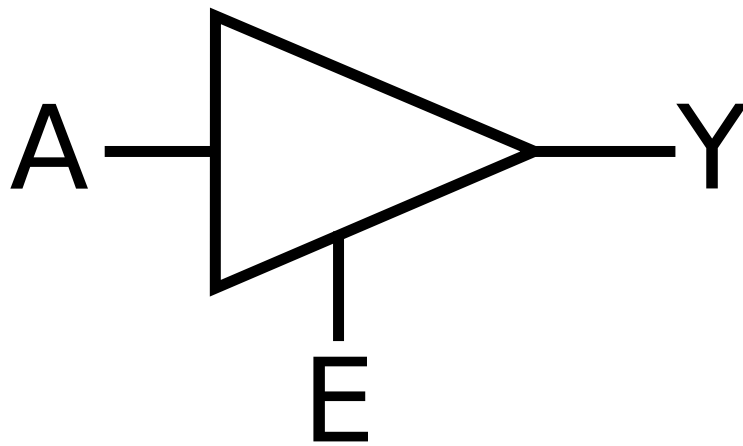


(b) Schematic of INV1X4

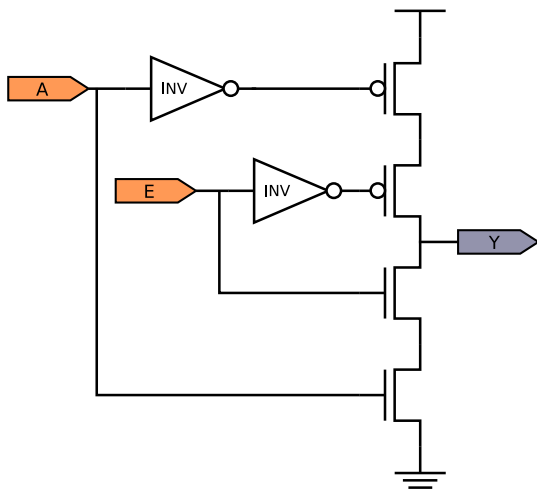


(c) Layout of INV1X4

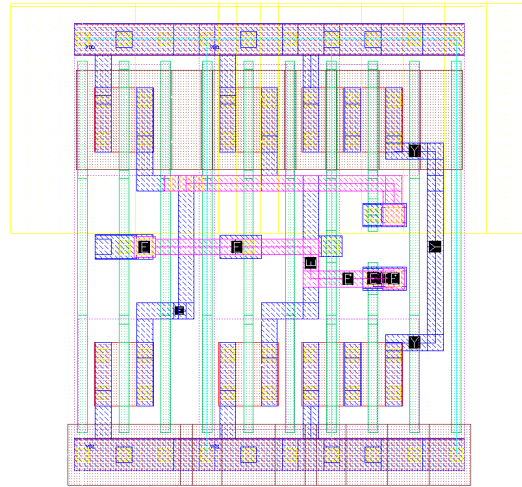
Fig. 17: Standard cell: INV1X4



(a) Symbol for BUFF1X1

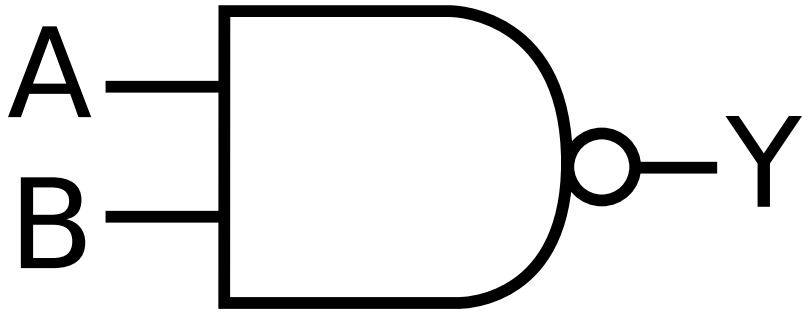


(b) Schematic of BUFF1X1

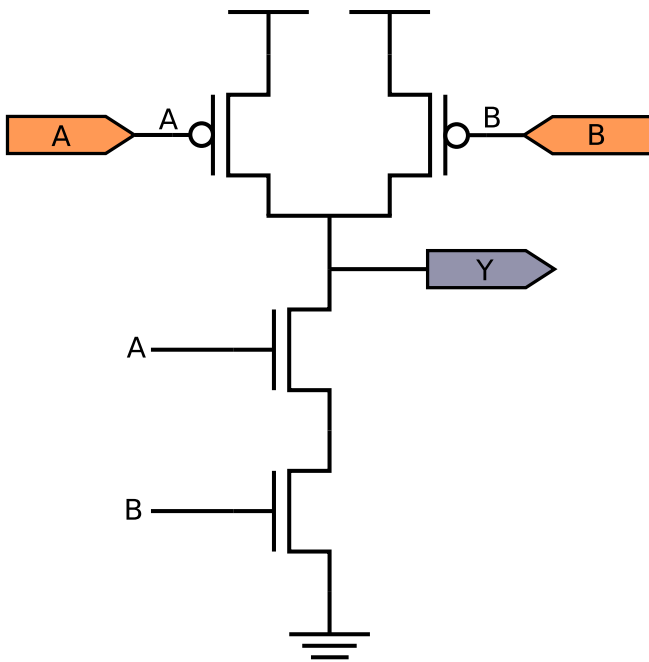


(c) Layout of BUFF1X1

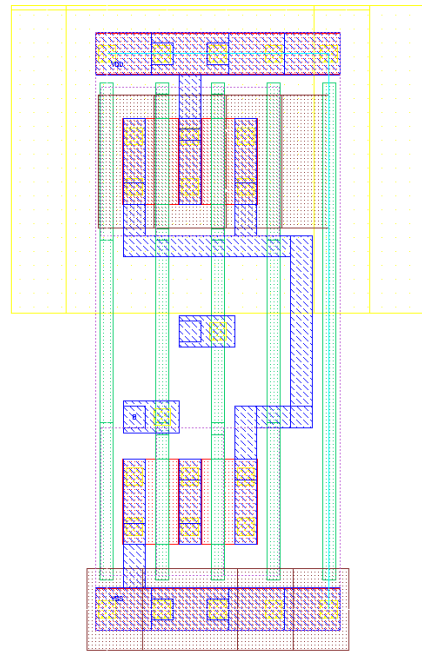
Fig. 18: Standard cell: BUFF1X1



(a) Symbol for NAND2X1

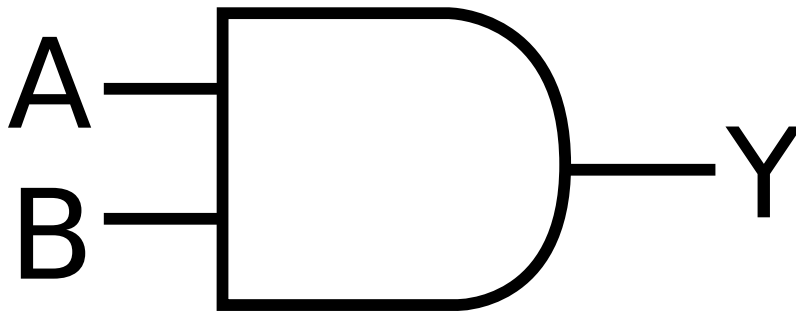


(b) Schematic of NAND2X1

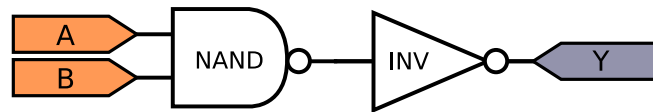


(c) Layout of NAND2X1

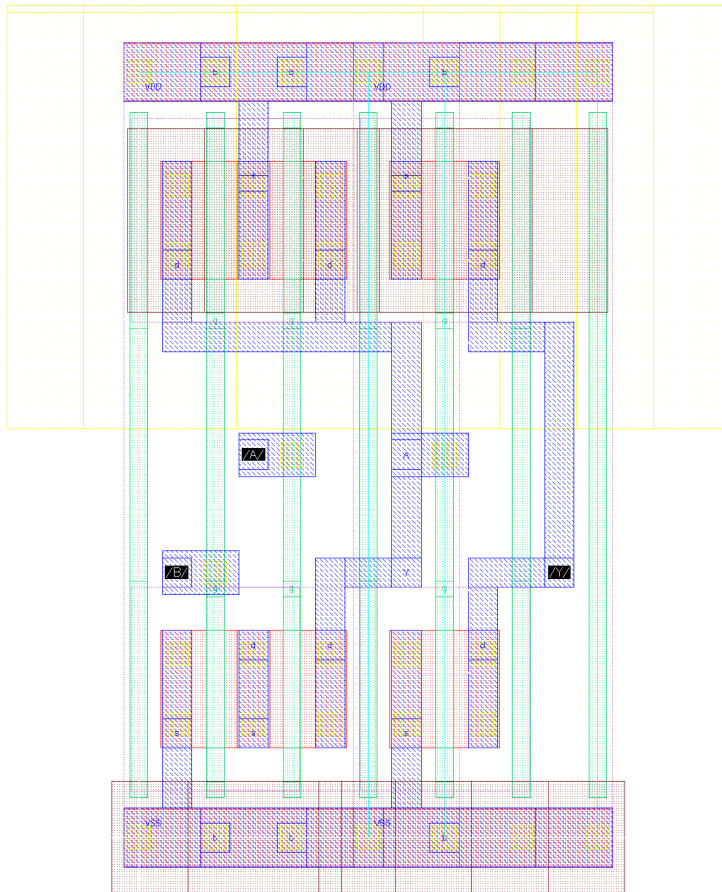
Fig. 19: Standard cell: NAND2X1



(a) Symbol for AND2X1

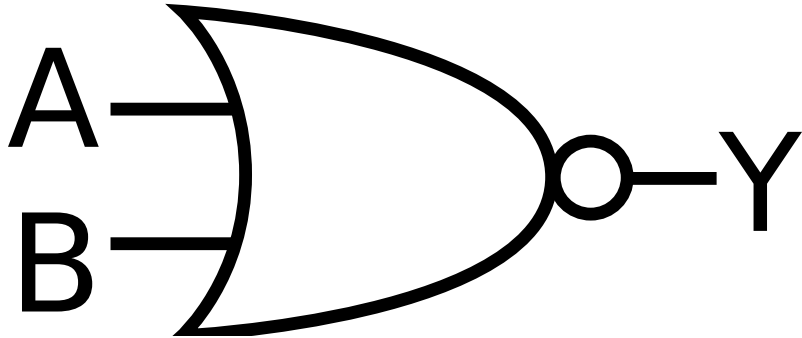


(b) Schematic of AND2X1

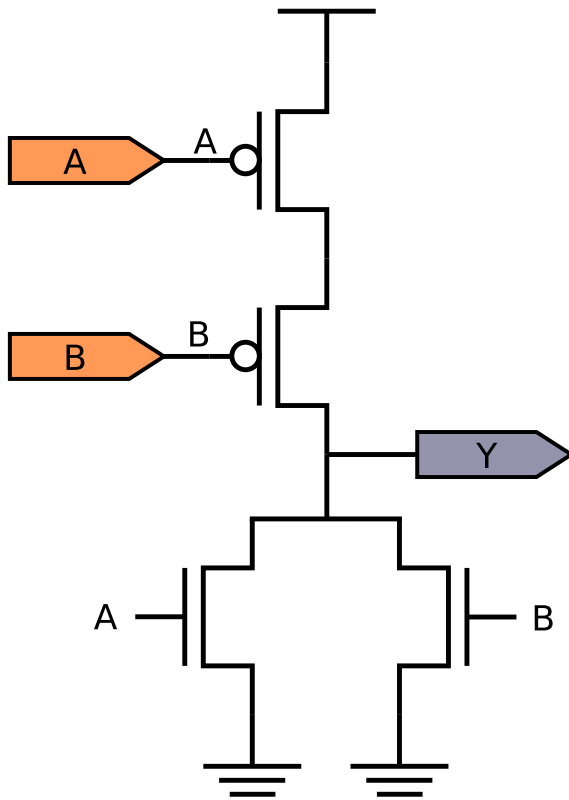


(c) Layout of AND2X1

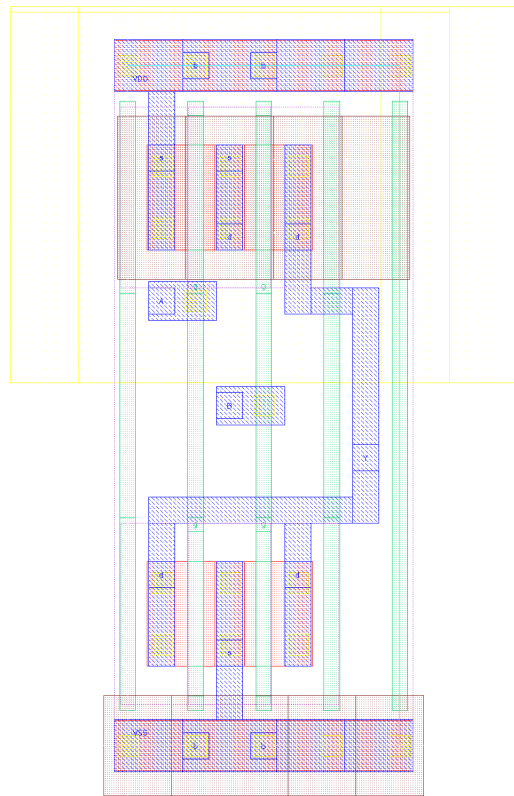
Fig. 20: Standard cell: AND2X1



(a) Symbol for NOR2X1

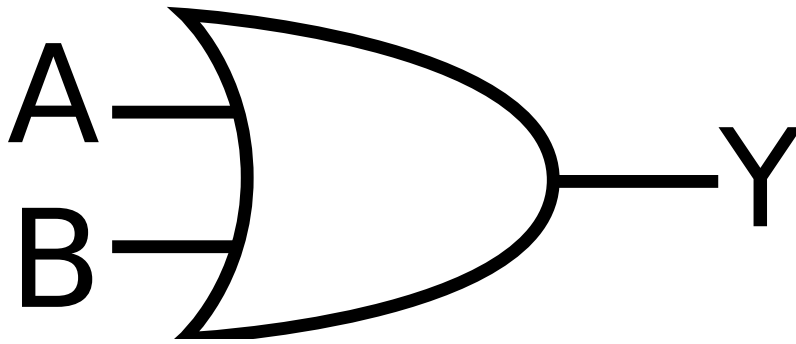


(b) Schematic of NOR2X1

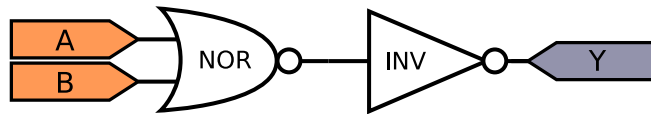


(c) Layout of NOR2X1

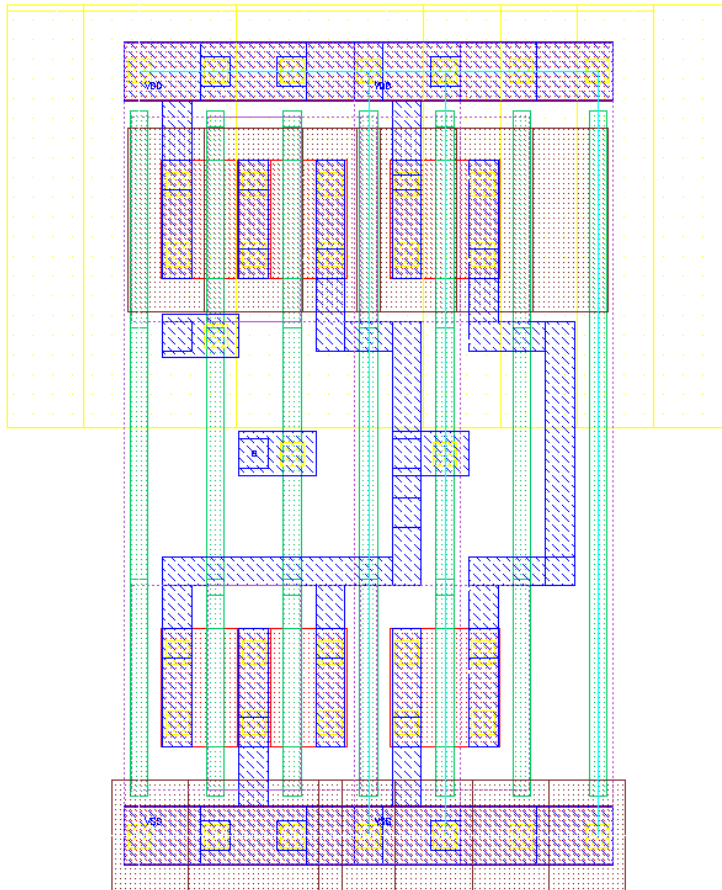
Fig. 21: Standard cell: NOR2X1



(a) Symbol for OR2X1



(b) Schematic of OR2X1



(c) Layout of OR2X1

Fig. 22: Standard cell: OR2X1

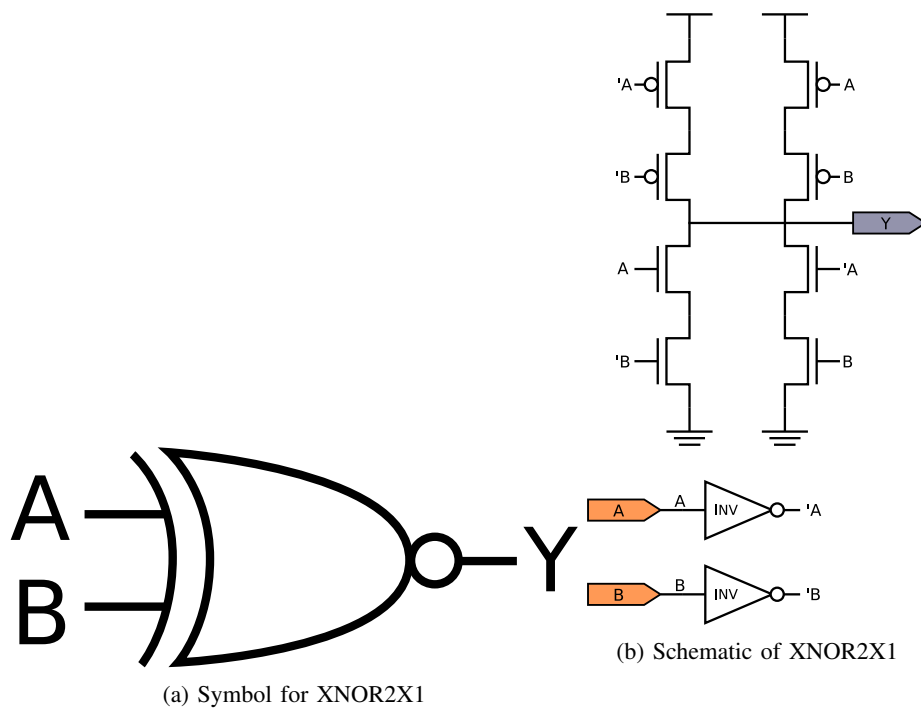
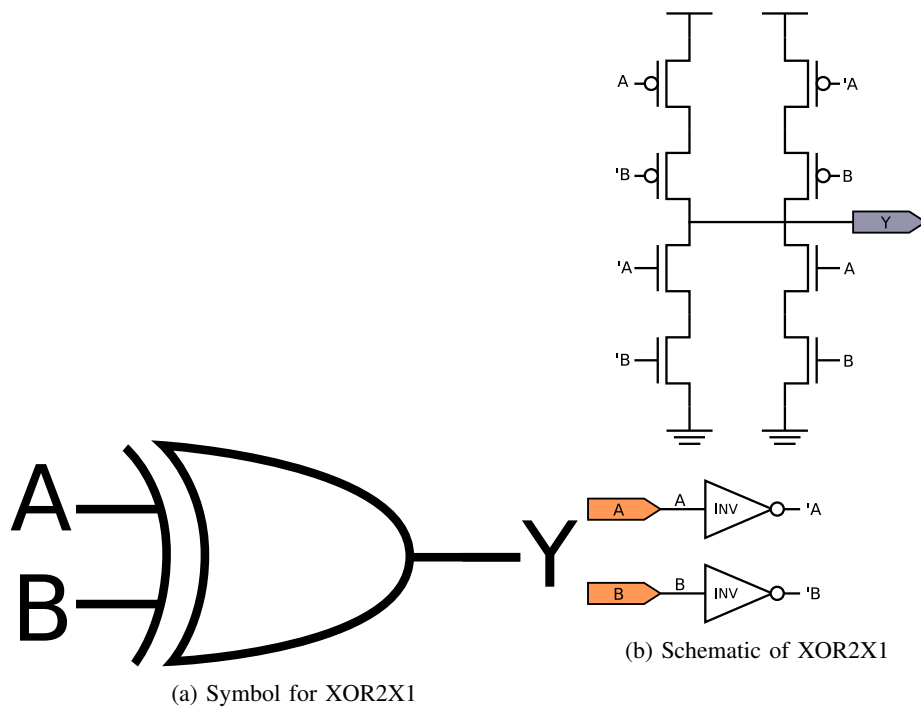
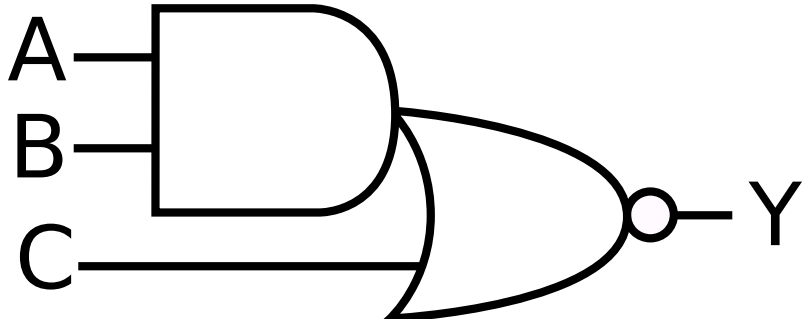


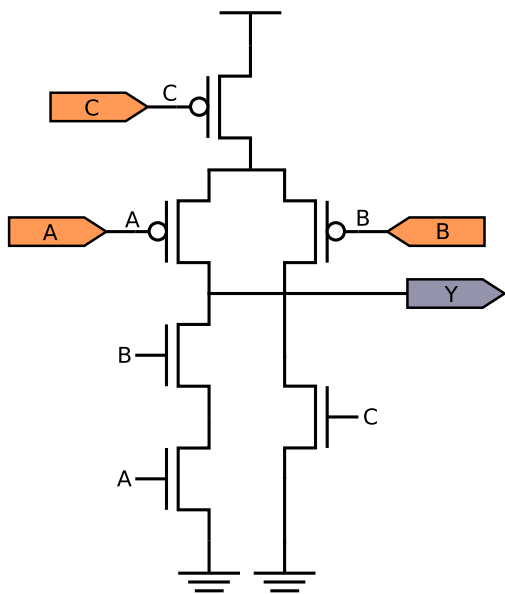
Fig. 23: Standard cell: XNOR2X1



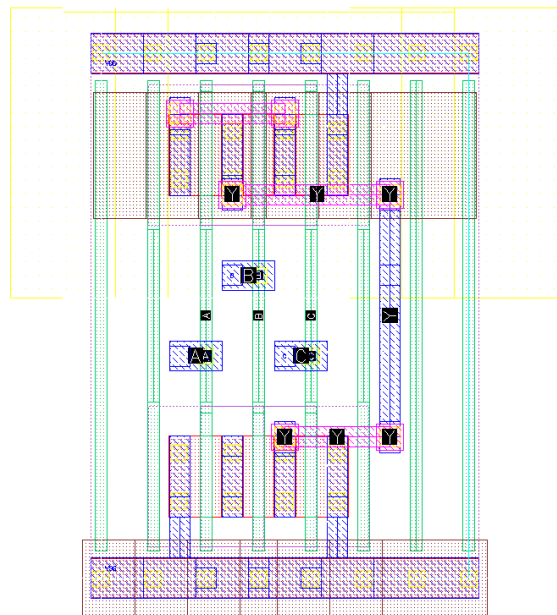
(c) Layout of XOR2X1
 Fig. 24: Standard cell: XOR2X1



(a) Symbol for AOI12X1

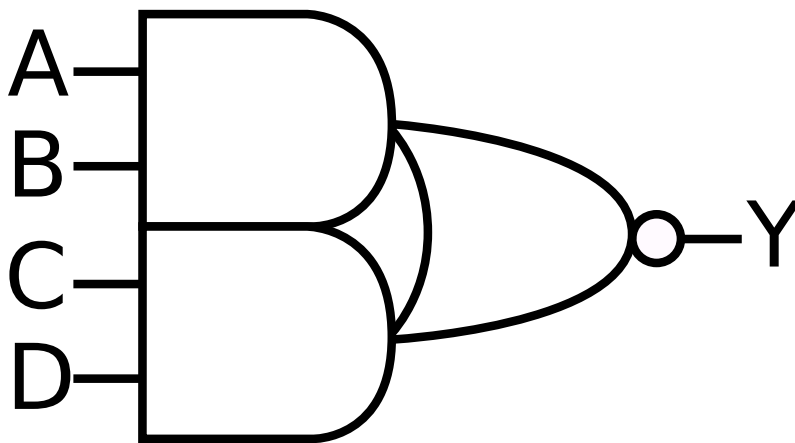


(b) Schematic of AOI12X1

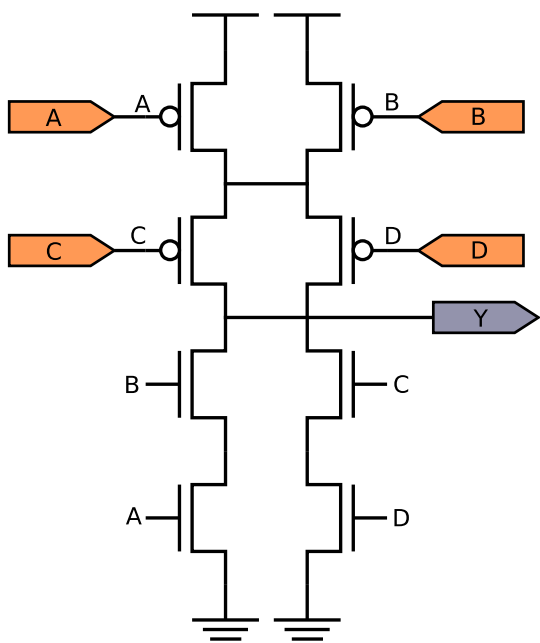


(c) Layout of AOI12X1

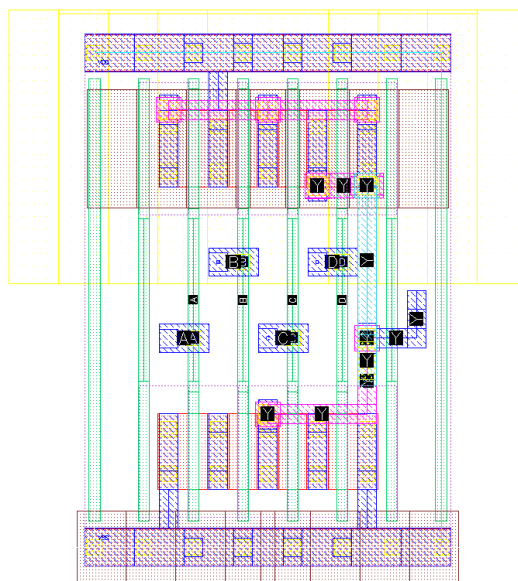
Fig. 25: Standard cell: AOI12X1



(a) Symbol for AOI22X1

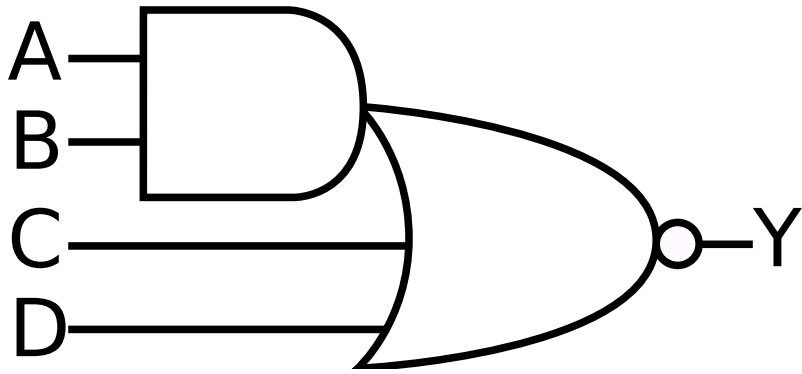


(b) Schematic of AOI22X1

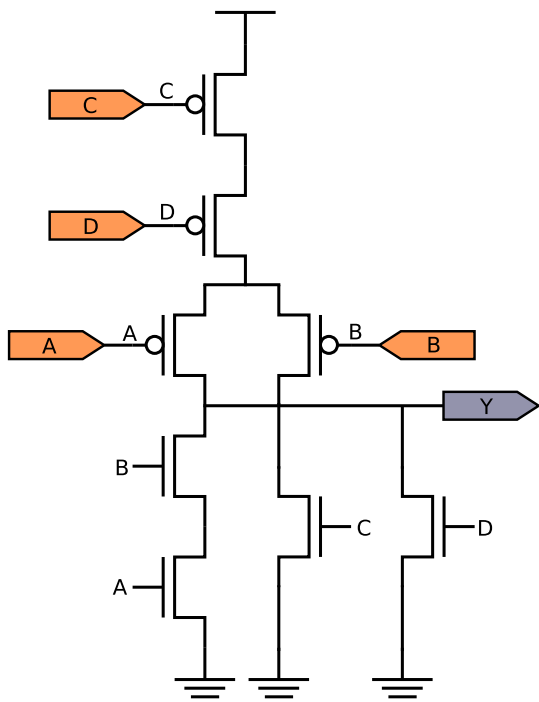


(c) Layout of AOI22X1

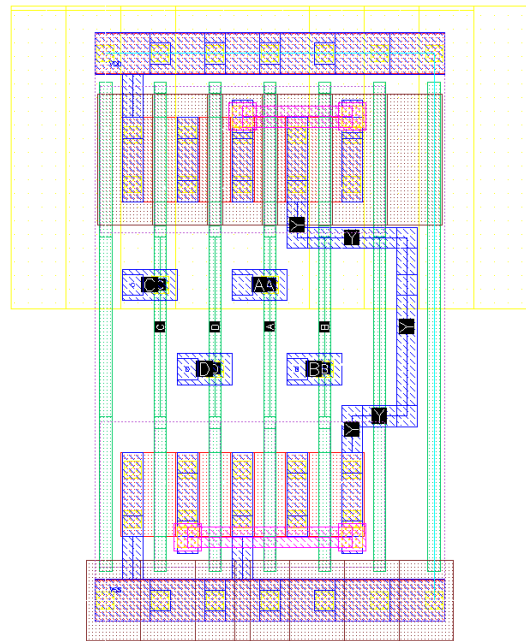
Fig. 26: Standard cell: AOI22X1



(a) Symbol for AOI112X1

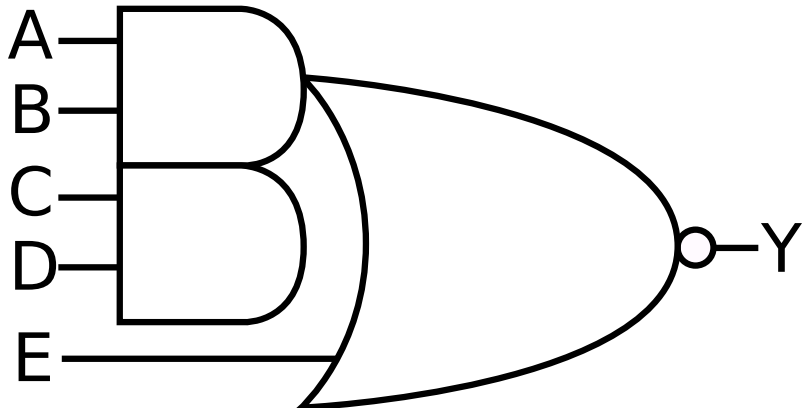


(b) Schematic of AOI112X1

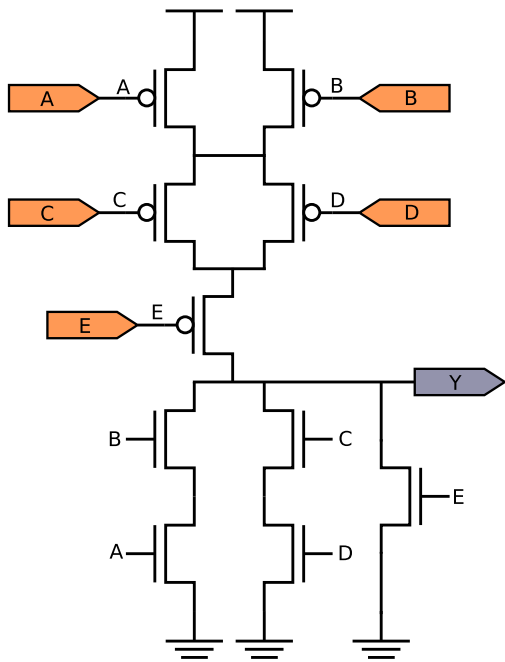


(c) Layout of AOI112X1

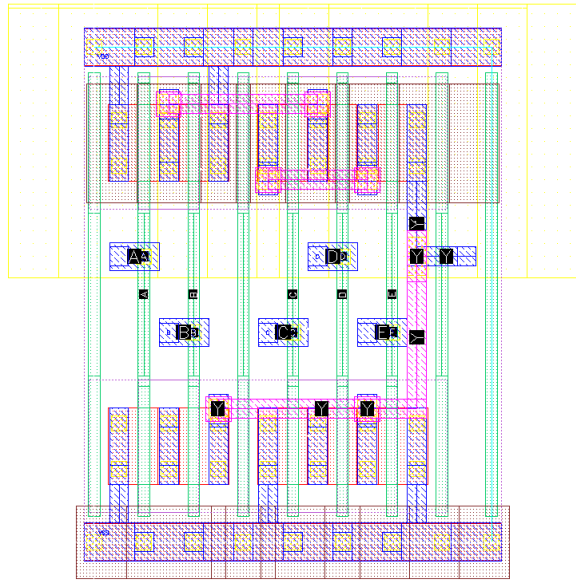
Fig. 27: Standard cell: AOI112X1



(a) Symbol for AOI212X1

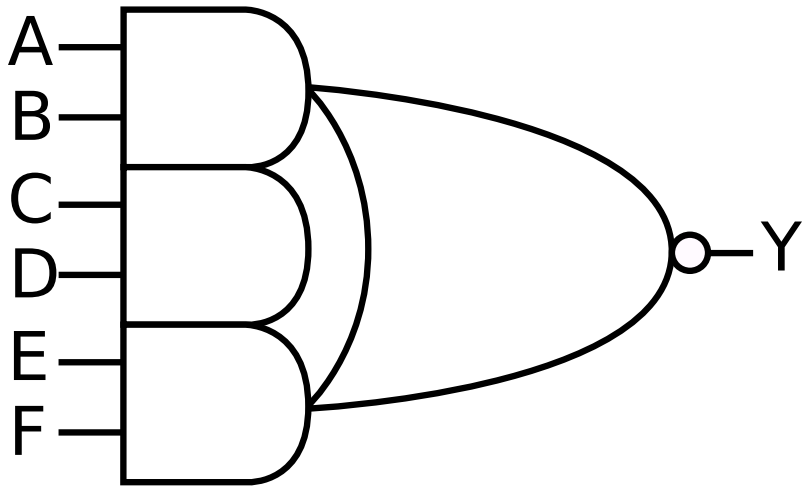


(b) Schematic of AOI212X1

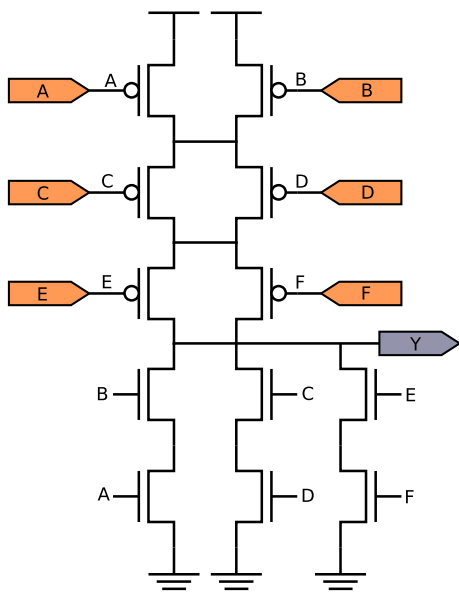


(c) Layout of AOI212X1

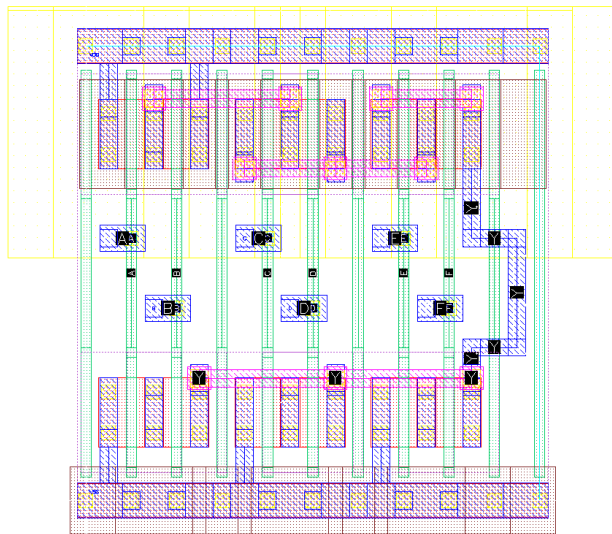
Fig. 28: Standard cell: AOI212X1



(a) Symbol for AOI222X1

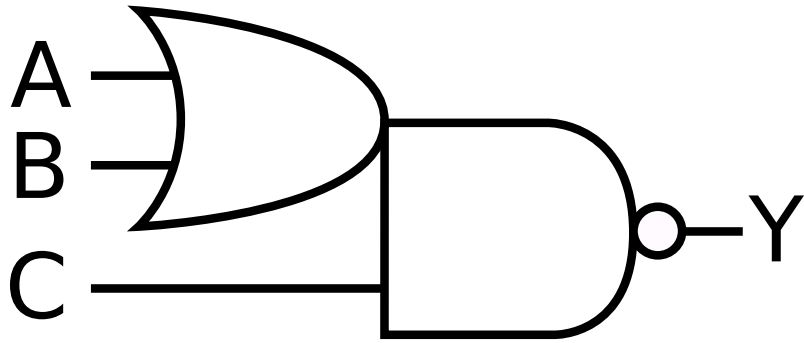


(b) Schematic of AOI222X1

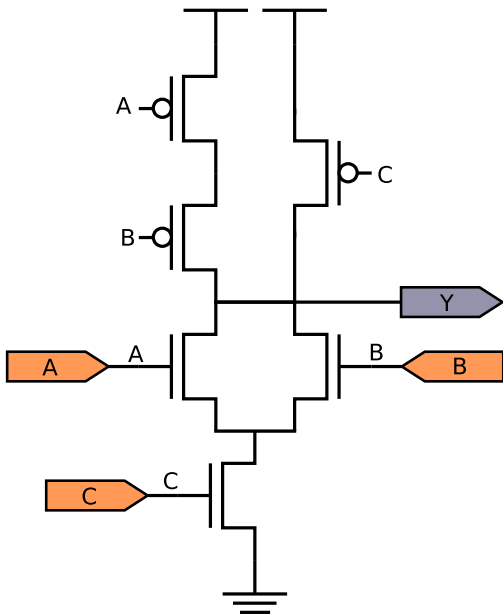


(c) Layout of AOI222X1

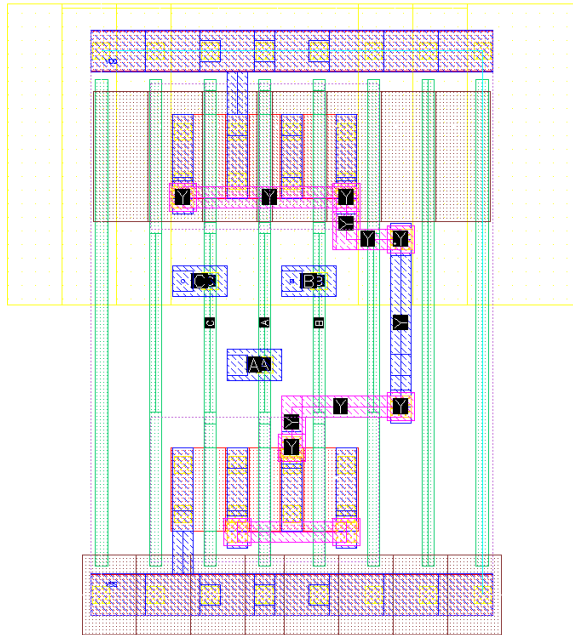
Fig. 29: Standard cell: AOI222X1



(a) Symbol for OAI12X1

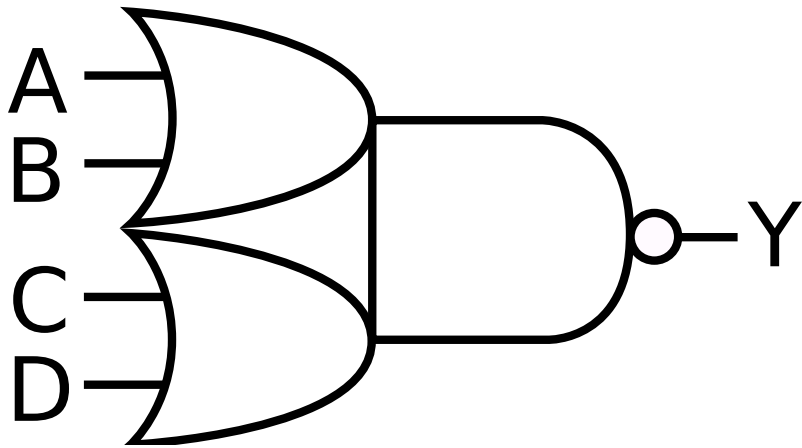


(b) Schematic of OAI12X1

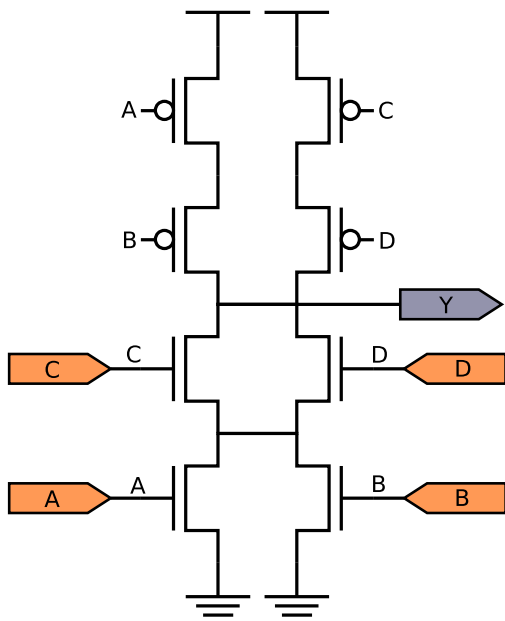


(c) Layout of OAI12X1

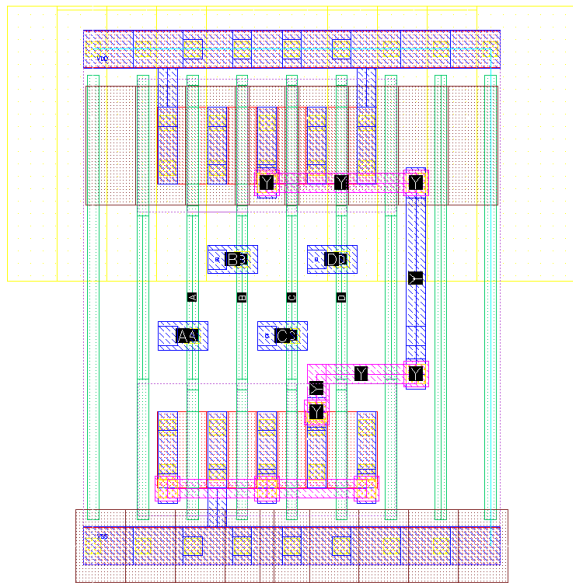
Fig. 30: Standard cell: OAI12X1



(a) Symbol for OAI22X1

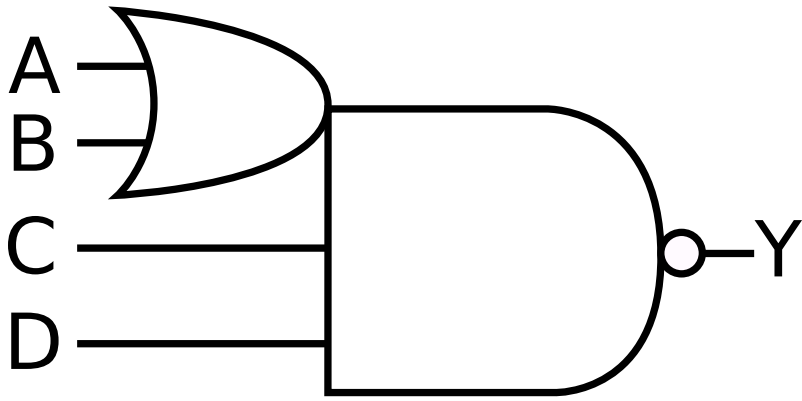


(b) Schematic of OAI22X1

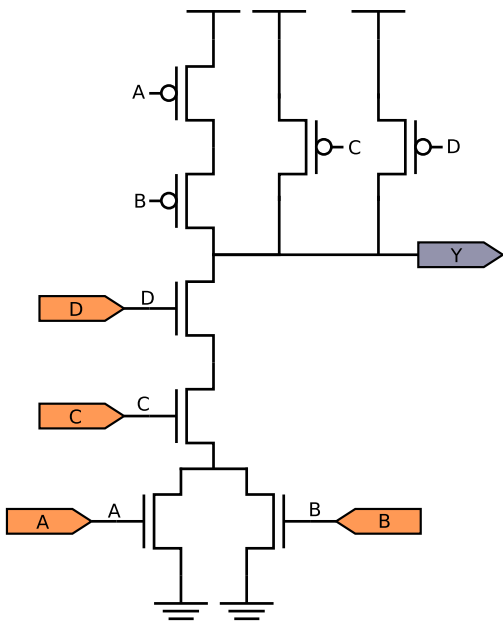


(c) Layout of OAI22X1

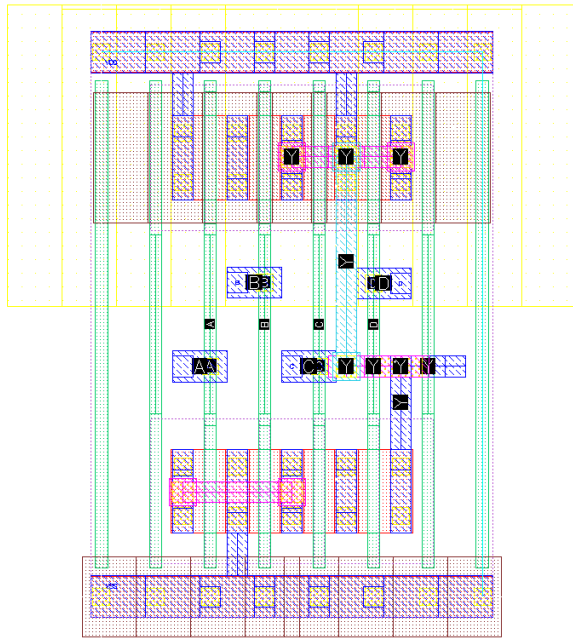
Fig. 31: Standard cell: OAI22X1



(a) Symbol for OAI211X1

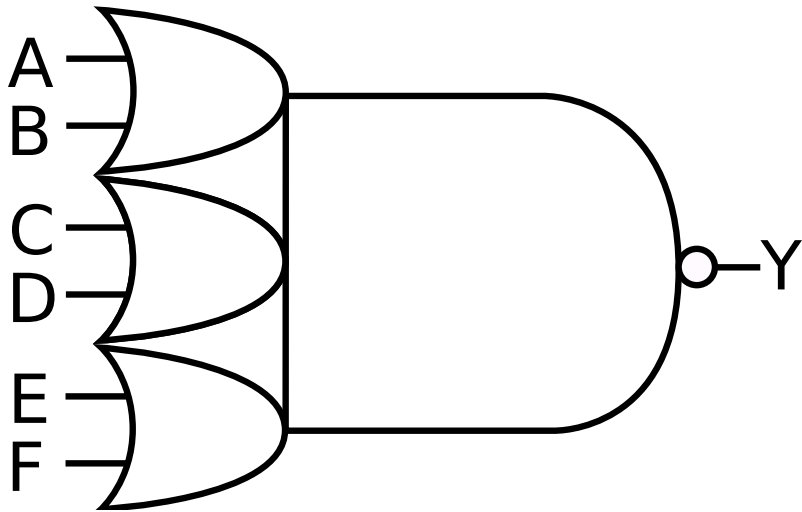


(b) Schematic of OAI211X1

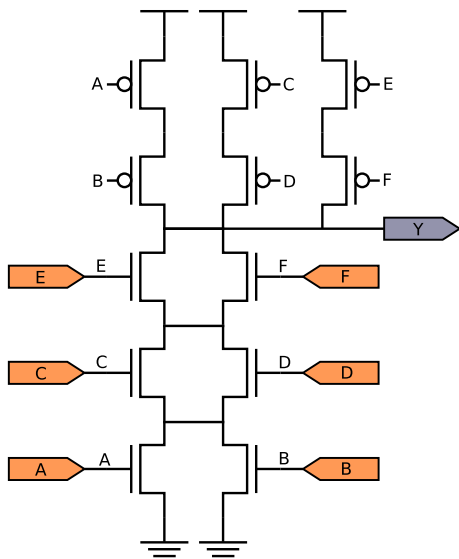


(c) Layout of OAI211X1

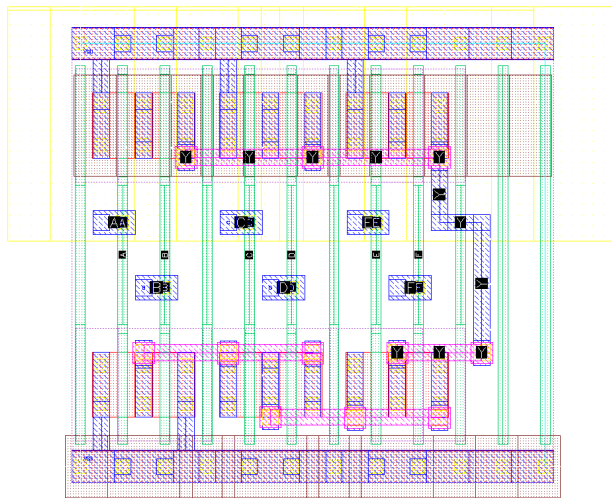
Fig. 32: Standard cell: OAI211X1



(a) Symbol for OAI222X1



(b) Schematic of OAI222X1



(c) Layout of OAI222X1

Fig. 33: Standard cell: OAI222X1

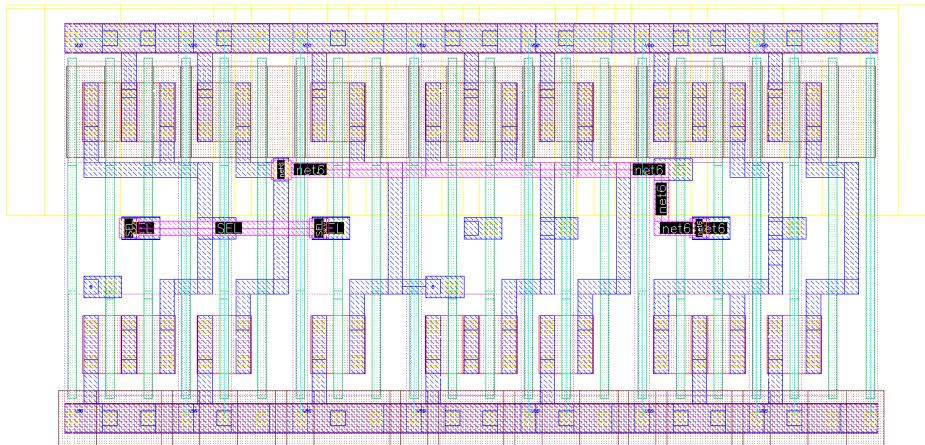
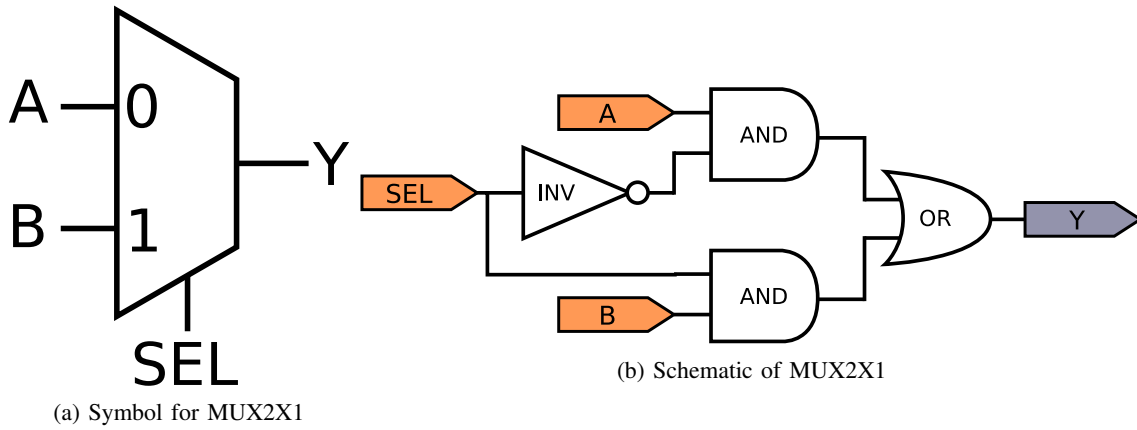
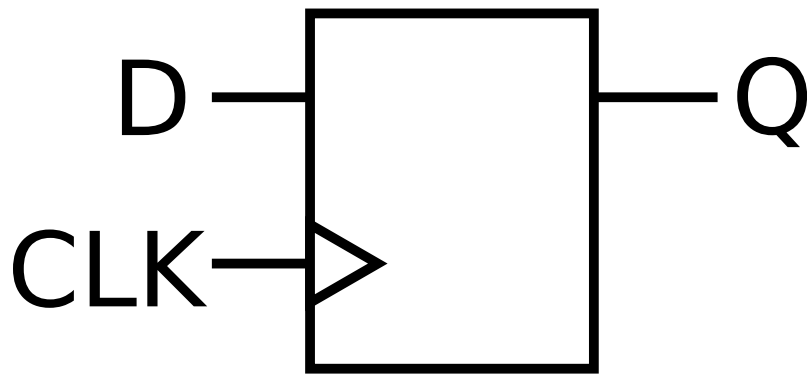
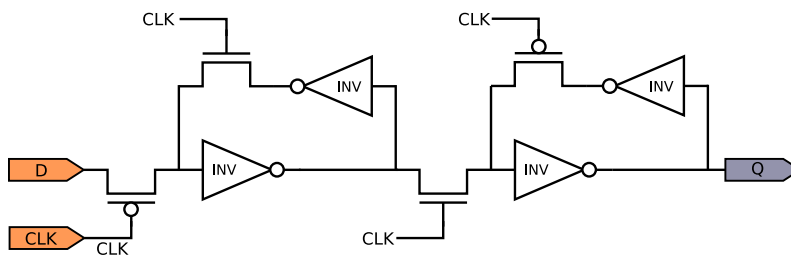


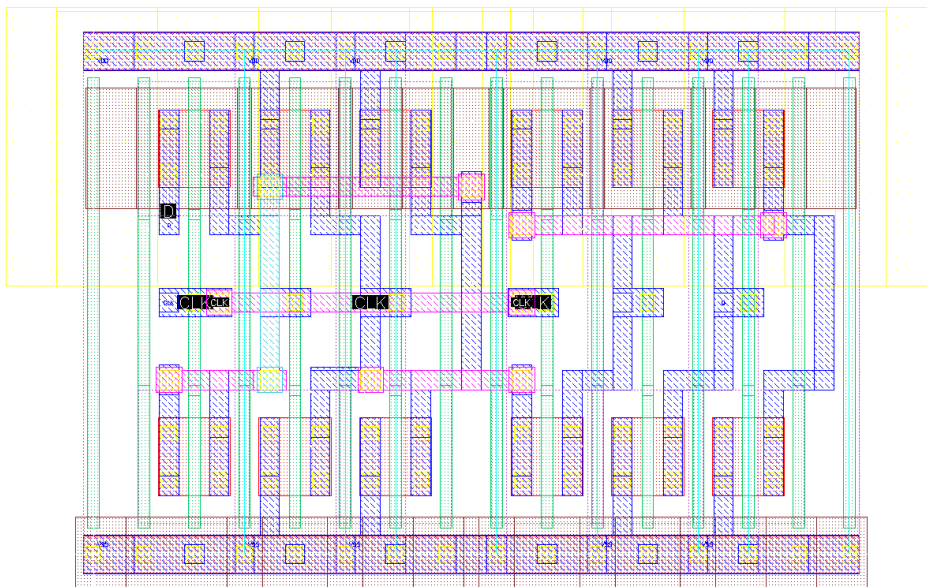
Fig. 34: Standard cell: MUX2X1



(a) Symbol for DFFX1

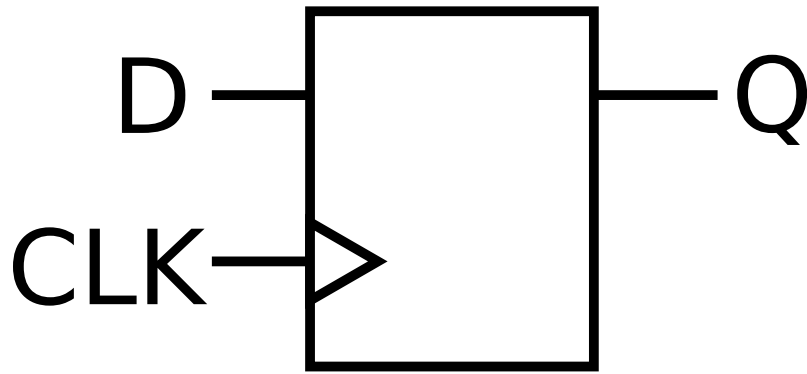


(b) Schematic of DFFX1

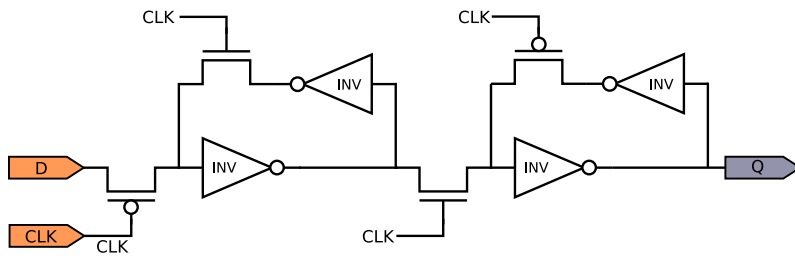


(c) Layout of DFFX1

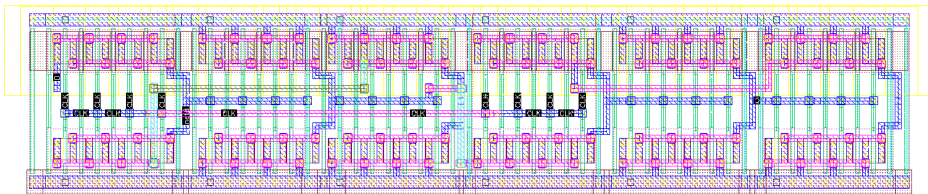
Fig. 35: Standard cell: DFFX1



(a) Symbol for DFFX4



(b) Schematic of DFFX4



(c) Layout of DFFX4

Fig. 36: Standard cell: DFFX4

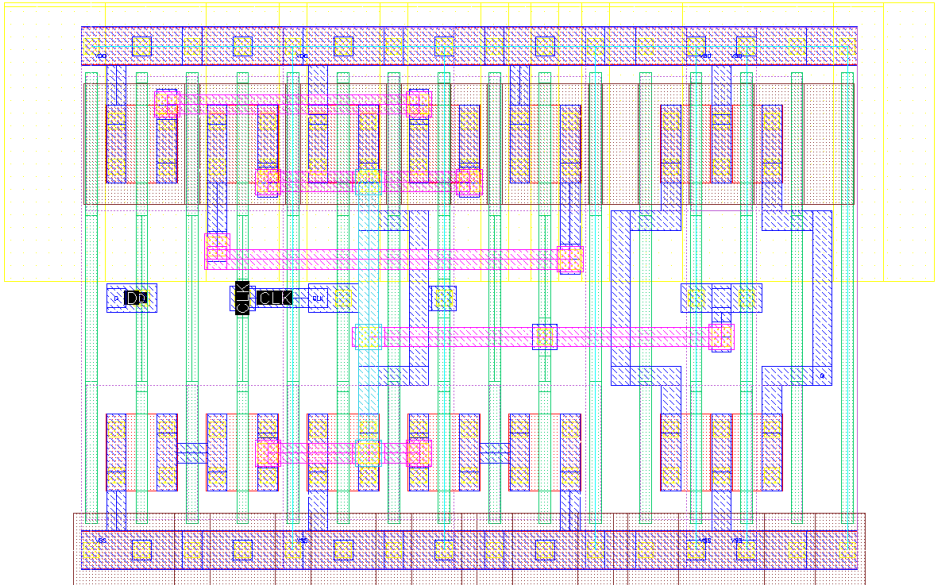
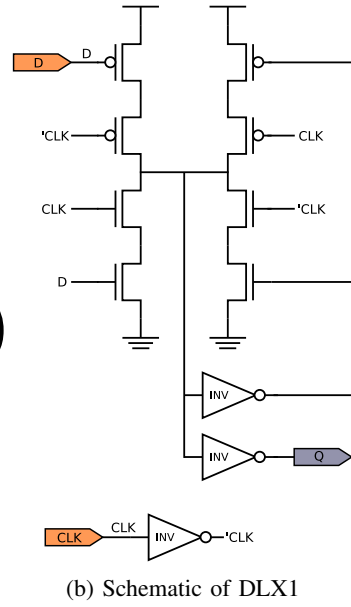
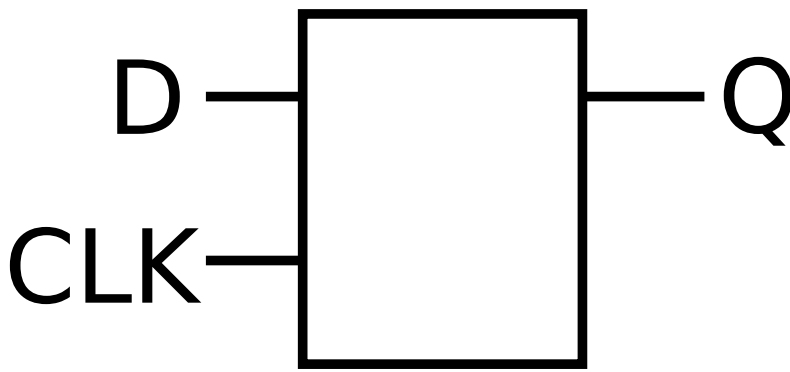
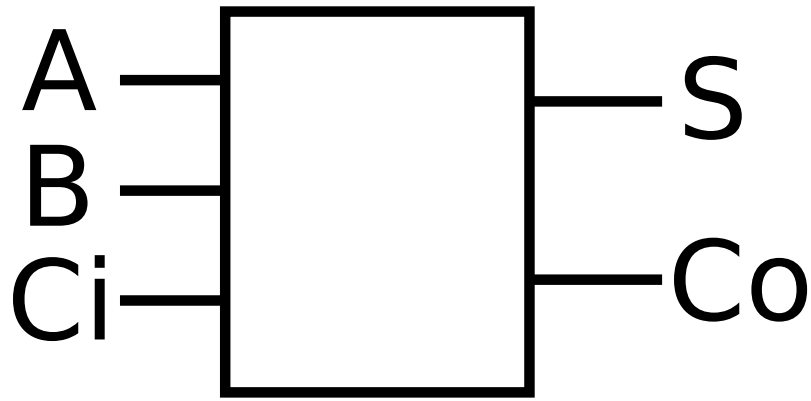
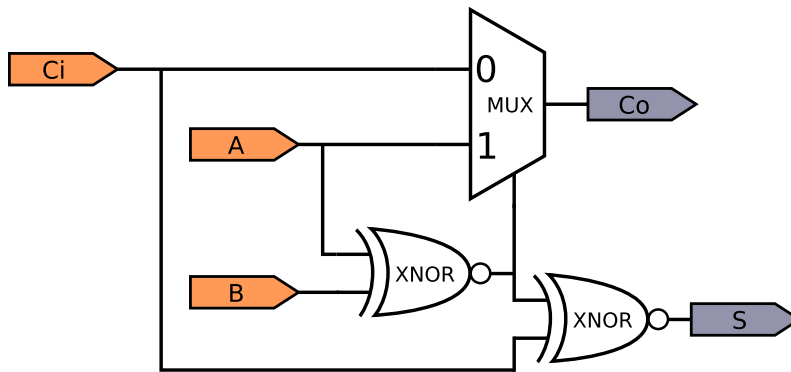


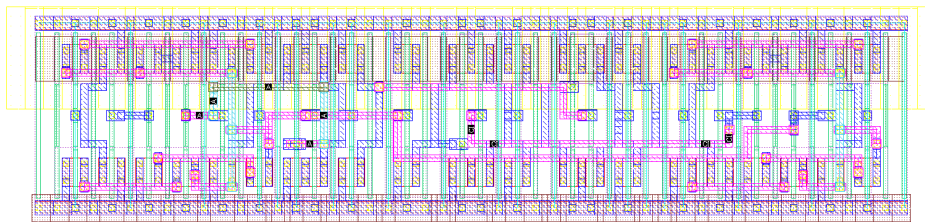
Fig. 37: Standard cell: DLX1



(a) Symbol for FAX1



(b) Schematic of FAX1



(c) Layout of FAX1

Fig. 38: Standard cell: FAX1

B. Datasheets

Cell Group INV1X1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	!A

Truth Table

Input	Output
A	Y
0	1
1	0

Footprint:

Cell	Area
INV1X1	0.0000

Leakage

Leakage (nW)			
Cell	Min	Avg	Max
INV1X1	0.0000	0.1014	0.1425

Pin Capacitance

		Pin Cap(pf)	Max Cap(pf)
Cell	A	Y	
INV1X1	0.0006	0.0050	

Delay

Delays(ns) to Y rising:

		Delay (ns)		
Cell	Timing Arc (Dir)	first	mid	last
INV1X1	A->Y(FR)	1.3528	4.1534	10.8876

Delays(ns) to Y falling:

		Delay (ns)		
Cell	Timing Arc (Dir)	first	mid	last
INV1X1	A->Y(RF)	1.1313	3.6975	10.0364

Power

Internal switching power(pJ) to Y rising:

Power (pJ)					
Cell	Input	first	mid	last	
INV1X1	A	0.0000	0.0000	0.0000	
INV1X1	A	0.0000	0.0000	0.0000	

Internal switching power(pJ) to Y falling:

Power (pJ)					
Cell	Input	first	mid	last	
INV1X1	A	0.0000	0.0000	0.0000	
INV1X1	A	0.0000	0.0000	0.0000	

END Cell Group INV1X1

Cell Group INV1X4 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	!A

Truth Table

Input	Output
A	Y
0	1
1	0

Footprint:

Cell	Area
INV1X4	0.0000

Leakage

Leakage (nW)				
Cell	Min	Avg	Max	
INV1X4	0.0000	0.4056	0.5701	

Pin Capacitance

Pin Cap(pf) Max Cap(pf)			
Cell	A	Y	
INV1X4	0.0024	0.0050	

Delay

Delays(ns) to Y rising :

Delay (ns)						
Cell	Timing	Arc(Dir)	first	mid	last	
INV1X4		A->Y(FR)	1.0398	2.8032	7.2760	

Delays(ns) to Y falling :

Delay (ns)						
Cell	Timing	Arc(Dir)	first	mid	last	
INV1X4		A->Y(RF)	0.8949	2.6590	7.1362	

Power

Internal switching power(pJ) to Y rising :

Power (pJ)					
Cell	Input	first	mid	last	
INV1X4	A	0.0001	0.0001	0.0001	
INV1X4	A	0.0000	0.0000	0.0000	

Internal switching power(pJ) to Y falling :

Power (pJ)					
Cell	Input	first	mid	last	
INV1X4	A	0.0000	0.0000	0.0000	
INV1X4	A	0.0001	0.0001	0.0001	

END Cell Group INV1X4

Cell Group BUFF1X1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	A

Truth Table

Input	Output	
A	E	Y
-	0	HiZ
0	1	0
1	1	1

Footprint :

Cell	Area
BUFF1X1	0.0000

Leakage

Leakage (nW)				
Cell	Min	Avg	Max	
BUFF1X1	0.0000	0.2371	0.3401	

Pin Capacitance

Cell	Pin Cap(pf)		Max Cap(pf)
	A	E	Y
BUFF1X1	0.0006	0.0011	0.0050

Delay

Delays (ns) to Y rising :

Cell	Timing Arc (Dir)	Delay (ns)		
		first	mid	last
BUFF1X1	A->Y(RR)	5.7565	11.2019	22.9915
BUFF1X1	E->Y(FR)	0.5549	1.2726	-0.4096
BUFF1X1	E->Y(RR)	4.2458	9.6596	21.0987

Delays (ns) to Y falling :

Cell	Timing Arc (Dir)	Delay (ns)		
		first	mid	last
BUFF1X1	A->Y(FF)	5.3539	9.5851	19.0213
BUFF1X1	E->Y(FF)	0.5467	1.2695	-0.3931
BUFF1X1	E->Y(RF)	2.0627	6.0792	14.8059

Power

Internal switching power(pJ) to Y rising :

Cell	Input	Power (pJ)		
		first	mid	last
BUFF1X1	A	0.0001	0.0001	0.0001
BUFF1X1	A	0.0001	0.0001	0.0001
BUFF1X1	E	0.0000	0.0000	0.0000
BUFF1X1	E	0.0001	0.0001	0.0001

Internal switching power(pJ) to Y falling :

Cell	Input	Power (pJ)		
		first	mid	last
BUFF1X1	A	0.0001	0.0001	0.0001
BUFF1X1	A	0.0000	0.0000	0.0000
BUFF1X1	E	0.0000	0.0000	0.0000
BUFF1X1	E	0.0001	0.0001	0.0001

Passive Power

Hidden power(pJ) for A rising:
Conditional

Power(pJ)				
Cell	first	mid	last	
BUFF1X1	0.0000	0.0000	0.0000	
BUFF1X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for A falling:
Conditional

Power(pJ)				
Cell	first	mid	last	
BUFF1X1	0.0000	0.0000	0.0000	
BUFF1X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for E rising:
Conditional

Power(pJ)				
Cell	first	mid	last	
BUFF1X1	0.0000	0.0000	0.0000	
BUFF1X1	0.0001	0.0000	0.0000	
BUFF1X1	0.0000	0.0000	0.0000	
BUFF1X1	0.0001	0.0001	0.0000	

Hidden power(pJ) for E falling:
Conditional

Power(pJ)				
Cell	first	mid	last	
BUFF1X1	0.0000	0.0000	0.0000	
BUFF1X1	-0.0000	-0.0000	-0.0000	
BUFF1X1	0.0000	0.0000	0.0000	
BUFF1X1	-0.0000	-0.0000	-0.0000	

END Cell Group BUFF1X1

Cell Group NAND2X1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	(!A) + (!B)

Truth Table

Input		Output
A	B	Y
0	x	1
1	0	1
1	1	0

Footprint:

Cell	Area
NAND2X1	0.0000

Leakage

Leakage (nW)			
Cell	Min	Avg	Max
NAND2X1	0.0000	0.1075	0.2921

Pin Capacitance

		Pin Cap(pf)		Max Cap(pf)
Cell	A	B	Y	
NAND2X1	0.0006	0.0005	0.0050	

Delay

Delays(ns) to Y rising:

		Delay (ns)		
Cell	Timing Arc(Dir)	first	mid	last
NAND2X1	A->Y(FR)	1.5354	4.2866	10.9284
NAND2X1	B->Y(FR)	1.6203	4.3860	11.0435

Delays(ns) to Y falling:

		Delay (ns)		
Cell	Timing Arc(Dir)	first	mid	last
NAND2X1	A->Y(RF)	2.9155	6.7847	15.5451
NAND2X1	B->Y(RF)	3.0773	7.3031	16.6388

Power

Internal switching power(pJ) to Y rising:

		Power (pJ)		
Cell	Input	first	mid	last
NAND2X1	A	0.0000	0.0000	0.0000
NAND2X1	A	0.0000	0.0000	0.0000
NAND2X1	B	0.0000	0.0000	0.0000
NAND2X1	B	0.0000	0.0000	0.0000

Internal switching power(pJ) to Y falling :

		Power(pJ)			
Cell	Input	first	mid	last	
NAND2X1	A	0.0000	0.0000	0.0000	
NAND2X1	A	0.0000	0.0000	0.0000	
NAND2X1	B	0.0000	0.0000	0.0000	
NAND2X1	B	0.0001	0.0001	0.0000	

Passive Power

Hidden power(pJ) for A rising :
Conditional

		Power(pJ)		
Cell		first	mid	last
NAND2X1		-0.0000	-0.0000	-0.0000
NAND2X1		0.0000	0.0000	0.0000

Hidden power(pJ) for A falling :
Conditional

		Power(pJ)		
Cell		first	mid	last
NAND2X1		0.0000	0.0000	0.0000
NAND2X1		-0.0000	-0.0000	-0.0000

Hidden power(pJ) for B rising :
Conditional

		Power(pJ)		
Cell		first	mid	last
NAND2X1		-0.0000	-0.0000	-0.0000
NAND2X1		0.0000	0.0000	0.0000

Hidden power(pJ) for B falling :
Conditional

		Power(pJ)		
Cell		first	mid	last
NAND2X1		0.0000	0.0000	0.0000
NAND2X1		-0.0000	-0.0000	-0.0000

END Cell Group NAND2X1

Cell Group AND2X1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	(A * B)

Truth Table

Input		Output
A	B	Y
0	x	0
1	0	0
1	1	1

Footprint:

Cell	Area
AND2X1	0.0000

Leakage

Leakage (nW)			
Cell	Min	Avg	Max
AND2X1	0.0000	0.2298	0.3532

Pin Capacitance

		Pin Cap(pf)	Max Cap(pf)
Cell	A	B	Y
AND2X1	0.0006	0.0005	0.0050

Delay

Delays(ns) to Y rising:

		Delay (ns)		
Cell	Timing Arc (Dir)	first	mid	last
AND2X1	A->Y(RR)	6.1860	8.8850	15.0894
AND2X1	B->Y(RR)	6.3587	9.4090	16.0261

Delays(ns) to Y falling:

		Delay (ns)		
Cell	Timing Arc (Dir)	first	mid	last
AND2X1	A->Y(FF)	4.0482	6.6574	12.7442
AND2X1	B->Y(FF)	4.2390	6.8654	12.9879

Power

Internal switching power(pJ) to Y rising:

		Power(pJ)		
Cell	Input	first	mid	last
AND2X1	A	0.0000	0.0000	0.0000
AND2X1	A	0.0001	0.0001	0.0001
AND2X1	B	0.0000	0.0000	0.0000
AND2X1	B	0.0001	0.0001	0.0001

Internal switching power(pJ) to Y falling:

		Power(pJ)		
Cell	Input	first	mid	last
AND2X1	A	0.0001	0.0001	0.0001
AND2X1	A	0.0000	0.0000	0.0000
AND2X1	B	0.0001	0.0001	0.0001
AND2X1	B	0.0000	0.0000	0.0000

Passive Power

Hidden power(pJ) for A rising:

Conditional

		Power(pJ)		
Cell		first	mid	last
AND2X1		-0.0000	-0.0000	-0.0000
AND2X1		0.0000	0.0000	0.0000

Hidden power(pJ) for A falling:

Conditional

		Power(pJ)		
Cell		first	mid	last
AND2X1		0.0000	0.0000	0.0000
AND2X1		-0.0000	-0.0000	-0.0000

Hidden power(pJ) for B rising:

Conditional

		Power(pJ)		
Cell		first	mid	last
AND2X1		-0.0000	-0.0000	-0.0000
AND2X1		0.0000	0.0000	0.0000

Hidden power(pJ) for B falling:
Conditional

Power(pJ)			
Cell	first	mid	last
AND2X1	0.0000	0.0000	0.0000
AND2X1	-0.0000	-0.0000	-0.0000

END Cell Group AND2X1

Cell Group NOR2X1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	(!A * !B)

Truth Table

Input			Output
A	B	Y	
0	0	1	
x	1	0	
1	x	0	

Footprint:

Cell	Area
NOR2X1	0.0000

Leakage

Leakage (nW)			
Cell	Min	Avg	Max
NOR2X1	0.0000	0.1085	0.1454

Pin Capacitance

Pin Cap(pf)		Max Cap(pf)	
Cell	A	B	Y
NOR2X1	0.0005	0.0006	0.0050

Delay

Delays(ns) to Y rising :

Delay (ns)					
Cell	Timing Arc(Dir)	first	mid	last	
NOR2X1	A->Y(FR)	4.1164	9.3631	20.6254	
NOR2X1	B->Y(FR)	3.9472	8.7277	19.2154	

Delays(ns) to Y falling :

		Delay (ns)		
Cell	Timing Arc(Dir)	first	mid	last
NOR2X1	A->Y(RF)	1.3138	3.8473	10.1108
NOR2X1	B->Y(RF)	1.2671	3.7879	10.0417

Power

Internal switching power(pJ) to Y rising :

		Power (pJ)		
Cell	Input	first	mid	last
NOR2X1	A	0.0000	0.0000	0.0000
NOR2X1	A	0.0000	0.0000	0.0000
NOR2X1	B	0.0000	0.0000	0.0000
NOR2X1	B	0.0000	0.0000	0.0000

Internal switching power(pJ) to Y falling :

		Power (pJ)		
Cell	Input	first	mid	last
NOR2X1	A	0.0000	0.0000	0.0000
NOR2X1	A	0.0000	0.0000	0.0000
NOR2X1	B	0.0000	0.0000	0.0000
NOR2X1	B	0.0000	0.0000	0.0000

Passive Power

Hidden power(pJ) for A rising :

Conditional

		Power (pJ)		
Cell		first	mid	last
NOR2X1		-0.0000	-0.0000	-0.0000
NOR2X1		0.0000	0.0000	0.0000

Hidden power(pJ) for A falling :

Conditional

		Power (pJ)		
Cell		first	mid	last
NOR2X1		0.0000	0.0000	0.0000
NOR2X1		-0.0000	-0.0000	-0.0000

Hidden power(pJ) for B rising :

Conditional

		Power (pJ)		
Cell		first	mid	last
NOR2X1		-0.0000	-0.0000	-0.0000
NOR2X1		0.0000	0.0000	0.0000

Hidden power(pJ) for B falling:
Conditional

Power (pJ)				
Cell	first	mid	last	
NOR2X1	0.0000	0.0000	0.0000	
NOR2X1	-0.0000	-0.0000	-0.0000	

END Cell Group NOR2X1

Cell Group OR2X1 from Library 28nm_slvt, Process corner, Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	(A) + (B)

Truth Table

Input			Output
A	B	Y	
0	0	0	
x	1	1	
1	x	1	

Footprint:

Cell	Area
OR2X1	0.0000

Leakage

Leakage (nW)				
Cell	Min	Avg	Max	
OR2X1	0.0000	0.1897	0.2686	

Pin Capacitance

Cell	Pin Cap(pf)		Max Cap(pf)
	A	B	Y
OR2X1	0.0005	0.0006	0.0050

Delay

Delays(ns) to Y rising:

Delay (ns)						
Cell	Timing Arc (Dir)	first	mid	last		
OR2X1	A->Y(RR)	3.6169	6.5607	13.4596		
OR2X1	B->Y(RR)	3.4894	6.4135	13.2651		

Delays(ns) to Y falling :

		Delay (ns)		
Cell	Timing Arc (Dir)	first	mid	last
OR2X1	A->Y(FF)	8.0744	10.9812	16.8192
OR2X1	B->Y(FF)	7.8967	10.3387	15.6313

Power

Internal switching power(pJ) to Y rising :

		Power (pJ)		
Cell	Input	first	mid	last
OR2X1	A	0.0000	0.0000	0.0000
OR2X1	A	0.0001	0.0001	0.0001
OR2X1	B	0.0000	0.0000	0.0000
OR2X1	B	0.0001	0.0001	0.0001

Internal switching power(pJ) to Y falling :

		Power (pJ)		
Cell	Input	first	mid	last
OR2X1	A	0.0001	0.0001	0.0001
OR2X1	A	0.0000	0.0000	0.0000
OR2X1	B	0.0001	0.0001	0.0001
OR2X1	B	0.0000	0.0000	0.0000

Passive Power

Hidden power(pJ) for A rising :
Conditional

		Power (pJ)		
Cell		first	mid	last
OR2X1		-0.0000	-0.0000	-0.0000
OR2X1		0.0000	0.0000	0.0000

Hidden power(pJ) for A falling :
Conditional

		Power (pJ)		
Cell		first	mid	last
OR2X1		0.0000	0.0000	0.0000
OR2X1		-0.0000	-0.0000	-0.0000

Hidden power(pJ) for B rising:
Conditional

Power (pJ)				
Cell	first	mid	last	
OR2X1	-0.0000	-0.0000	-0.0000	
OR2X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for B falling:
Conditional

Power (pJ)				
Cell	first	mid	last	
OR2X1	0.0000	0.0000	0.0000	
OR2X1	-0.0000	-0.0000	-0.0000	

END Cell Group OR2X1

Cell Group XNOR2X1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	$(A * B) + (!A * !B)$

Truth Table

Input			Output
A	B	Y	
0	0	1	
0	1	0	
1	0	0	
1	1	1	

Footprint:

Cell	Area
XNOR2X1	0.0000

Leakage

Leakage (nW)				
Cell	Min	Avg	Max	
XNOR2X1	0.0000	0.3884	0.4609	

Pin Capacitance

Pin Cap(pf)		Max Cap(pf)		
Cell	A	B	Y	
XNOR2X1	0.0011	0.0011	0.0050	

Delay

Delays(ns) to Y rising :
Conditional

		Delay (ns)					
Cell	Timing	Arc (Dir)	first	mid	last	when	
XNOR2X1		A->Y(RR)	8.2437	13.8784	25.9048	B	
XNOR2X1		A->Y(FR)	4.9675	10.3716	21.8947	!B	
XNOR2X1		B->Y(RR)	7.6727	13.2511	24.9355	A	
XNOR2X1		B->Y(FR)	5.3475	10.3129	21.0232	!A	

Delays(ns) to Y falling :
Conditional

		Delay (ns)					
Cell	Timing	Arc (Dir)	first	mid	last	when	
XNOR2X1		A->Y(FF)	6.5591	10.9216	20.3828	B	
XNOR2X1		A->Y(RF)	3.7500	7.7815	16.7604	!B	
XNOR2X1		B->Y(FF)	7.0130	11.3704	21.0145	A	
XNOR2X1		B->Y(RF)	4.1229	8.5086	18.1800	!A	

Power

Internal switching power(pJ) to Y rising :
Conditional

		Power (pJ)					
Cell	Input		first	mid	last	when	
XNOR2X1	A		0.0001	0.0001	0.0001	B	
XNOR2X1	A		0.0001	0.0001	0.0001	B	
XNOR2X1	A		0.0001	0.0001	0.0001	!B	
XNOR2X1	A		0.0000	0.0000	0.0000	!B	
XNOR2X1	B		0.0001	0.0001	0.0001	A	
XNOR2X1	B		0.0001	0.0001	0.0001	A	
XNOR2X1	B		0.0001	0.0001	0.0001	!A	
XNOR2X1	B		0.0000	0.0000	0.0000	!A	

Internal switching power(pJ) to Y falling :
Conditional

		Power (pJ)					
Cell	Input		first	mid	last	when	
XNOR2X1	A		0.0001	0.0001	0.0001	B	
XNOR2X1	A		0.0001	0.0001	0.0001	B	
XNOR2X1	A		0.0000	0.0000	0.0000	!B	
XNOR2X1	A		0.0001	0.0001	0.0001	!B	
XNOR2X1	B		0.0001	0.0001	0.0001	A	
XNOR2X1	B		0.0001	0.0001	0.0001	A	
XNOR2X1	B		0.0001	0.0001	0.0000	!A	
XNOR2X1	B		0.0001	0.0001	0.0001	!A	

END Cell Group XNOR2X1

Cell Group XOR2X1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	$(A * !B) + (!A * B)$

Truth Table

Input		Output
A	B	Y
0	0	0
0	1	1
1	0	1
1	1	0

Footprint:

Cell	Area
XOR2X1	0.0000

Leakage

Leakage (nW)			
Cell	Min	Avg	Max
XOR2X1	0.0000	0.3884	0.5429

Pin Capacitance

		Pin Cap(pf)		Max Cap(pf)
Cell	A	B	Y	
XOR2X1	0.0011	0.0013	0.0050	

Delay

Delays(ns) to Y rising :

Conditional

		Delay (ns)				
Cell	Timing Arc (Dir)	first	mid	last	when	
XOR2X1	A->Y(RR)	8.0407	13.5796	25.5246	!B	
XOR2X1	A->Y(FR)	5.9006	11.3175	22.9153	B	
XOR2X1	B->Y(RR)	7.8593	13.4267	25.0866	!A	
XOR2X1	B->Y(FR)	5.5975	10.5309	21.2164	A	

Delays(ns) to Y falling :

Conditional

		Delay (ns)				
Cell	Timing Arc (Dir)	first	mid	last	when	
XOR2X1	A->Y(FF)	6.6895	11.0672	20.5456	!B	
XOR2X1	A->Y(RF)	4.0980	8.1460	17.1547	B	
XOR2X1	B->Y(FF)	7.4502	11.8762	21.5616	!A	
XOR2X1	B->Y(RF)	4.1543	8.5651	18.2118	A	

Power

Internal switching power(pJ) to Y rising:
Conditional

		Power (pJ)				
Cell	Input	first	mid	last	when	
XOR2X1	A	0.0001	0.0001	0.0001	B	
XOR2X1	A	0.0001	0.0001	0.0001	B	
XOR2X1	A	0.0001	0.0001	0.0001	!B	
XOR2X1	A	0.0001	0.0001	0.0001	!B	
XOR2X1	B	0.0001	0.0001	0.0001	A	
XOR2X1	B	0.0000	0.0000	0.0000	A	
XOR2X1	B	0.0001	0.0001	0.0001	!A	
XOR2X1	B	0.0001	0.0001	0.0001	!A	

Internal switching power(pJ) to Y falling:
Conditional

		Power (pJ)				
Cell	Input	first	mid	last	when	
XOR2X1	A	0.0001	0.0000	0.0000	B	
XOR2X1	A	0.0001	0.0001	0.0001	B	
XOR2X1	A	0.0001	0.0001	0.0001	!B	
XOR2X1	A	0.0001	0.0001	0.0001	!B	
XOR2X1	B	0.0000	0.0000	0.0000	A	
XOR2X1	B	0.0001	0.0001	0.0001	A	
XOR2X1	B	0.0001	0.0001	0.0001	!A	
XOR2X1	B	0.0001	0.0001	0.0001	!A	

END Cell Group XOR2X1

Cell Group AOI12X1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	(!A * !C) + (!B * !C)

Truth Table

Input			Output
A	B	C	Y
0	x	0	1
x	x	1	0
1	0	0	1
1	1	x	0

Footprint:

Cell	Area
AOI12X1	0.0000

Leakage

Leakage (nW)			
Cell	Min	Avg	Max
AOI12X1	0.0000	0.1311	0.2930

Pin Capacitance

Cell	Pin Cap(pf)			Max Cap(pf)
	A	B	C	Y
AOI12X1	0.0005	0.0005	0.0005	0.0050

Delay

Delays(ns) to Y rising :

Cell	Timing Arc(Dir)	Delay (ns)		
		first	mid	last
AOI12X1	A->Y(FR)	4.1845	8.9820	19.4185
AOI12X1	B->Y(FR)	3.8102	8.5469	18.8650
AOI12X1	C->Y(FR)	4.8707	10.1665	21.5289

Delays(ns) to Y falling :

Cell	Timing Arc(Dir)	Delay (ns)		
		first	mid	last
AOI12X1	A->Y(RF)	3.0151	7.1594	16.3249
AOI12X1	B->Y(RF)	2.8414	6.6328	15.2112
AOI12X1	C->Y(RF)	1.3865	3.9303	10.1670

Power

Internal switching power(pJ) to Y rising :

Cell	Input	Power (pJ)		
		first	mid	last
AOI12X1	A	0.0000	0.0000	0.0000
AOI12X1	A	0.0000	0.0000	0.0000
AOI12X1	B	0.0000	0.0000	0.0000
AOI12X1	B	0.0000	0.0000	0.0000
AOI12X1	C	0.0001	0.0001	0.0001
AOI12X1	C	0.0000	0.0000	0.0000

Internal switching power(pJ) to Y falling :

Cell	Input	Power (pJ)		
		first	mid	last
AOI12X1	A	0.0000	0.0000	0.0000
AOI12X1	A	0.0001	0.0000	0.0000
AOI12X1	B	0.0000	0.0000	0.0000
AOI12X1	B	0.0000	0.0000	0.0000
AOI12X1	C	0.0000	0.0000	0.0000
AOI12X1	C	0.0001	0.0001	0.0001

Passive Power

Hidden power(pJ) for A rising :
Conditional

Power(pJ)				
Cell	first	mid	last	
AOI12X1	-0.0000	-0.0000	-0.0000	
AOI12X1	0.0000	0.0000	0.0000	
AOI12X1	-0.0000	-0.0000	-0.0000	
AOI12X1	0.0000	0.0000	0.0000	
AOI12X1	-0.0000	-0.0000	-0.0000	
AOI12X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for A falling :
Conditional

Power(pJ)				
Cell	first	mid	last	
AOI12X1	0.0000	0.0000	0.0000	
AOI12X1	-0.0000	-0.0000	-0.0000	
AOI12X1	0.0000	0.0000	0.0000	
AOI12X1	-0.0000	-0.0000	-0.0000	
AOI12X1	0.0000	0.0000	0.0000	
AOI12X1	-0.0000	-0.0000	-0.0000	

Hidden power(pJ) for B rising :
Conditional

Power(pJ)				
Cell	first	mid	last	
AOI12X1	-0.0000	-0.0000	-0.0000	
AOI12X1	0.0000	0.0000	0.0000	
AOI12X1	-0.0000	-0.0000	-0.0000	
AOI12X1	0.0000	0.0000	0.0000	
AOI12X1	-0.0000	-0.0000	-0.0000	
AOI12X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for B falling :
Conditional

Power(pJ)				
Cell	first	mid	last	
AOI12X1	0.0000	0.0000	0.0000	
AOI12X1	-0.0000	-0.0000	-0.0000	
AOI12X1	0.0000	0.0000	0.0000	
AOI12X1	-0.0000	-0.0000	-0.0000	
AOI12X1	0.0000	0.0000	0.0000	
AOI12X1	-0.0000	-0.0000	-0.0000	

Hidden power(pJ) for C rising:
Conditional

Power(pJ)				
Cell	first	mid	last	
AOI12X1	-0.0000	-0.0000	-0.0000	
AOI12X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for C falling:
Conditional

Power(pJ)				
Cell	first	mid	last	
AOI12X1	0.0000	0.0000	0.0000	
AOI12X1	-0.0000	-0.0000	-0.0000	

END Cell Group AOI12X1

Cell Group AOI22X1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	(!A * !C) + (!A * !D) + (!B * !C) + (!B * !D)

Truth Table

Input				Output	
A	B	C	D	Y	
0	x	0	x	1	
0	x	1	0	1	
x	x	1	1	0	
1	0	0	x	1	
1	0	1	0	1	
1	1	x	x	0	

Footprint:

Cell	Area
AOI22X1	0.0000

Leakage

Leakage (nW)				
Cell	Min	Avg	Max	
AOI22X1	0.0000	0.1582	0.2955	

Pin Capacitance

Pin Cap(pf)		Max Cap(pf)				
Cell	A	B	C	D	Y	
AOI22X1	0.0005	0.0005	0.0005	0.0005	0.0050	

Delay

Delays(ns) to Y rising :

		Delay (ns)				
Cell	Timing Arc (Dir)	first	mid	last		
AOI22X1	A->Y(FR)	5.3355	10.6423	22.0407		
AOI22X1	B->Y(FR)	4.8598	10.0689	21.2997		
AOI22X1	C->Y(FR)	4.0844	8.8686	19.1932		
AOI22X1	D->Y(FR)	4.5128	9.3628	19.8032		

Delays(ns) to Y falling :

		Delay (ns)				
Cell	Timing Arc (Dir)	first	mid	last		
AOI22X1	A->Y(RF)	3.5963	7.8102	17.0006		
AOI22X1	B->Y(RF)	3.3546	7.2101	15.8078		
AOI22X1	C->Y(RF)	2.7778	6.5574	15.0976		
AOI22X1	D->Y(RF)	2.9857	7.1150	16.2479		

Power

Internal switching power(pJ) to Y rising :

		Power (pJ)				
Cell	Input	first	mid	last		
AOI22X1	A	0.0001	0.0001	0.0001		
AOI22X1	A	0.0000	0.0000	0.0000		
AOI22X1	B	0.0001	0.0001	0.0001		
AOI22X1	B	0.0000	0.0000	0.0000		
AOI22X1	C	0.0000	0.0000	0.0000		
AOI22X1	C	0.0000	0.0000	0.0000		
AOI22X1	D	0.0001	0.0001	0.0001		
AOI22X1	D	0.0000	0.0000	0.0000		

Internal switching power(pJ) to Y falling :

		Power (pJ)				
Cell	Input	first	mid	last		
AOI22X1	A	0.0000	0.0000	0.0000		
AOI22X1	A	0.0001	0.0001	0.0001		
AOI22X1	B	0.0000	0.0000	0.0000		
AOI22X1	B	0.0001	0.0001	0.0001		
AOI22X1	C	0.0000	0.0000	0.0000		
AOI22X1	C	0.0000	0.0000	0.0000		
AOI22X1	D	0.0000	0.0000	0.0000		
AOI22X1	D	0.0001	0.0001	0.0001		

Passive Power

Hidden power(pJ) for A rising:
Conditional

Power(pJ)				
Cell	first	mid	last	
AOI22X1	-0.0000	-0.0000	-0.0000	
AOI22X1	0.0000	0.0000	0.0000	
AOI22X1	-0.0000	-0.0000	-0.0000	
AOI22X1	0.0000	0.0000	0.0000	
AOI22X1	-0.0000	-0.0000	-0.0000	
AOI22X1	0.0000	0.0000	0.0000	
AOI22X1	-0.0000	-0.0000	-0.0000	
AOI22X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for A falling:
Conditional

Power(pJ)				
Cell	first	mid	last	
AOI22X1	0.0000	0.0000	0.0000	
AOI22X1	-0.0000	-0.0000	-0.0000	
AOI22X1	0.0000	0.0000	0.0000	
AOI22X1	-0.0000	-0.0000	-0.0000	
AOI22X1	0.0000	0.0000	0.0000	
AOI22X1	-0.0000	-0.0000	-0.0000	
AOI22X1	0.0000	0.0000	0.0000	
AOI22X1	-0.0000	-0.0000	-0.0000	

Hidden power(pJ) for B rising:
Conditional

Power(pJ)				
Cell	first	mid	last	
AOI22X1	-0.0000	-0.0000	-0.0000	
AOI22X1	0.0000	0.0000	0.0000	
AOI22X1	-0.0000	-0.0000	-0.0000	
AOI22X1	0.0000	0.0000	0.0000	
AOI22X1	-0.0000	-0.0000	-0.0000	
AOI22X1	0.0000	0.0000	0.0000	
AOI22X1	-0.0000	-0.0000	-0.0000	
AOI22X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for B falling:
Conditional

Power(pJ)				
Cell	first	mid	last	
AOI22X1	0.0000	0.0000	0.0000	
AOI22X1	-0.0000	-0.0000	-0.0000	
AOI22X1	0.0000	0.0000	0.0000	
AOI22X1	-0.0000	-0.0000	-0.0000	
AOI22X1	0.0000	0.0000	0.0000	
AOI22X1	-0.0000	-0.0000	-0.0000	
AOI22X1	0.0000	0.0000	0.0000	
AOI22X1	-0.0000	-0.0000	-0.0000	

Hidden power(pJ) for C rising :
Conditional

Power (pJ)			
Cell	first	mid	last
AOI22X1	-0.0000	-0.0000	-0.0000
AOI22X1	0.0000	0.0000	0.0000
AOI22X1	-0.0000	-0.0000	-0.0000
AOI22X1	0.0000	0.0000	0.0000
AOI22X1	-0.0000	-0.0000	-0.0000
AOI22X1	0.0000	0.0000	0.0000
AOI22X1	-0.0000	-0.0000	-0.0000
AOI22X1	0.0000	0.0000	0.0000

Hidden power(pJ) for C falling :
Conditional

Power (pJ)			
Cell	first	mid	last
AOI22X1	0.0000	0.0000	0.0000
AOI22X1	-0.0000	-0.0000	-0.0000
AOI22X1	0.0000	0.0000	0.0000
AOI22X1	-0.0000	-0.0000	-0.0000
AOI22X1	0.0000	0.0000	0.0000
AOI22X1	-0.0000	-0.0000	-0.0000
AOI22X1	0.0000	0.0000	0.0000
AOI22X1	-0.0000	-0.0000	-0.0000

Hidden power(pJ) for D rising :
Conditional

Power (pJ)			
Cell	first	mid	last
AOI22X1	-0.0000	-0.0000	-0.0000
AOI22X1	0.0000	0.0000	0.0000
AOI22X1	-0.0000	-0.0000	-0.0000
AOI22X1	0.0000	0.0000	0.0000
AOI22X1	-0.0000	-0.0000	-0.0000
AOI22X1	0.0000	0.0000	0.0000
AOI22X1	-0.0000	-0.0000	-0.0000
AOI22X1	0.0000	0.0000	0.0000

Hidden power(pJ) for D falling :
Conditional

Power (pJ)			
Cell	first	mid	last
AOI22X1	0.0000	0.0000	0.0000
AOI22X1	-0.0000	-0.0000	-0.0000
AOI22X1	0.0000	0.0000	0.0000
AOI22X1	-0.0000	-0.0000	-0.0000
AOI22X1	0.0000	0.0000	0.0000
AOI22X1	-0.0000	-0.0000	-0.0000
AOI22X1	0.0000	0.0000	0.0000
AOI22X1	-0.0000	-0.0000	-0.0000

END Cell Group AOI22X1

Cell Group AOI112X1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	(!A * !C * !D) + (!B * !C * !D)

Truth Table

Input				Output
A	B	C	D	Y
0	x	0	0	1
0	x	x	1	0
x	x	1	x	0
1	0	0	0	1
1	0	x	1	0
1	1	x	x	0

Footprint:

Cell	Area
AOI112X1	0.0000

Leakage

Leakage (nW)			
Cell	Min	Avg	Max
AOI112X1	0.0000	0.1130	0.2904

Pin Capacitance

Pin Cap(pf)						Max Cap(pf)
Cell	A	B	C	D	Y	
AOI112X1	0.0005	0.0005	0.0005	0.0005	0.0050	

Delay

Delays(ns) to Y rising:

Delay (ns)					
Cell	Timing Arc(Dir)	first	mid	last	
AOI112X1	A->Y(FR)	7.1897	14.1338	28.6145	
AOI112X1	B->Y(FR)	6.8323	13.7621	28.2779	
AOI112X1	C->Y(FR)	8.8349	16.4958	32.3457	
AOI112X1	D->Y(FR)	8.6913	15.9876	31.4248	

Delays(ns) to Y falling:

Delay (ns)					
Cell	Timing Arc(Dir)	first	mid	last	
AOI112X1	A->Y(RF)	3.2276	7.3092	16.3073	
AOI112X1	B->Y(RF)	3.1257	6.8646	15.3259	
AOI112X1	C->Y(RF)	1.4740	4.0055	10.2053	
AOI112X1	D->Y(RF)	1.4302	3.9202	10.0664	

Power

Internal switching power(pJ) to Y rising :

		Power(pJ)			
Cell	Input	first	mid	last	
AOI112X1	A	0.0001	0.0001	0.0001	
AOI112X1	A	0.0000	0.0000	0.0000	
AOI112X1	B	0.0001	0.0001	0.0001	
AOI112X1	B	0.0000	0.0000	0.0000	
AOI112X1	C	0.0001	0.0001	0.0001	
AOI112X1	C	0.0000	0.0000	0.0000	
AOI112X1	D	0.0001	0.0001	0.0001	
AOI112X1	D	0.0000	0.0000	0.0000	

Internal switching power(pJ) to Y falling :

		Power(pJ)			
Cell	Input	first	mid	last	
AOI112X1	A	0.0000	0.0000	0.0000	
AOI112X1	A	0.0001	0.0001	0.0000	
AOI112X1	B	0.0000	0.0000	0.0000	
AOI112X1	B	0.0000	0.0000	0.0000	
AOI112X1	C	0.0000	0.0000	0.0000	
AOI112X1	C	0.0001	0.0001	0.0001	
AOI112X1	D	0.0000	0.0000	0.0000	
AOI112X1	D	0.0001	0.0001	0.0001	

Passive Power

Hidden power(pJ) for A rising :
Conditional

		Power(pJ)		
Cell		first	mid	last
AOI112X1		-0.0000	-0.0000	-0.0000
AOI112X1		0.0000	0.0000	0.0000
AOI112X1		-0.0000	-0.0000	-0.0000
AOI112X1		0.0000	0.0000	0.0000
AOI112X1		-0.0000	-0.0000	-0.0000
AOI112X1		0.0000	0.0000	0.0000
AOI112X1		-0.0000	-0.0000	-0.0000
AOI112X1		0.0000	0.0000	0.0000
AOI112X1		-0.0000	-0.0000	-0.0000
AOI112X1		0.0000	0.0000	0.0000

Hidden power(pJ) for A falling :
Conditional

		Power(pJ)		
Cell		first	mid	last
AOI112X1		0.0000	0.0000	0.0000
AOI112X1		-0.0000	-0.0000	-0.0000
AOI112X1		0.0000	0.0000	0.0000
AOI112X1		-0.0000	-0.0000	-0.0000
AOI112X1		0.0000	0.0000	0.0000
AOI112X1		-0.0000	-0.0000	-0.0000
AOI112X1		0.0000	0.0000	0.0000
AOI112X1		-0.0000	-0.0000	-0.0000
AOI112X1		0.0000	0.0000	0.0000

AOI112X1	-0.0000	-0.0000	-0.0000
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Hidden power(pJ) for B rising:
Conditional

Power (pJ)			
Cell	first	mid	last
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000

Hidden power(pJ) for B falling:
Conditional

Power (pJ)			
Cell	first	mid	last
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000

Hidden power(pJ) for C rising:
Conditional

Power (pJ)			
Cell	first	mid	last
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000

Hidden power(pJ) for C falling:
Conditional

Power (pJ)			
Cell	first	mid	last
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000

AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000

Hidden power(pJ) for D rising :
Conditional

Power (pJ)			
Cell	first	mid	last
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000

Hidden power(pJ) for D falling :
Conditional

Power (pJ)			
Cell	first	mid	last
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000
AOI112X1	0.0000	0.0000	0.0000
AOI112X1	-0.0000	-0.0000	-0.0000

END Cell Group AOI112X1

Cell Group AOI212X1 from Library 28nm_slvt , Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	(!A * !C * !E) + (!A * !D * !E) + (!B * !C * !E) + (!B * !D * !E)

Truth Table

Input					Output	
A	B	C	D	E	Y	
0	x	0	x	0	1	
0	x	x	x	1	0	
0	x	1	0	0	1	
x	x	1	1	x	0	
1	0	0	x	0	1	
1	0	x	x	1	0	
1	0	1	0	0	1	
1	1	x	x	x	0	

Footprint :

Cell	Area
AOI212X1	0.0000

Leakage

Leakage (nW)			
Cell	Min	Avg	Max
AOI212X1	0.0000	0.1415	0.2236

Pin Capacitance

Pin Cap(pf)						Max Cap(pf)
Cell	A	B	C	D	E	Y
AOI212X1	0.0005	0.0005	0.0005	0.0005	0.0006	0.0050

Delay

Delays (ns) to Y rising :

Delay (ns)					
Cell	Timing Arc (Dir)	first	mid	last	
AOI212X1	A->Y(FR)	10.0778	17.8842	34.0767	
AOI212X1	B->Y(FR)	9.5091	17.2756	33.4306	
AOI212X1	C->Y(FR)	9.6754	17.1420	32.8010	
AOI212X1	D->Y(FR)	8.9044	16.2748	31.7692	
AOI212X1	E->Y(FR)	8.2129	15.3508	30.1809	

Delays (ns) to Y falling :

Delay (ns)					
Cell	Timing Arc (Dir)	first	mid	last	
AOI212X1	A->Y(RF)	4.0161	8.4164	17.8906	
AOI212X1	B->Y(RF)	3.8826	7.9176	16.8120	
AOI212X1	C->Y(RF)	3.7539	7.9884	17.2282	
AOI212X1	D->Y(RF)	3.5359	7.4015	16.0709	
AOI212X1	E->Y(RF)	1.3489	3.8709	10.0917	

Power

Internal switching power(pJ) to Y rising :

Power (pJ)					
Cell	Input	first	mid	last	
AOI212X1	A	0.0001	0.0001	0.0001	
AOI212X1	A	0.0000	0.0000	0.0000	
AOI212X1	B	0.0001	0.0001	0.0001	
AOI212X1	B	0.0000	0.0000	0.0000	
AOI212X1	C	0.0001	0.0001	0.0001	
AOI212X1	C	0.0000	0.0000	0.0000	
AOI212X1	D	0.0001	0.0001	0.0001	
AOI212X1	D	0.0000	0.0000	0.0000	
AOI212X1	E	0.0001	0.0001	0.0001	
AOI212X1	E	0.0000	0.0000	0.0000	

Internal switching power(pJ) to Y falling :

		Power (pJ)		
Cell	Input	first	mid	last
AOI212X1	A	0.0000	0.0000	0.0000
AOI212X1	A	0.0001	0.0001	0.0001
AOI212X1	B	0.0000	0.0000	0.0000
AOI212X1	B	0.0001	0.0001	0.0001
AOI212X1	C	0.0000	0.0000	0.0000
AOI212X1	C	0.0001	0.0001	0.0001
AOI212X1	D	0.0000	0.0000	0.0000
AOI212X1	D	0.0001	0.0001	0.0001
AOI212X1	E	0.0000	0.0000	0.0000
AOI212X1	E	0.0000	0.0000	0.0000

Passive Power

Hidden power(pJ) for A rising :
Conditional

		Power (pJ)		
Cell		first	mid	last
AOI212X1		-0.0000	-0.0000	-0.0000
AOI212X1		0.0000	0.0000	0.0000
AOI212X1		-0.0000	-0.0000	-0.0000
AOI212X1		0.0000	0.0000	0.0000
AOI212X1		-0.0000	-0.0000	-0.0000
AOI212X1		0.0000	0.0000	0.0000
AOI212X1		-0.0000	-0.0000	-0.0000
AOI212X1		0.0000	0.0000	0.0000
AOI212X1		-0.0000	-0.0000	-0.0000
AOI212X1		0.0000	0.0000	0.0000
AOI212X1		-0.0000	-0.0000	-0.0000
AOI212X1		0.0000	0.0000	0.0000
AOI212X1		-0.0000	-0.0000	-0.0000
AOI212X1		0.0000	0.0000	0.0000
AOI212X1		-0.0000	-0.0000	-0.0000
AOI212X1		0.0000	0.0000	0.0000

Hidden power(pJ) for A falling :
Conditional

		Power (pJ)		
Cell		first	mid	last
AOI212X1		0.0000	0.0000	0.0000
AOI212X1		-0.0000	-0.0000	-0.0000
AOI212X1		0.0000	0.0000	0.0000
AOI212X1		-0.0000	-0.0000	-0.0000
AOI212X1		0.0000	0.0000	0.0000
AOI212X1		-0.0000	-0.0000	-0.0000
AOI212X1		0.0000	0.0000	0.0000
AOI212X1		-0.0000	-0.0000	-0.0000
AOI212X1		0.0000	0.0000	0.0000
AOI212X1		-0.0000	-0.0000	-0.0000
AOI212X1		0.0000	0.0000	0.0000
AOI212X1		-0.0000	-0.0000	-0.0000
AOI212X1		0.0000	0.0000	0.0000
AOI212X1		-0.0000	-0.0000	-0.0000
AOI212X1		0.0000	0.0000	0.0000
AOI212X1		-0.0000	-0.0000	-0.0000

Hidden power(pJ) for B rising :
Conditional

Power (pJ)			
Cell	first	mid	last
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000

Hidden power(pJ) for B falling :
Conditional

Power (pJ)			
Cell	first	mid	last
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000

Hidden power(pJ) for C rising :
Conditional

Power (pJ)			
Cell	first	mid	last
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000

AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000

Hidden power(pJ) for C falling :
Conditional

Power (pJ)			
Cell	first	mid	last
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000

Hidden power(pJ) for D rising :
Conditional

Power (pJ)			
Cell	first	mid	last
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000
AOI212X1	-0.0000	-0.0000	-0.0000
AOI212X1	0.0000	0.0000	0.0000

Hidden power(pJ) for D falling :

Conditional

Power (pJ)				
Cell	first	mid	last	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	

Hidden power(pJ) for E rising:
Conditional

Power (pJ)				
Cell	first	mid	last	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for E falling:
Conditional

Power (pJ)				
Cell	first	mid	last	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	
AOI212X1	0.0000	0.0000	0.0000	
AOI212X1	-0.0000	-0.0000	-0.0000	

END Cell Group AOI212X1

Cell Group AOI222X1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	$(!A * !C * !E) + (!A * !C * !F) + (!A * !D * !E) + (!A * !D * !F) + (!B * !C * !E) + (!B * !C * !F) + (!B * !D * !E) + (!B * !D * !F)$

Truth Table

Input							Output
A	B	C	D	E	F	Y	
0	x	0	x	0	x	1	
0	x	0	x	1	0	1	
0	x	x	x	1	1	0	
0	x	1	0	0	x	1	
0	x	1	0	1	0	1	
x	x	1	1	x	x	0	
1	0	0	x	0	x	1	
1	0	0	x	1	0	1	
1	0	x	x	1	1	0	
1	0	1	0	0	x	1	
1	0	1	0	1	0	1	
1	1	x	x	x	x	0	

Footprint :

Cell	Area
AOI222X1	0.0000

Leakage

Leakage (nW)			
Cell	Min	Avg	Max
AOI222X1	0.0000	0.1722	0.2887

Pin Capacitance

Pin Cap(pf)							Max Cap(pf)
Cell	A	B	C	D	E	F	Y
AOI222X1	0.0005	0.0005	0.0005	0.0005	0.0005	0.0005	0.0050

Delay

Delays(ns) to Y rising :

Delay (ns)					
Cell	Timing Arc (Dir)	first	mid	last	
AOI222X1	A->Y(FR)	12.7439	20.5733	36.8308	
AOI222X1	B->Y(FR)	12.1545	19.9581	36.1816	
AOI222X1	C->Y(FR)	12.3830	19.8574	35.5589	
AOI222X1	D->Y(FR)	11.7435	19.1918	34.8508	
AOI222X1	E->Y(FR)	10.3159	17.4525	32.2929	
AOI222X1	F->Y(FR)	9.6858	16.8113	31.6164	

Delays(ns) to Y falling :

		Delay (ns)		
Cell	Timing Arc (Dir)	first	mid	last
AOI222X1	A->Y(RF)	5.0132	9.3996	18.8914
AOI222X1	B->Y(RF)	4.8809	8.9040	17.8061
AOI222X1	C->Y(RF)	4.7945	9.1177	18.5286
AOI222X1	D->Y(RF)	4.6128	8.5577	17.3951
AOI222X1	E->Y(RF)	4.1872	8.4518	17.8059
AOI222X1	F->Y(RF)	4.0339	7.9404	16.7250

Power

Internal switching power(pJ) to Y rising :

		Power (pJ)		
Cell	Input	first	mid	last
AOI222X1	A	0.0001	0.0001	0.0001
AOI222X1	A	0.0000	0.0000	0.0000
AOI222X1	B	0.0001	0.0001	0.0001
AOI222X1	B	0.0000	0.0000	0.0000
AOI222X1	C	0.0001	0.0001	0.0001
AOI222X1	C	0.0000	0.0000	0.0000
AOI222X1	D	0.0001	0.0001	0.0001
AOI222X1	D	0.0000	0.0000	0.0000
AOI222X1	E	0.0001	0.0001	0.0001
AOI222X1	E	0.0000	0.0000	0.0000
AOI222X1	F	0.0001	0.0001	0.0001
AOI222X1	F	0.0000	0.0000	0.0000

Internal switching power(pJ) to Y falling :

		Power (pJ)		
Cell	Input	first	mid	last
AOI222X1	A	0.0000	0.0000	0.0000
AOI222X1	A	0.0001	0.0001	0.0001
AOI222X1	B	0.0000	0.0000	0.0000
AOI222X1	B	0.0001	0.0001	0.0001
AOI222X1	C	0.0000	0.0000	0.0000
AOI222X1	C	0.0001	0.0001	0.0001
AOI222X1	D	0.0000	0.0000	0.0000
AOI222X1	D	0.0001	0.0001	0.0001
AOI222X1	E	0.0000	0.0000	0.0000
AOI222X1	E	0.0001	0.0001	0.0001
AOI222X1	F	0.0000	0.0000	0.0000
AOI222X1	F	0.0001	0.0001	0.0001

Passive Power

Hidden power(pJ) for A rising :

Conditional

		Power (pJ)		
Cell		first	mid	last
AOI222X1		-0.0000	-0.0000	-0.0000
AOI222X1		0.0000	0.0000	0.0000
AOI222X1		-0.0000	-0.0000	-0.0000
AOI222X1		0.0000	0.0000	0.0000
AOI222X1		-0.0000	-0.0000	-0.0000
AOI222X1		0.0000	0.0000	0.0000
AOI222X1		-0.0000	-0.0000	-0.0000

AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000

Hidden power(pJ) for A falling :
Conditional

Cell	Power (pJ)		
	first	mid	last
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000

Hidden power(pJ) for B rising :
Conditional

Cell	Power (pJ)		
	first	mid	last
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000
AOI222X1	0.0000	0.0000	0.0000
AOI222X1	-0.0000	-0.0000	-0.0000

Leakage

Leakage (nW)			
Cell	Min	Avg	Max
OAI12X1	0.0000	0.1347	0.2923

Pin Capacitance

Cell	Pin Cap(pf)			Max Cap(pf)
	A	B	C	Y
OAI12X1	0.0005	0.0005	0.0005	0.0050

Delay

Delays(ns) to Y rising :

Cell	Timing Arc(Dir)	Delay (ns)		
		first	mid	last
OAI12X1	A->Y(FR)	4.3268	9.4647	20.4674
OAI12X1	B->Y(FR)	4.2045	8.8890	19.1535
OAI12X1	C->Y(FR)	1.8298	4.6148	11.2896

Delays(ns) to Y falling :

Cell	Timing Arc(Dir)	Delay (ns)		
		first	mid	last
OAI12X1	A->Y(RF)	3.1661	7.0018	15.6145
OAI12X1	B->Y(RF)	3.0477	6.8556	15.5053
OAI12X1	C->Y(RF)	3.6423	7.8548	17.1619

Power

Internal switching power(pJ) to Y rising :

Cell	Input	Power (pJ)		
		first	mid	last
OAI12X1	A	0.0000	0.0000	0.0000
OAI12X1	A	0.0000	0.0000	0.0000
OAI12X1	B	0.0000	0.0000	0.0000
OAI12X1	B	0.0000	0.0000	0.0000
OAI12X1	C	0.0001	0.0001	0.0001
OAI12X1	C	0.0000	0.0000	0.0000

Internal switching power(pJ) to Y falling :

Cell	Input	Power (pJ)		
		first	mid	last
OAI12X1	A	0.0000	0.0000	0.0000
OAI12X1	A	0.0001	0.0001	0.0001
OAI12X1	B	0.0000	0.0000	0.0000
OAI12X1	B	0.0000	0.0000	0.0000
OAI12X1	C	0.0000	0.0000	0.0000
OAI12X1	C	0.0001	0.0001	0.0001

Passive Power

Hidden power(pJ) for A rising:
Conditional

Power(pJ)				
Cell	first	mid	last	
OAI12X1	-0.0000	-0.0000	-0.0000	
OAI12X1	0.0000	0.0000	0.0000	
OAI12X1	-0.0000	-0.0000	-0.0000	
OAI12X1	0.0000	0.0000	0.0000	
OAI12X1	-0.0000	-0.0000	-0.0000	
OAI12X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for A falling:
Conditional

Power(pJ)				
Cell	first	mid	last	
OAI12X1	0.0000	0.0000	0.0000	
OAI12X1	-0.0000	-0.0000	-0.0000	
OAI12X1	0.0000	0.0000	0.0000	
OAI12X1	-0.0000	-0.0000	-0.0000	
OAI12X1	0.0000	0.0000	0.0000	
OAI12X1	-0.0000	-0.0000	-0.0000	

Hidden power(pJ) for B rising:
Conditional

Power(pJ)				
Cell	first	mid	last	
OAI12X1	-0.0000	-0.0000	-0.0000	
OAI12X1	0.0000	0.0000	0.0000	
OAI12X1	-0.0000	-0.0000	-0.0000	
OAI12X1	0.0000	0.0000	0.0000	
OAI12X1	-0.0000	-0.0000	-0.0000	
OAI12X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for B falling:
Conditional

Power(pJ)				
Cell	first	mid	last	
OAI12X1	0.0000	0.0000	0.0000	
OAI12X1	-0.0000	-0.0000	-0.0000	
OAI12X1	0.0000	0.0000	0.0000	
OAI12X1	-0.0000	-0.0000	-0.0000	
OAI12X1	0.0000	0.0000	0.0000	
OAI12X1	-0.0000	-0.0000	-0.0000	

Hidden power(pJ) for C rising:
Conditional

Power(pJ)				
Cell	first	mid	last	
OAI12X1	-0.0000	-0.0000	-0.0000	
OAI12X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for C falling:
Conditional

Power(pJ)				
Cell	first	mid	last	
OAI12X1	0.0000	0.0000	0.0000	
OAI12X1	-0.0000	-0.0000	-0.0000	

END Cell Group OAI12X1

Cell Group OAI22X1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	(!A * !B) + (!C * !D)

Truth Table

Input				Output	
A	B	C	D	Y	
0	0	x	x	1	
x	1	0	0	1	
x	1	x	1	0	
x	1	1	x	0	
1	x	0	0	1	
1	x	x	1	0	
1	x	1	x	0	

Footprint:

Cell	Area
OAI22X1	0.0000

Leakage

Leakage (nW)				
Cell	Min	Avg	Max	
OAI22X1	0.0000	0.1659	0.2991	

Pin Capacitance

		Pin Cap(pf)				Max Cap(pf)
Cell	A	B	C	D	Y	
OAI22X1	0.0005	0.0005	0.0005	0.0005	0.0050	

Delay

Delays(ns) to Y rising :

		Delay (ns)			
Cell	Timing Arc (Dir)	first	mid	last	
OAI22X1	A->Y(FR)	5.1618	10.4630	21.6769	
OAI22X1	B->Y(FR)	4.8598	9.6910	20.1135	
OAI22X1	C->Y(FR)	3.8060	8.5555	18.8994	
OAI22X1	D->Y(FR)	4.1189	9.3270	20.4627	

Delays(ns) to Y falling :

		Delay (ns)			
Cell	Timing Arc (Dir)	first	mid	last	
OAI22X1	A->Y(RF)	3.8395	8.0655	17.4312	
OAI22X1	B->Y(RF)	3.5473	7.6977	16.9407	
OAI22X1	C->Y(RF)	2.8818	6.6916	15.2313	
OAI22X1	D->Y(RF)	3.2008	7.0563	15.6893	

Power

Internal switching power(pJ) to Y rising :

		Power (pJ)		
Cell	Input	first	mid	last
OAI22X1	A	0.0001	0.0001	0.0001
OAI22X1	A	0.0000	0.0000	0.0000
OAI22X1	B	0.0001	0.0001	0.0001
OAI22X1	B	0.0000	0.0000	0.0000
OAI22X1	C	0.0000	0.0000	0.0000
OAI22X1	C	0.0000	0.0000	0.0000
OAI22X1	D	0.0001	0.0001	0.0000
OAI22X1	D	0.0000	0.0000	0.0000

Internal switching power(pJ) to Y falling :

		Power (pJ)		
Cell	Input	first	mid	last
OAI22X1	A	0.0000	0.0000	0.0000
OAI22X1	A	0.0001	0.0001	0.0001
OAI22X1	B	0.0000	0.0000	0.0000
OAI22X1	B	0.0001	0.0001	0.0001
OAI22X1	C	0.0000	0.0000	0.0000
OAI22X1	C	0.0001	0.0000	0.0000
OAI22X1	D	0.0000	0.0000	0.0000
OAI22X1	D	0.0001	0.0001	0.0001

Passive Power

Hidden power(pJ) for A rising:
Conditional

Power(pJ)				
Cell	first	mid	last	
OAI22X1	-0.0000	-0.0000	-0.0000	
OAI22X1	0.0000	0.0000	0.0000	
OAI22X1	-0.0000	-0.0000	-0.0000	
OAI22X1	0.0000	0.0000	0.0000	
OAI22X1	-0.0000	-0.0000	-0.0000	
OAI22X1	0.0000	0.0000	0.0000	
OAI22X1	-0.0000	-0.0000	-0.0000	
OAI22X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for A falling:
Conditional

Power(pJ)				
Cell	first	mid	last	
OAI22X1	0.0000	0.0000	0.0000	
OAI22X1	-0.0000	-0.0000	-0.0000	
OAI22X1	0.0000	0.0000	0.0000	
OAI22X1	-0.0000	-0.0000	-0.0000	
OAI22X1	0.0000	0.0000	0.0000	
OAI22X1	-0.0000	-0.0000	-0.0000	
OAI22X1	0.0000	0.0000	0.0000	
OAI22X1	-0.0000	-0.0000	-0.0000	

Hidden power(pJ) for B rising:
Conditional

Power(pJ)				
Cell	first	mid	last	
OAI22X1	-0.0000	-0.0000	-0.0000	
OAI22X1	0.0000	0.0000	0.0000	
OAI22X1	-0.0000	-0.0000	-0.0000	
OAI22X1	0.0000	0.0000	0.0000	
OAI22X1	-0.0000	-0.0000	-0.0000	
OAI22X1	0.0000	0.0000	0.0000	
OAI22X1	-0.0000	-0.0000	-0.0000	
OAI22X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for B falling:
Conditional

Power(pJ)				
Cell	first	mid	last	
OAI22X1	0.0000	0.0000	0.0000	
OAI22X1	-0.0000	-0.0000	-0.0000	
OAI22X1	0.0000	0.0000	0.0000	
OAI22X1	-0.0000	-0.0000	-0.0000	
OAI22X1	0.0000	0.0000	0.0000	
OAI22X1	-0.0000	-0.0000	-0.0000	
OAI22X1	0.0000	0.0000	0.0000	
OAI22X1	-0.0000	-0.0000	-0.0000	

Hidden power(pJ) for C rising:
Conditional

		Power (pJ)		
Cell		first	mid	last
OAI22X1		-0.0000	-0.0000	-0.0000
OAI22X1		0.0000	0.0000	0.0000
OAI22X1		-0.0000	-0.0000	-0.0000
OAI22X1		0.0000	0.0000	0.0000
OAI22X1		-0.0000	-0.0000	-0.0000
OAI22X1		0.0000	0.0000	0.0000
OAI22X1		-0.0000	-0.0000	-0.0000
OAI22X1		0.0000	0.0000	0.0000

Hidden power(pJ) for C falling:
Conditional

		Power (pJ)		
Cell		first	mid	last
OAI22X1		0.0000	0.0000	0.0000
OAI22X1		-0.0000	-0.0000	-0.0000
OAI22X1		0.0000	0.0000	0.0000
OAI22X1		-0.0000	-0.0000	-0.0000
OAI22X1		0.0000	0.0000	0.0000
OAI22X1		-0.0000	-0.0000	-0.0000
OAI22X1		0.0000	0.0000	0.0000
OAI22X1		-0.0000	-0.0000	-0.0000

Hidden power(pJ) for D rising:
Conditional

		Power (pJ)		
Cell		first	mid	last
OAI22X1		-0.0000	-0.0000	-0.0000
OAI22X1		0.0000	0.0000	0.0000
OAI22X1		-0.0000	-0.0000	-0.0000
OAI22X1		0.0000	0.0000	0.0000
OAI22X1		-0.0000	-0.0000	-0.0000
OAI22X1		0.0000	0.0000	0.0000
OAI22X1		-0.0000	-0.0000	-0.0000
OAI22X1		0.0000	0.0000	0.0000

Hidden power(pJ) for D falling:
Conditional

		Power (pJ)		
Cell		first	mid	last
OAI22X1		0.0000	0.0000	0.0000
OAI22X1		-0.0000	-0.0000	-0.0000
OAI22X1		0.0000	0.0000	0.0000
OAI22X1		-0.0000	-0.0000	-0.0000
OAI22X1		0.0000	0.0000	0.0000
OAI22X1		-0.0000	-0.0000	-0.0000
OAI22X1		0.0000	0.0000	0.0000
OAI22X1		-0.0000	-0.0000	-0.0000

END Cell Group OAI22X1

Cell Group OAI211X1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	(!A * !B) + (!C) + (!D)

Truth Table

Input				Output	
A	B	C	D	Y	
0	0	x	x	1	
x	1	0	x	1	
x	1	1	0	1	
x	1	1	1	0	
1	x	0	x	1	
1	x	1	0	1	
1	x	1	1	0	

Footprint:

Cell	Area
OAI211X1	0.0000

Leakage

Leakage (nW)			
Cell	Min	Avg	Max
OAI211X1	0.0000	0.1134	0.4457

Pin Capacitance

Pin Cap(pf)		Max Cap(pf)				
Cell	A	B	C	D	Y	
OAI211X1	0.0005	0.0005	0.0005	0.0006	0.0050	

Delay

Delays(ns) to Y rising:

Delay (ns)				
Cell	Timing Arc (Dir)	first	mid	last
OAI211X1	A->Y(FR)	5.0530	10.2942	21.3510
OAI211X1	B->Y(FR)	4.7481	9.5261	19.8006
OAI211X1	C->Y(FR)	1.6382	4.3700	10.9295
OAI211X1	D->Y(FR)	1.6031	4.3440	10.9631

Delays(ns) to Y falling :

		Delay (ns)		
Cell	Timing Arc(Dir)	first	mid	last
OAI211X1	A->Y(RF)	5.7734	11.6137	23.9734
OAI211X1	B->Y(RF)	5.2936	11.0401	23.2420
OAI211X1	C->Y(RF)	5.4448	11.0183	22.9878
OAI211X1	D->Y(RF)	5.0535	10.3382	21.6955

Power

Internal switching power(pJ) to Y rising:

		Power (pJ)		
Cell	Input	first	mid	last
OAI211X1	A	0.0001	0.0001	0.0001
OAI211X1	A	0.0000	0.0000	0.0000
OAI211X1	B	0.0001	0.0001	0.0001
OAI211X1	B	0.0000	0.0000	0.0000
OAI211X1	C	0.0000	0.0000	0.0000
OAI211X1	C	0.0000	0.0000	0.0000
OAI211X1	D	0.0000	0.0000	0.0000
OAI211X1	D	0.0000	0.0000	0.0000

Internal switching power(pJ) to Y falling:

		Power (pJ)		
Cell	Input	first	mid	last
OAI211X1	A	0.0000	0.0000	0.0000
OAI211X1	A	0.0001	0.0001	0.0001
OAI211X1	B	0.0000	0.0000	0.0000
OAI211X1	B	0.0001	0.0001	0.0001
OAI211X1	C	0.0000	0.0000	0.0000
OAI211X1	C	0.0001	0.0001	0.0001
OAI211X1	D	0.0000	0.0000	0.0000
OAI211X1	D	0.0001	0.0001	0.0001

Passive Power

Hidden power(pJ) for A rising:
Conditional

		Power (pJ)		
Cell		first	mid	last
OAI211X1		-0.0000	-0.0000	-0.0000
OAI211X1		0.0000	0.0000	0.0000
OAI211X1		-0.0000	-0.0000	-0.0000
OAI211X1		0.0000	0.0000	0.0000
OAI211X1		-0.0000	-0.0000	-0.0000
OAI211X1		0.0000	0.0000	0.0000
OAI211X1		-0.0000	-0.0000	-0.0000
OAI211X1		0.0000	0.0000	0.0000
OAI211X1		-0.0000	-0.0000	-0.0000
OAI211X1		0.0000	0.0000	0.0000
OAI211X1		-0.0000	-0.0000	-0.0000
OAI211X1		0.0000	0.0000	0.0000

Hidden power(pJ) for A falling :
Conditional

Power (pJ)				
Cell	first	mid	last	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	

Hidden power(pJ) for B rising :
Conditional

Power (pJ)				
Cell	first	mid	last	
OAI211X1	-0.0000	-0.0000	0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for B falling :
Conditional

Power (pJ)				
Cell	first	mid	last	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	

Hidden power(pJ) for C rising:
Conditional

Power (pJ)				
Cell	first	mid	last	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for C falling:
Conditional

Power (pJ)				
Cell	first	mid	last	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	

Hidden power(pJ) for D rising:
Conditional

Power (pJ)				
Cell	first	mid	last	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	

Hidden power(pJ) for D falling:
Conditional

Power (pJ)				
Cell	first	mid	last	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	
OAI211X1	0.0000	0.0000	0.0000	
OAI211X1	-0.0000	-0.0000	-0.0000	

END Cell Group OAI211X1

Cell Group OAI222X1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	(!A * !B) + (!C * !D) + (!E * !F)

Truth Table

Input							Output
A	B	C	D	E	F	Y	
0	0	x	x	x	x	1	
x	1	0	0	x	x	1	
x	1	x	1	0	0	1	
x	1	x	1	x	1	0	
x	1	x	1	1	x	0	
x	1	1	x	0	0	1	
x	1	1	x	x	1	0	
x	1	1	x	1	x	0	
1	x	0	0	x	x	1	
1	x	x	1	0	0	1	
1	x	x	1	x	1	0	
1	x	x	1	1	x	0	
1	x	1	x	0	0	1	
1	x	1	x	x	1	0	
1	x	1	x	1	x	0	

Footprint :

Cell	Area
OAI222X1	0.0000

Leakage

Leakage (nW)			
Cell	Min	Avg	Max
OAI222X1	0.0000	0.1825	0.4345

Pin Capacitance

Pin Cap(pf)								Max Cap(pf)
Cell	A	B	C	D	E	F	Y	
OAI222X1	0.0005	0.0005	0.0005	0.0005	0.0005	0.0005	0.0050	

Delay

Delays(ns) to Y rising :

Delay (ns)						
Cell	Timing Arc(Dir)	first	mid	last		
OAI222X1	A->Y(FR)	6.9757	12.4087	23.8048		
OAI222X1	B->Y(FR)	6.8661	11.8214	22.4230		
OAI222X1	C->Y(FR)	6.3519	11.6994	22.9715		
OAI222X1	D->Y(FR)	6.1897	11.0672	21.5634		
OAI222X1	E->Y(FR)	5.3191	10.5870	21.7816		
OAI222X1	F->Y(FR)	5.1894	9.9936	20.4215		

Delays(ns) to Y falling :

		Delay (ns)		
Cell	Timing Arc(Dir)	first	mid	last
OAI222X1	A->Y(RF)	8.9804	15.0563	28.0175
OAI222X1	B->Y(RF)	8.5959	14.6552	27.5964
OAI222X1	C->Y(RF)	8.5230	14.3216	26.7896
OAI222X1	D->Y(RF)	8.1333	13.9106	26.3514
OAI222X1	E->Y(RF)	6.9305	12.4495	24.1914
OAI222X1	F->Y(RF)	6.5983	12.0977	23.8122

Power

Internal switching power(pJ) to Y rising :

		Power (pJ)		
Cell	Input	first	mid	last
OAI222X1	A	0.0001	0.0001	0.0001
OAI222X1	A	0.0000	0.0000	0.0000
OAI222X1	B	0.0001	0.0001	0.0001
OAI222X1	B	0.0000	0.0000	0.0000
OAI222X1	C	0.0001	0.0001	0.0001
OAI222X1	C	0.0000	0.0000	0.0000
OAI222X1	D	0.0001	0.0001	0.0001
OAI222X1	D	0.0000	0.0000	0.0000
OAI222X1	E	0.0001	0.0001	0.0001
OAI222X1	E	0.0000	0.0000	0.0000
OAI222X1	F	0.0001	0.0001	0.0001
OAI222X1	F	0.0000	0.0000	0.0000

Internal switching power(pJ) to Y falling :

		Power (pJ)		
Cell	Input	first	mid	last
OAI222X1	A	0.0000	0.0000	0.0000
OAI222X1	A	0.0001	0.0001	0.0001
OAI222X1	B	0.0000	0.0000	0.0000
OAI222X1	B	0.0001	0.0001	0.0001
OAI222X1	C	0.0000	0.0000	0.0000
OAI222X1	C	0.0001	0.0001	0.0001
OAI222X1	D	0.0000	0.0000	0.0000
OAI222X1	D	0.0001	0.0001	0.0001
OAI222X1	E	0.0000	0.0000	0.0000
OAI222X1	E	0.0001	0.0001	0.0001
OAI222X1	F	0.0000	0.0000	0.0000
OAI222X1	F	0.0001	0.0001	0.0001

Passive Power

Hidden power(pJ) for A rising :

Conditional

		Power (pJ)		
Cell		first	mid	last
OAI222X1		-0.0000	-0.0000	-0.0000
OAI222X1		0.0000	0.0000	0.0000
OAI222X1		-0.0000	-0.0000	-0.0000
OAI222X1		0.0000	0.0000	0.0000
OAI222X1		-0.0000	-0.0000	-0.0000
OAI222X1		0.0000	0.0000	0.0000
OAI222X1		-0.0000	-0.0000	-0.0000

OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000

Hidden power(pJ) for A falling :
Conditional

Power (pJ)			
Cell	first	mid	last
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000

Hidden power(pJ) for B rising :
Conditional

Power (pJ)			
Cell	first	mid	last
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000

OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000

Hidden power(pJ) for E falling:
Conditional

Cell	Power (pJ)		
	first	mid	last
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000

Hidden power(pJ) for F rising:
Conditional

Cell	Power (pJ)		
	first	mid	last
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000

OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000

Hidden power(pJ) for F falling:
Conditional

Power (pJ)			
Cell	first	mid	last
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000
OAI222X1	0.0000	0.0000	0.0000
OAI222X1	-0.0000	-0.0000	-0.0000

END Cell Group OAI222X1

Cell Group MUX2X1 from Library 28nm_slvt, Process corner, Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Y	(A * !SEL) + (B * SEL)

Truth Table

Input			Output
A	B	SEL	Y
0	0	x	0
0	1	0	0
x	1	1	1
1	x	0	1
1	0	1	0

Footprint:

Cell	Area
MUX2X1	0.0000

Leakage

Leakage (nW)			
Cell	Min	Avg	Max
MUX2X1	0.0000	0.7921	0.8997

Pin Capacitance

Cell	Pin Cap(pf)			Max Cap(pf)
	A	B	SEL	
MUX2X1	0.0006	0.0005	0.0012	0.0050

Delay

Delays(ns) to Y rising:
Conditional

Cell	Timing Arc(Dir)	Delay (ns)			when
		first	mid	last	
MUX2X1	A->Y(RR)	11.8933	14.4693	20.5722	—
MUX2X1	B->Y(RR)	12.2867	15.1731	21.7196	—
MUX2X1	SEL->Y(RR)	12.1899	14.7241	20.8322	(!A * B)
MUX2X1	SEL->Y(FR)	14.6077	17.4738	24.1094	(A * !B)

Delays(ns) to Y falling:
Conditional

Cell	Timing Arc(Dir)	Delay (ns)			when
		first	mid	last	
MUX2X1	A->Y(FF)	13.4804	16.5005	22.7898	—
MUX2X1	B->Y(FF)	13.2450	16.2400	22.5410	—
MUX2X1	SEL->Y(FF)	13.0747	16.0842	22.3567	(!A * B)
MUX2X1	SEL->Y(RF)	15.6524	18.7613	25.1587	(A * !B)

Power

Internal switching power(pJ) to Y rising:
Conditional

Cell	Input	Power (pJ)			when
		first	mid	last	
MUX2X1	A	0.0001	0.0001	0.0001	—
MUX2X1	A	0.0001	0.0001	0.0001	—
MUX2X1	B	0.0001	0.0001	0.0001	—
MUX2X1	B	0.0002	0.0002	0.0002	—
MUX2X1	SEL	0.0002	0.0002	0.0002	(A * !B)
MUX2X1	SEL	0.0001	0.0001	0.0001	(A * !B)
MUX2X1	SEL	0.0001	0.0001	0.0001	(!A * B)
MUX2X1	SEL	0.0002	0.0002	0.0002	(!A * B)

Internal switching power(pJ) to Y falling:
Conditional

		Power(pJ)				
Cell	Input	first	mid	last	when	
MUX2X1	A	0.0001	0.0001	0.0001	—	
MUX2X1	A	0.0001	0.0001	0.0001	—	
MUX2X1	B	0.0002	0.0002	0.0002	—	
MUX2X1	B	0.0001	0.0001	0.0001	—	
MUX2X1	SEL	0.0002	0.0001	0.0001	(A * !B)	
MUX2X1	SEL	0.0002	0.0002	0.0002	(A * !B)	
MUX2X1	SEL	0.0002	0.0002	0.0002	(!A * B)	
MUX2X1	SEL	0.0001	0.0001	0.0001	(!A * B)	

Passive Power

Hidden power(pJ) for A rising:
Conditional

		Power(pJ)		
Cell		first	mid	last
MUX2X1		-0.0000	-0.0000	-0.0000
MUX2X1		0.0000	0.0000	0.0000

Hidden power(pJ) for A falling:
Conditional

		Power(pJ)		
Cell		first	mid	last
MUX2X1		0.0000	0.0000	0.0000
MUX2X1		0.0000	0.0000	0.0000

Hidden power(pJ) for B rising:
Conditional

		Power(pJ)		
Cell		first	mid	last
MUX2X1		-0.0000	-0.0000	-0.0000
MUX2X1		0.0000	0.0000	0.0000

Hidden power(pJ) for B falling:
Conditional

		Power(pJ)		
Cell		first	mid	last
MUX2X1		0.0000	0.0000	0.0000
MUX2X1		-0.0000	-0.0000	-0.0000

Hidden power(pJ) for SEL rising :
Conditional

Power(pJ)				
Cell	first	mid	last	
MUX2X1	0.0002	0.0002	0.0001	
MUX2X1	0.0002	0.0002	0.0001	
MUX2X1	0.0000	0.0000	0.0000	
MUX2X1	0.0001	0.0001	0.0001	

Hidden power(pJ) for SEL falling :
Conditional

Power(pJ)				
Cell	first	mid	last	
MUX2X1	0.0002	0.0002	0.0001	
MUX2X1	0.0002	0.0002	0.0001	
MUX2X1	0.0001	0.0001	0.0001	
MUX2X1	0.0000	0.0000	0.0000	

END Cell Group MUX2X1

Cell Group DFFX1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Q	IQ

Truth Table

Input			Output
D	CLK	Q	
0	R	0	
1	R	1	
x	x	IQ	

Footprint :

Cell	Area
DFFX1	0.0000

Leakage

Leakage (nW)				
Cell	Min	Avg	Max	
DFFX1	0.0000	0.4710	0.6419	

Pin Capacitance

		Pin Cap(pf)	Max Cap(pf)	
Cell	D	CLK	Q	
DFFX1	0.0010	0.0011	0.0050	

Delay

Delays(ns) to Q rising :

		Delay (ns)		
Cell	Timing Arc(Dir)	first	mid	last
DFFX1	CLK->Q(RR)	4.4799	7.4187	14.1670

Delays(ns) to Q falling :

		Delay (ns)		
Cell	Timing Arc(Dir)	first	mid	last
DFFX1	CLK->Q(RF)	33.3664	47.0010	69.2139

Constraint

Constraints (ns) for D rising :

			Reference Slew Rate (ns)		
Cell	Check	Ref Pin(Trans)	first	mid	last
DFFX1	hold	CLK(rising)	-1.7569	-1.8008	-1.8703
DFFX1	setup	CLK(rising)	4.9289	4.9509	4.9857

Constraints (ns) for D falling :

			Reference Slew Rate (ns)		
Cell	Check	Ref Pin(Trans)	first	mid	last
DFFX1	hold	CLK(rising)	-967.0310	0.0000	-974.1250
DFFX1	setup	CLK(rising)	40.3651	40.3432	40.3214

Constraints (ns) for CLK rising :

Conditional

			Reference Slew Rate (ns)			
Cell	Check	Ref Pin(Trans)	first	mid	last	when
DFFX1	min_pulse_width	CLK	2.8954	2.9305	2.9868	D
DFFX1	min_pulse_width	CLK	39.2651	39.2920	39.3237	!D

Constraints (ns) for CLK falling :

Conditional

			Reference Slew Rate (ns)			
Cell	Check	Ref Pin(Trans)	first	mid	last	when
DFFX1	min_pulse_width	CLK	4.7090	4.7201	4.7352	D
DFFX1	min_pulse_width	CLK	38.4595	38.4570	38.4668	!D

Power

Internal switching power(pJ) to Q rising:

		Power (pJ)			
Cell	Input	first	mid	last	
DFFX1	CLK	0.0001	0.0001	0.0001	
DFFX1	CLK	0.0001	0.0001	0.0001	

Internal switching power(pJ) to Q falling:

		Power (pJ)			
Cell	Input	first	mid	last	
DFFX1	CLK	0.0002	0.0002	0.0002	
DFFX1	CLK	0.0002	0.0002	0.0002	

Passive Power

Hidden power(pJ) for D rising:
Conditional

		Power (pJ)		
Cell		first	mid	last
DFFX1		-0.0000	-0.0000	0.0000
DFFX1		0.0000	0.0000	0.0000
DFFX1		0.0000	0.0000	-0.0000
DFFX1		0.0001	0.0001	0.0000

Hidden power(pJ) for D falling:
Conditional

		Power (pJ)		
Cell		first	mid	last
DFFX1		0.0000	0.0000	0.0000
DFFX1		0.0000	0.0000	0.0000
DFFX1		0.0000	0.0000	0.0000
DFFX1		0.0000	0.0000	-0.0000

Hidden power(pJ) for CLK rising:
Conditional

		Power (pJ)		
Cell		first	mid	last
DFFX1		-0.0000	-0.0000	-0.0000
DFFX1		0.0000	0.0000	0.0000
DFFX1		-0.0000	-0.0000	-0.0000
DFFX1		0.0000	0.0000	0.0000

Hidden power(pJ) for CLK falling :
Conditional

Power(pJ)				
Cell	first	mid	last	
DFFX1	0.0000	0.0000	0.0000	
DFFX1	-0.0000	-0.0000	-0.0000	
DFFX1	0.0001	0.0001	0.0000	
DFFX1	0.0001	0.0001	0.0000	
DFFX1	0.0000	0.0000	0.0000	
DFFX1	-0.0000	-0.0000	-0.0000	
DFFX1	0.0000	0.0000	0.0000	
DFFX1	-0.0000	-0.0000	-0.0000	

END Cell Group DFFX1

Cell Group DFFX4 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Q	IQ

Truth Table

Input			Output
D	CLK	Q	Q
0	R	0	0
1	R	1	1
x	x	IQ	

Footprint:

Cell	Area
DFFX4	0.0000

Leakage

Leakage (nW)				
Cell	Min	Avg	Max	
DFFX4	0.0000	1.8839	2.5677	

Pin Capacitance

Pin Cap(pf)				
Cell	D	CLK	Q	
DFFX4	0.0037	0.0042	0.0050	

Delay

Delays(ns) to Q rising :

			Delay (ns)		
Cell	Timing Arc(Dir)		first	mid	last
DFFX4	CLK->Q(RR)		4.0330	5.8973	10.5754

Delays(ns) to Q falling :

			Delay (ns)		
Cell	Timing Arc(Dir)		first	mid	last
DFFX4	CLK->Q(RF)		28.8831	33.9046	44.0681

Constraint

Constraints(ns) for D rising :

			Reference Slew Rate(ns)		
Cell	Check	Ref Pin(Trans)	first	mid	last
DFFX4	hold	CLK(rising)	-1.6706	-1.7133	-1.7837
DFFX4	setup	CLK(rising)	4.6175	4.6328	4.6669

Constraints(ns) for D falling :

			Reference Slew Rate(ns)		
Cell	Check	Ref Pin(Trans)	first	mid	last
DFFX4	hold	CLK(rising)	-952.8810	0.0000	-951.5050
DFFX4	setup	CLK(rising)	37.1850	37.1688	37.1273

Constraints(ns) for CLK rising :

Conditional

			Reference Slew Rate(ns)			
Cell	Check	Ref Pin(Trans)	first	mid	last	when
DFFX4	min_pulse_width	CLK	2.5316	2.5740	2.6399	D
DFFX4	min_pulse_width	CLK	35.0781	35.1025	35.1270	! D

Constraints(ns) for CLK falling :

Conditional

			Reference Slew Rate(ns)			
Cell	Check	Ref Pin(Trans)	first	mid	last	when
DFFX4	min_pulse_width	CLK	4.6605	4.6698	4.6906	D
DFFX4	min_pulse_width	CLK	36.9165	36.9141	36.9067	! D

Power

Internal switching power(pJ) to Q rising:

		Power (pJ)		
Cell	Input	first	mid	last
DFFX4	CLK	0.0002	0.0002	0.0002
DFFX4	CLK	0.0004	0.0004	0.0004

Internal switching power(pJ) to Q falling:

		Power (pJ)		
Cell	Input	first	mid	last
DFFX4	CLK	0.0005	0.0005	0.0005
DFFX4	CLK	0.0006	0.0006	0.0006

Passive Power

Hidden power(pJ) for D rising:
Conditional

		Power (pJ)		
Cell		first	mid	last
DFFX4		0.0000	0.0000	0.0000
DFFX4		0.0000	0.0000	0.0000
DFFX4		0.0002	0.0002	-0.0000
DFFX4		0.0003	0.0003	0.0001

Hidden power(pJ) for D falling:
Conditional

		Power (pJ)		
Cell		first	mid	last
DFFX4		0.0000	0.0000	0.0000
DFFX4		-0.0000	-0.0000	-0.0000
DFFX4		0.0001	0.0001	0.0001
DFFX4		0.0000	0.0000	0.0000

Hidden power(pJ) for CLK rising:
Conditional

		Power (pJ)		
Cell		first	mid	last
DFFX4		-0.0000	-0.0000	-0.0000
DFFX4		0.0001	0.0001	0.0001
DFFX4		-0.0001	-0.0001	-0.0001
DFFX4		0.0001	0.0001	0.0001

Hidden power(pJ) for CLK falling :
Conditional

		Power(pJ)		
Cell		first	mid	last
DFFX4		0.0001	0.0001	0.0001
DFFX4		-0.0001	-0.0001	-0.0001
DFFX4		0.0002	0.0002	0.0001
DFFX4		0.0003	0.0003	0.0001
DFFX4		0.0002	0.0001	0.0001
DFFX4		-0.0001	-0.0001	-0.0001
DFFX4		0.0001	0.0001	0.0001
DFFX4		-0.0000	-0.0001	-0.0001

END Cell Group DFFX4

Cell Group DLX1 from Library 28nm_slvt , Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
Q	IQ

Truth Table

Input		Output
D	CLK	Q
x	0	IQ
0	1	0
1	1	1

Footprint:

Cell	Area
DLX1	0.0000

Leakage

Leakage (nW)			
Cell	Min	Avg	Max
DLX1	0.0000	0.4371	0.5089

Pin Capacitance

		Pin Cap(pf)	Max Cap(pf)
Cell	D	CLK	Q
DLX1	0.0005	0.0011	0.0050

Delay

Delays(ns) to Q rising :

		Delay (ns)			
Cell	Timing Arc(Dir)	first	mid	last	
DLX1	CLK->Q(RR)	8.5420	11.9772	18.4396	
DLX1	D->Q(RR)	9.9965	13.8588	20.9541	

Delays(ns) to Q falling :

		Delay (ns)			
Cell	Timing Arc(Dir)	first	mid	last	
DLX1	CLK->Q(RF)	13.6957	17.9512	24.4688	
DLX1	D->Q(FF)	13.0496	17.1272	23.8146	

Constraint

Constraints(ns) for D rising :

			Reference Slew Rate(ns)		
Cell	Check	Ref Pin(Trans)	first	mid	last
DLX1	hold	CLK(falling)	-5.2734	-5.3036	-5.3540
DLX1	setup	CLK(falling)	8.0039	8.0333	8.0835

Constraints(ns) for D falling :

			Reference Slew Rate(ns)		
Cell	Check	Ref Pin(Trans)	first	mid	last
DLX1	hold	CLK(falling)	-6.6323	-6.6240	-6.6096
DLX1	setup	CLK(falling)	10.1813	10.1709	10.1557

Constraints(ns) for CLK rising :

Conditional

			Reference Slew Rate(ns)			
Cell	Check	Ref Pin(Trans)	first	mid	last	when
DLX1	min_pulse_width	CLK	6.7163	6.7212	6.7383	D
DLX1	min_pulse_width	CLK	11.3818	11.4062	11.4453	!D

Power

Internal switching power(pJ) to Q rising :

		Power(pJ)		
Cell	Input	first	mid	last
DLX1	CLK	0.0001	0.0001	0.0001
DLX1	CLK	0.0002	0.0002	0.0002
DLX1	D	0.0001	0.0001	0.0001
DLX1	D	0.0001	0.0001	0.0001

Internal switching power(pJ) to Q falling :

		Power (pJ)			
Cell	Input	first	mid	last	
DLX1	CLK	0.0001	0.0001	0.0001	
DLX1	CLK	0.0002	0.0002	0.0002	
DLX1	D	0.0001	0.0001	0.0001	
DLX1	D	0.0001	0.0001	0.0001	

Passive Power

Hidden power(pJ) for D rising :
Conditional

		Power (pJ)		
Cell		first	mid	last
DLX1		-0.0000	-0.0000	-0.0000
DLX1		0.0000	0.0000	0.0000

Hidden power(pJ) for D falling :
Conditional

		Power (pJ)		
Cell		first	mid	last
DLX1		0.0000	0.0000	0.0000
DLX1		-0.0000	-0.0000	-0.0000

Hidden power(pJ) for CLK rising :
Conditional

		Power (pJ)		
Cell		first	mid	last
DLX1		0.0000	0.0000	0.0000
DLX1		0.0001	0.0000	0.0000
DLX1		0.0000	0.0000	0.0000
DLX1		0.0001	0.0001	0.0000

Hidden power(pJ) for CLK falling :
Conditional

		Power (pJ)		
Cell		first	mid	last
DLX1		0.0001	0.0001	0.0000
DLX1		0.0000	0.0000	0.0000
DLX1		0.0000	0.0000	0.0000
DLX1		0.0000	0.0000	0.0000

END Cell Group DLX1

Cell Group FAX1 from Library 28nm_slvt, Process corner , Temp 25.00, Voltage 0.30

Function

Pin Name	Function
CO	$(A * B) + (A * CI) + (B * CI)$
S	$(A * B * CI) + (A * !B * !CI) + (!A * B * !CI) + (!A * !B * CI)$

Truth Table

Input			Output		
A	B	CI	CO	S	
0	0	0	0	0	
0	0	1	0	1	
0	1	0	0	1	
0	1	1	1	0	
1	0	0	0	1	
1	0	1	1	0	
1	1	0	1	0	
1	1	1	1	1	

Footprint:

Cell	Area
FAX1	0.0000

Leakage

Leakage (nW)			
Cell	Min	Avg	Max
FAX1	0.0000	1.5715	1.7278

Pin Capacitance

Pin Cap(pf)							Max Cap(pf)
Cell	A	B	CI	CO	S		
FAX1	0.0018	0.0011	0.0020	0.0050	0.0050		

Delay

Delays(ns) to CO rising :

Delay (ns)						
Cell	Timing	Arc (Dir)	first	mid	last	
FAX1		A->CO(RR)	35.1078	38.2797	45.0745	
FAX1		B->CO(RR)	35.2187	38.0385	44.3320	
FAX1		CI->CO(RR)	12.0138	14.6031	20.6935	

Delays(ns) to CO falling :

Delay (ns)						
Cell	Timing	Arc (Dir)	first	mid	last	
FAX1		A->CO(FF)	35.7609	38.7198	44.5742	
FAX1		B->CO(FF)	35.5799	38.0779	43.1636	
FAX1		CI->CO(FF)	13.6210	16.6186	22.9076	

Delays(ns) to S rising:
Conditional

Delay (ns)						
Cell	Timing	Arc(Dir)	first	mid	last	when
FAX1		A->S(-R)	30.9481	36.9152	49.0263	-
FAX1		B->S(-R)	31.0438	36.6638	48.2674	-
FAX1		CI->S(RR)	7.8224	13.3711	25.0598	(A * B) + (!A * !B)
FAX1		CI->S(FR)	5.2799	10.3981	21.2886	(A * !B) + (!A * B)

Delays(ns) to S falling:
Conditional

Delay (ns)						
Cell	Timing	Arc(Dir)	first	mid	last	when
FAX1		A->S(-F)	24.9473	31.2950	41.8773	-
FAX1		B->S(-F)	25.0421	31.0634	41.1761	-
FAX1		CI->S(FF)	7.4546	11.8730	21.5641	(A * B) + (!A * !B)
FAX1		CI->S(RF)	4.2457	8.6112	18.2935	(A * !B) + (!A * B)

Power

Internal switching power(pJ) to CO rising:

Power (pJ)					
Cell	Input	first	mid	last	
FAX1	A	0.0002	0.0002	0.0002	
FAX1	A	0.0003	0.0002	0.0002	
FAX1	B	0.0002	0.0002	0.0002	
FAX1	B	0.0002	0.0002	0.0002	
FAX1	CI	0.0001	0.0001	0.0001	
FAX1	CI	0.0001	0.0001	0.0001	

Internal switching power(pJ) to CO falling:

Power (pJ)					
Cell	Input	first	mid	last	
FAX1	A	0.0002	0.0002	0.0002	
FAX1	A	0.0002	0.0002	0.0002	
FAX1	B	0.0002	0.0002	0.0002	
FAX1	B	0.0002	0.0002	0.0002	
FAX1	CI	0.0001	0.0001	0.0001	
FAX1	CI	0.0001	0.0001	0.0001	

Internal switching power(pJ) to S rising:
Conditional

Power (pJ)					
Cell	Input	first	mid	last	when
FAX1	A	0.0005	0.0005	0.0005	-
FAX1	A	0.0005	0.0005	0.0005	-
FAX1	B	0.0005	0.0005	0.0005	-
FAX1	B	0.0005	0.0005	0.0005	-
FAX1	CI	0.0001	0.0001	0.0001	(A * B) + (!A * !B)
FAX1	CI	0.0002	0.0002	0.0002	(A * B) + (!A * !B)
FAX1	CI	0.0002	0.0002	0.0001	(A * !B) + (!A * B)
FAX1	CI	0.0001	0.0001	0.0001	(A * !B) + (!A * B)

Internal switching power(pJ) to S falling:
Conditional

		Power(pJ)			
Cell	Input	first	mid	last	when
FAX1	A	0.0006	0.0006	0.0008	—
FAX1	A	0.0005	0.0006	0.0007	—
FAX1	B	0.0005	0.0005	0.0005	—
FAX1	B	0.0005	0.0005	0.0005	—
FAX1	CI	0.0002	0.0002	0.0002	(A * B) + (!A * !B)
FAX1	CI	0.0001	0.0001	0.0001	(A * B) + (!A * !B)
FAX1	CI	0.0001	0.0001	0.0001	(A * !B) + (!A * B)
FAX1	CI	0.0001	0.0001	0.0001	(A * !B) + (!A * B)

END Cell Group FAX1

C. Library characterization for different operating conditions

In Section V-A, the characterization results under different operating conditions were presented for a selection of cells. For the library characterization results for all the cells, they are presented in the following Tables:

- 25 °C, TT-corner , Table XII
- -20 °C, SS-corner, Table XIII
- 85 °C, FF-corner , Table XIV

TABLE XII: Library characterization results for nominal conditions (25 °C, TT-corner)

Operating conditions	Cell	Maximum delay	Δ delay	Leakage power	Δ power
25 °C, TT-corner	INV1X1	10.89 ns	1.0	0.14 nW	1.0
	INV1X4	7.28 ns	1.0	0.57 nW	1.0
	BUFF1X1	22.99 ns	1.0	0.34 nW	1.0
	NAND2X1	16.64 ns	1.0	0.29 nW	1.0
	AND2X1	16.03 ns	1.0	0.35 nW	1.0
	NOR2X1	20.63 ns	1.0	0.15 nW	1.0
	OR2X1	16.82 ns	1.0	0.27 nW	1.0
	XNOR2X1	25.90 ns	1.0	0.46 nW	1.0
	XOR2X1	25.52 ns	1.0	0.54 nW	1.0
	AOI12X1	21.53 ns	1.0	0.29 nW	1.0
	AOI22X1	22.04 ns	1.0	0.30 nW	1.0
	AOI112X1	32.35 ns	1.0	0.29 nW	1.0
	AOI212X1	34.08 ns	1.0	0.22 nW	1.0
	AOI222X1	36.83 ns	1.0	0.29 nW	1.0
	OAI12X1	20.47 ns	1.0	0.29 nW	1.0
	OAI22X1	21.68 ns	1.0	0.30 nW	1.0
	OAI211X1	23.97 ns	1.0	0.45 nW	1.0
	OAI222X1	28.02 ns	1.0	0.43 nW	1.0
	MUX2X1	22.79 ns	1.0	0.90 nW	1.0
	DFFX1	69.21 ns	1.0	0.64 nW	1.0
DFFX4	44.07 ns	1.0	2.57 nW	1.0	
DLX1	24.47 ns	1.0	0.51 nW	1.0	
FAX1	49.03 ns	1.0	1.73 nW	1.0	

TABLE XIII: Library characterization results for -20 °C, in the SS-corner

Operating conditions	Cell	Maximum delay	Δ delay	Leakage power	Δ power
-20 °C, SS-corner	INV1X1	48.8 ns	4.48	0.01 nW	0.06
	INV1X4	20.83 ns	2.86	0.03 nW	0.06
	BUFF1X1	151.56 ns	6.59	0.02 nW	0.06
	NAND2X1	89.90 ns	5.4	0.02 nW	0.06
	AND2X1	89.70 ns	5.6	0.02 nW	0.06
	NOR2X1	138.57 ns	6.72	0.01 nW	0.06
	OR2X1	101.45 ns	6.03	0.01 nW	0.05
	XNOR2X1	175.43 ns	6.77	0.03 nW	0.06
	XOR2X1	172.99 ns	6.78	0.03 nW	0.06
	AOI12X1	145.14 ns	6.74	0.02 nW	0.06
	AOI22X1	149.42 ns	6.78	0.02 nW	0.06
	AOI112X1	241.41 ns	7.46	0.02 nW	0.06
	AOI212X1	256.52 ns	7.53	0.01 nW	0.06
	AOI222X1	280.24 ns	7.61	0.02 nW	0.06
	OAI12X1	137.98 ns	6.74	0.02 nW	0.06
	OAI22X1	147.44 ns	6.8	0.02 nW	0.06
	OAI211X1	146.75 ns	6.12	0.03 nW	0.06
	OAI222X1	176.20 ns	6.29	0.02 nW	0.06
	MUX2X1	146.06 ns	6.41	0.05 nW	0.06
	DFFX1	748.08 ns	10.81	0.04 nW	0.06
DFFX4	458.77 ns	10.41	0.14 nW	0.06	
DLX1	162.34 ns	6.63	0.03 nW	0.06	
FAX1	375.03 ns	7.65	0.10 nW	0.05	

TABLE XIV: Library characterization results for 85 °C, in the FF-corner

Operating conditions	Cell	Maximum delay	Δ delay	Leakage power	Δ power
85 °C, FF-corner	INV1X1	4.05 ns	0.37	2.89 nW	20.27
	INV1X4	2.17 ns	0.3	11.56 nW	20.27
	BUFF1X1	4.10 ns	0.18	7.97 nW	23.43
	NAND2X1	4.50 ns	0.27	5.45 nW	18.67
	AND2X1	3.73 ns	0.23	8.44 nW	23.89
	NOR2X1	5.76 ns	0.28	5.92 nW	40.74
	OR2X1	4.60 ns	0.27	8.73 nW	32.49
	XNOR2X1	5.84 ns	0.23	11.14 nW	24.17
	XOR2X1	6.00 ns	0.24	10.95 nW	20.17
	AOI12X1	5.92 ns	0.27	6.03 nW	20.58
	AOI22X1	5.93 ns	0.27	6.14 nW	20.76
	AOI112X1	7.08 ns	0.22	9.07 nW	31.22
	AOI212X1	7.20 ns	0.21	8.88 nW	39.73
	AOI222X1	7.54 ns	0.2	8.72 nW	30.21
	OAI12X1	5.57 ns	0.27	5.94 nW	20.31
	OAI22X1	5.93 ns	0.27	6.08 nW	20.31
	OAI211X1	5.57 ns	0.23	8.24 nW	18.48
	OAI222X1	6.23 ns	0.22	8.00 nW	18.42
	MUX2X1	4.39 ns	0.19	22.97 nW	25.53
	DFFX1	6.58 ns	0.1	15.85 nW	24.69
	DFFX4	4.58 ns	0.1	63.39 nW	24.69
	DLX1	5.79 ns	0.24	13.99 nW	27.49
	FAX1	8.22 ns	0.17	44.83 nW	25.94

